



In the clouds:

Towards 1Tb/s per carrier

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University of Toronto

University of Southern California, October 12, 2012



Sorin Voinigescu, October 12, 2012



Credits

Graduate students

- ♦ Yannis Sarkas
- ♦ Andreea Balteanu
- ♦ Alex Tomkins
- ♦ Eric Dacquay
- ♦ Katya Laskin

Collaborators

- ♦ Juergen Hasch
- ♦ Pascal Chevalier
- ♦ Peter Asbeck
- ♦ Gabriel Rebeiz
- ♦ Jim Buckwalter
- ♦ Larry Larson

- NSERC, OCE
- Robert Bosch GmbH, DARPA, Ciena, Gennum for funding
- STMicroelectronics, Darpa, Ciena for chip donations



Outline

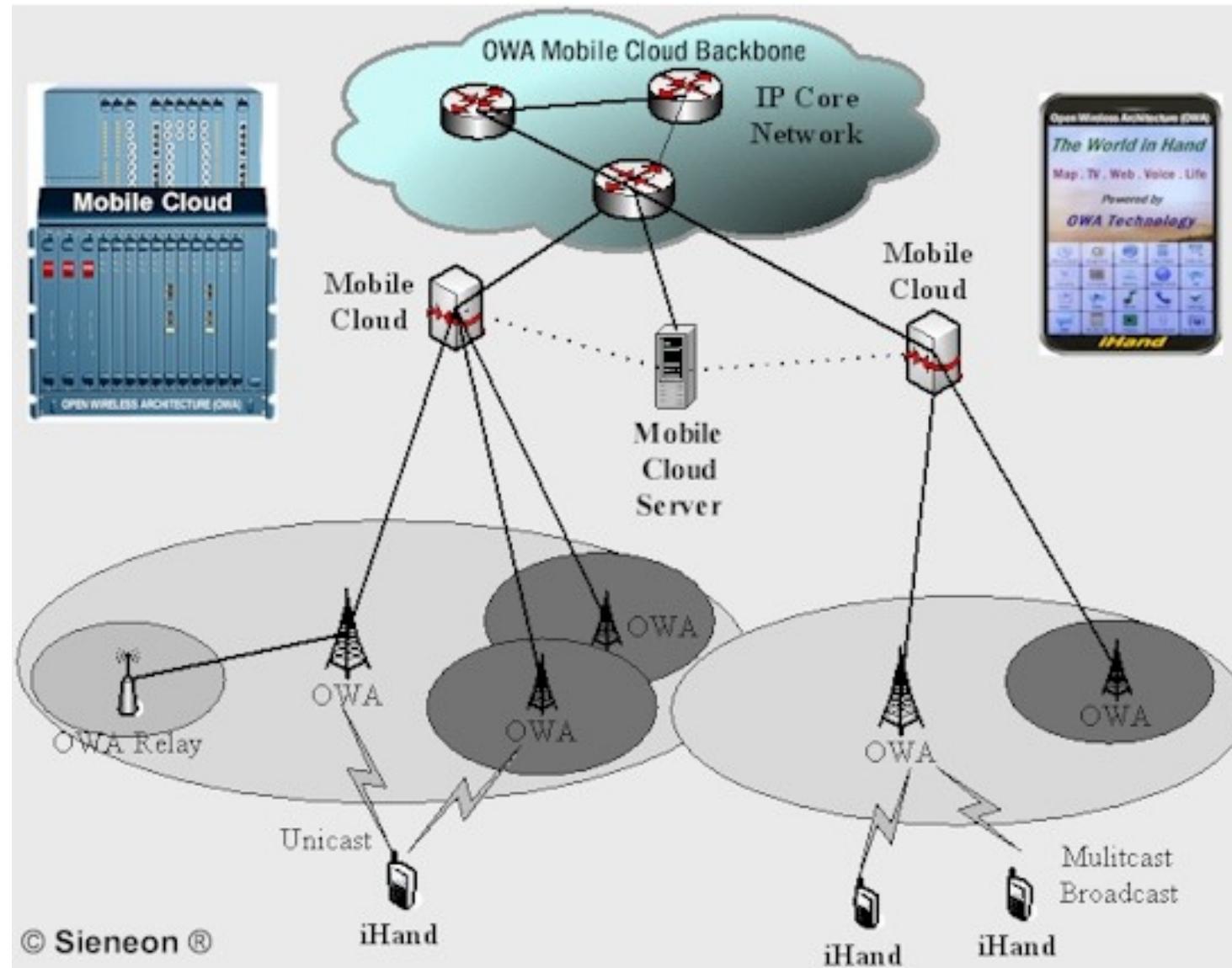
- Why?
- How?
 - ♦ System
 - ♦ Antenna
 - ♦ Baseband
 - ♦ Radio transceiver
- When



We are addicted ...



What's in a cloud?



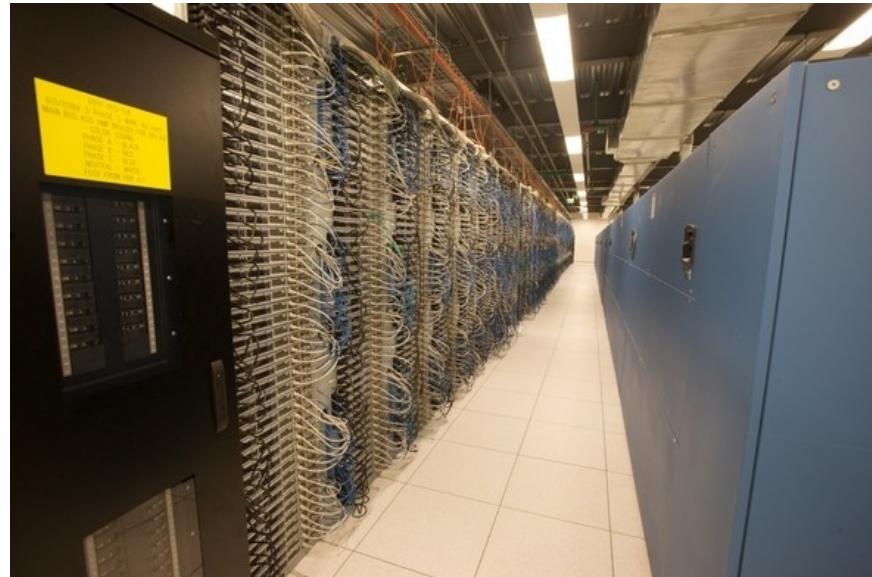
wireless links

- optical fiber links
- data centers

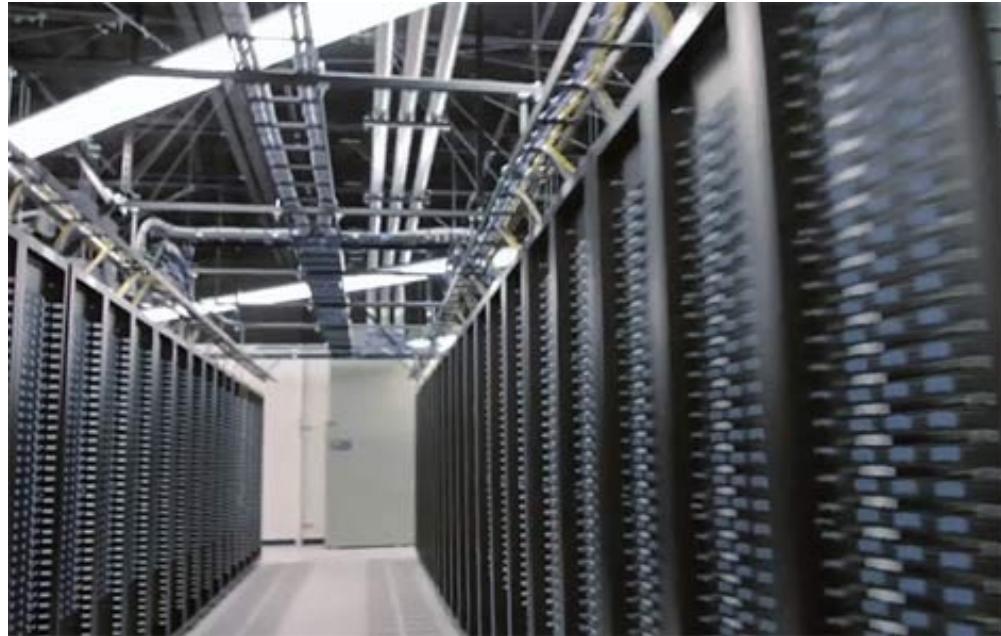
What's in a data center?



- Optical fiber links
- Coaxial cable links
- Routers
- Boards
- Backplanes



Facebook pictures...



- 40 Million pictures uploaded per day to Facebook
 - > 10^{15} bits/day => 15 Gb/s
- Worldwide: 2049 data centers
 - consume 30 Billion Watts = 30 nuclear power stations

Evolution of CMOS since 2000

- 130 nm, $f_T = 80$ GHz: $V_{DD} = 1.2$ V
- 2002 => 90 nm, $f_T = 120$ GHz: $V_{DD} = 1.2$ V
 - ◆ Strained channel, SiGe S/D
- 2004 => 65 nm, $f_T = 180$ GHz: $V_{DD} = 1.1-1.2$ V
 - ◆ More strain
- 2006 => 45 nm, $f_T = 240$ GHz: $V_{DD} = 1.0-1.2$ V
 - ◆ High-K MG, more strain
- 2008 => 32 nm, $f_T = 360?$ GHz: $V_{DD} = 0.9-1.2$ V
 - ◆ High-K MG, more strain
- 2011 => 22 nm, $f_T = 500??$ GHz: $V_{DD} = 0.9$ V
 - ◆ Tri-gate, High-K MG, more strain



Some observations

$$E \propto f \cdot C \cdot V_{DD}^2$$

- Moore's law is alive!
 - ◆ More transistors per area => C decreases



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 - Clock frequency should improve=> **Hint, hint** digital designers



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- Moore's law without Dennard's?
 - ◆ **A nuclear power station for the DIGITAL die!**

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Millimeter & sub-millimeter wave circuits are OK!

Why can't we reduce V_{DD} ?

- Because the subthreshold slope, S , does not scale
- S determined by the Fermi-Dirac distribution function

$$S[V/\text{decade}] = \frac{kT}{q} \cdot \ln(10)$$

Valid in

- ♦ 3-D (Fin)FETs, bipolar transistors
- ♦ 2-D crystal FETs (graphene, MoS₂)
- ♦ 1-D FETs (nanowire, carbon nanotube)

So what are we to do?

$$S[V/\text{decade}] = \frac{kT}{q} \cdot \ln(10)$$

k and q are constants, T is a variable

Solutions

- ♦ Refrigeration: 77 K (liquid nitrogen), 4 K (space station?)
 - ♦ Not in your hand!
 - ♦ Possible in the data center
- ♦ New physics:
 - ♦ Tunnel FETs? Maybe, but S is V_{gs} -dependent.



More immediate solutions in...

- Wireless, wireline, fiberoptic system architectures that
 - ♦ Increase data rate >1 Tb/s carrier (imperative in fiber links)
 - ♦ Increase efficiency per bit
- Faster, more efficient circuit topologies
 - ♦ CMOS logic at 50-100 Gb/s to save power?
 - ♦ Stacked CMOS logic for large swing drivers?
- Can we push the carrier frequency to 300 GHz?



Energy Efficiency of Communication Links

	4G WiMAX	60 GHz LOS Radio	Wireline IEE 802.3.an	Fiber SerDes VCSEL	Fiber DP-QPSK/BPSK
Data Rate	≤ 1 Gbps	5.3 Gbps	10 Gbps	10 Gbps	50 Gbps
Power	1.76 W	350 mW	2 W	2.5 W	25 W
Distance		2 m	100 m	20 km	3500 km
Energy/bit	1.6 nJ/b	66 pJ/b	200pJ/b	250 pJ/b	500pJ/b
Energy/bit/m	↑	33 pJ/b/m	2 pJ/b/m	12.5 fJ/b/m	0.14 fJ/b/m
Reference	[Krishnamurthy, •RFIC 2010]	[Laskin, •RFIC 2011]	[Gupta, ISSCC 2012]	[Voinigescu, CICC 2001]	[Crivelli, ISSCC 2012]



Energy Efficiency of Communication Links

Optical: 10 fJ/b/m

5000 km



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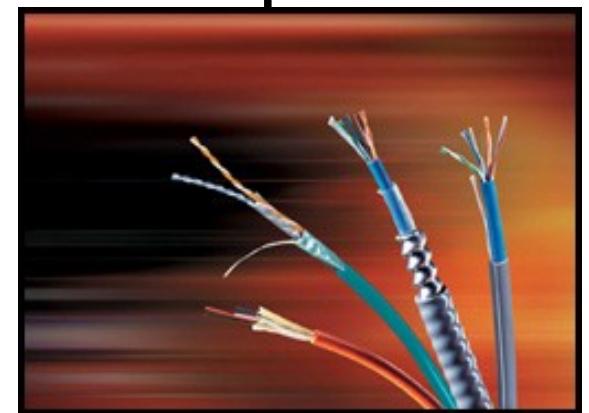
5000 km



Source: Belden Inc.

Wireline: 2 pJ/b/m

100 m



Source: Belden Inc.

Energy Efficiency of Communication Links

Wireless > 30 pJ/b/m



10m

Source: Samsung

Optical: 10 fJ/b/m



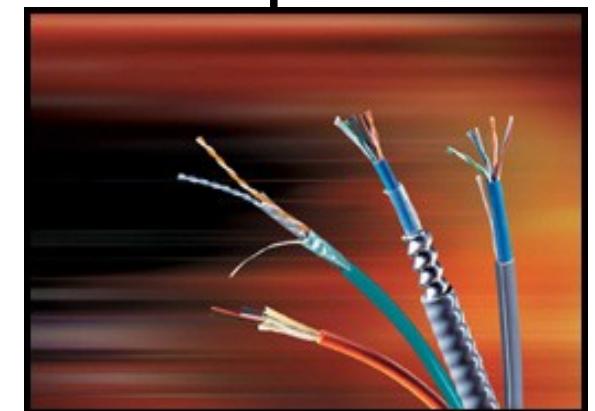
5000 km

Source: Belden Inc.

Wireless is the most inefficient, yet most popular!

Wireline: 2 pJ/b/m

100 m

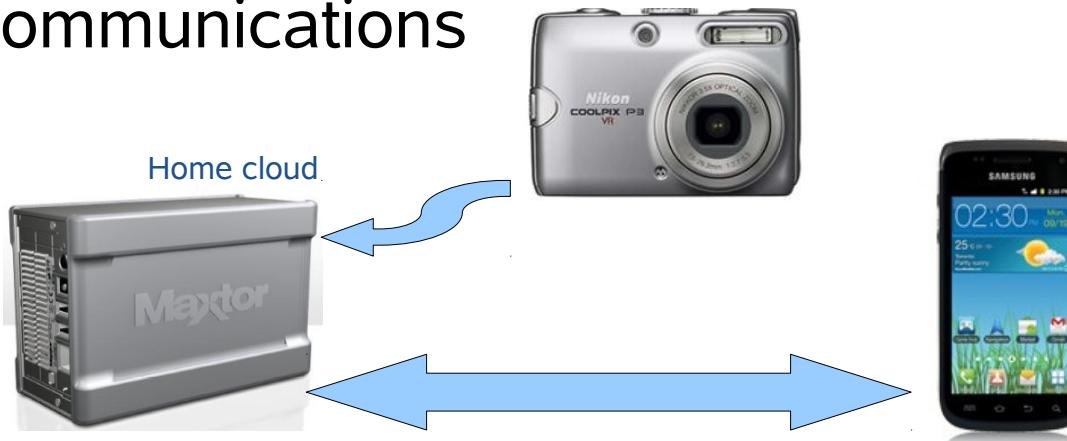


Source: Belden Inc.

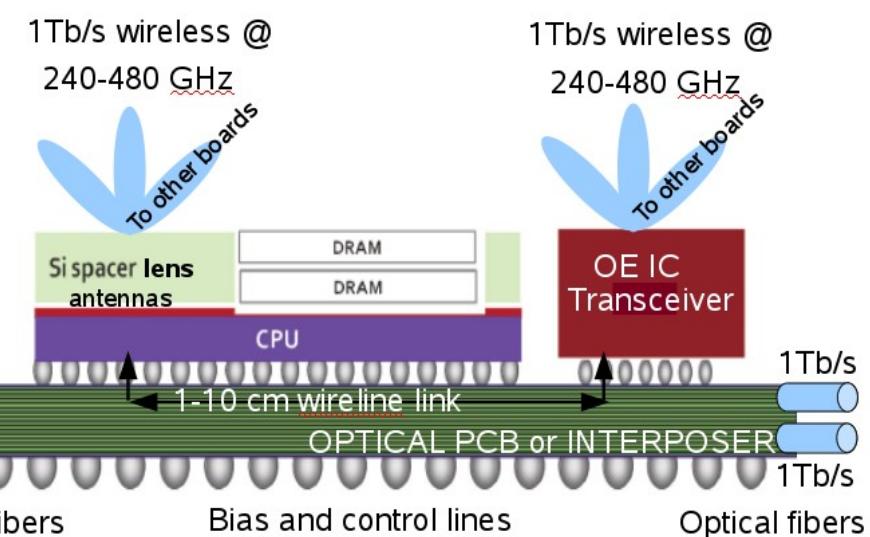


Why Tb/s wireless?

- Near field communications



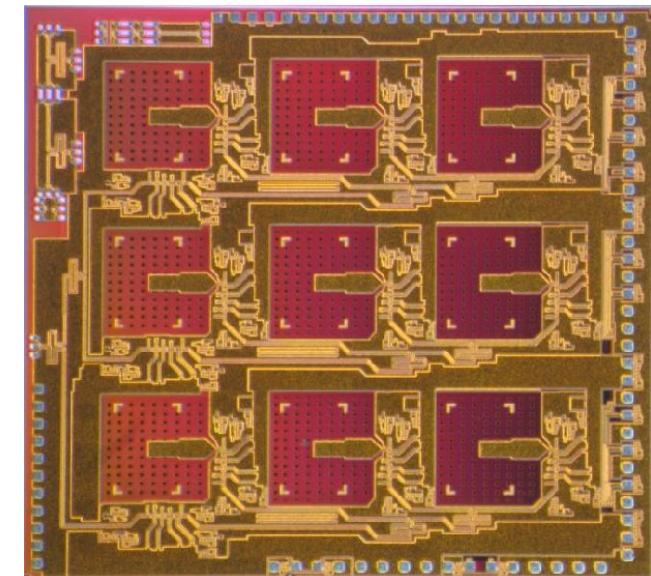
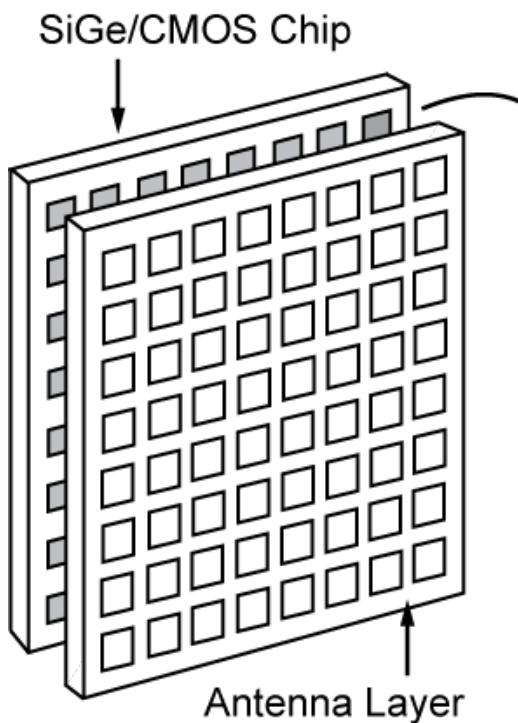
- Short-range reconfigurable wireless data transmission in the data center



- Board-to-board

Why 200-300 GHz?

- Silicon transistors with $f_{MAX} > 400$ GHz
- 100 GHz of bandwidth with no absorption
- Small antenna size with good gain
- Lower power LNA, mixer, receiver
- But...
 - ◆ higher power PLL,
 - ◆ reduced P_{out} ,
 - ◆ shorter range $\sim 1/f^2$



Source: G. Rebeiz UCSD

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Scalable Digital Radio Transmitters

- Can we improve efficiency by increasing the modulation rate per carrier at fixed P_{OUT} ?



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- Example: 0.3 Tb/s with 1 W PA => 3.3 pJ/b

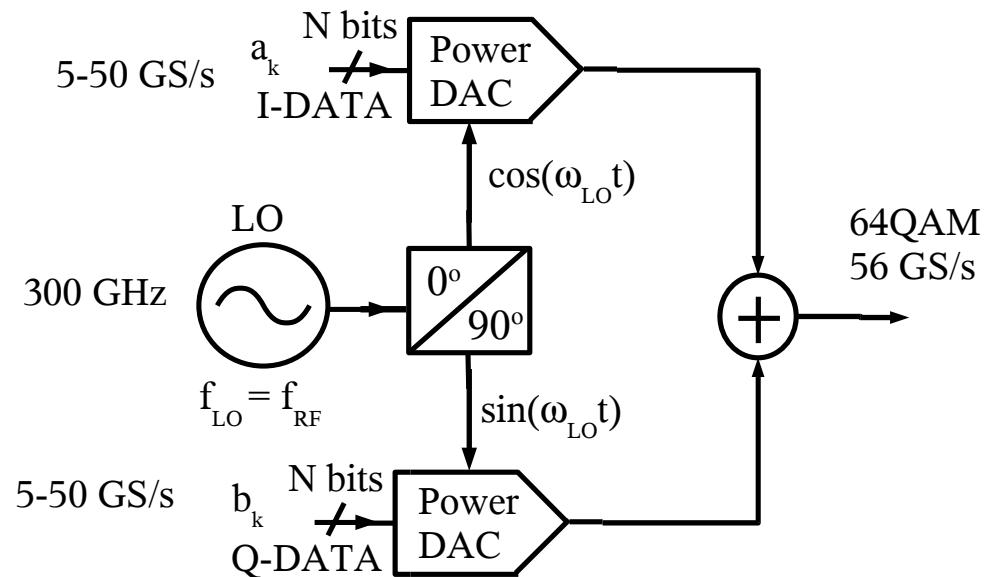
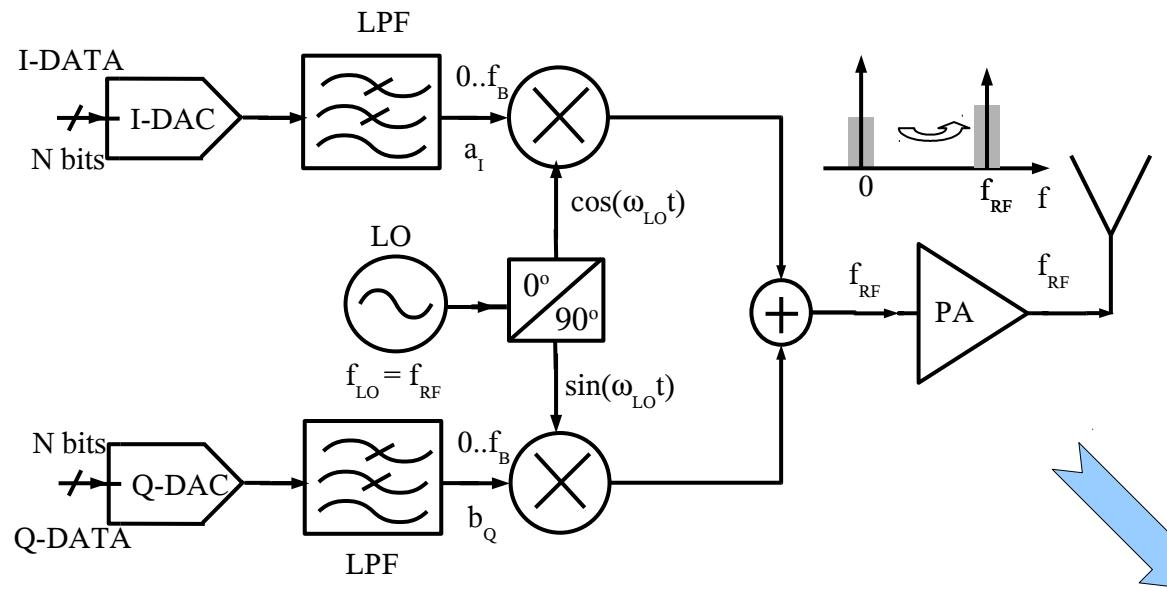


Scalable Digital Radio Transmitters

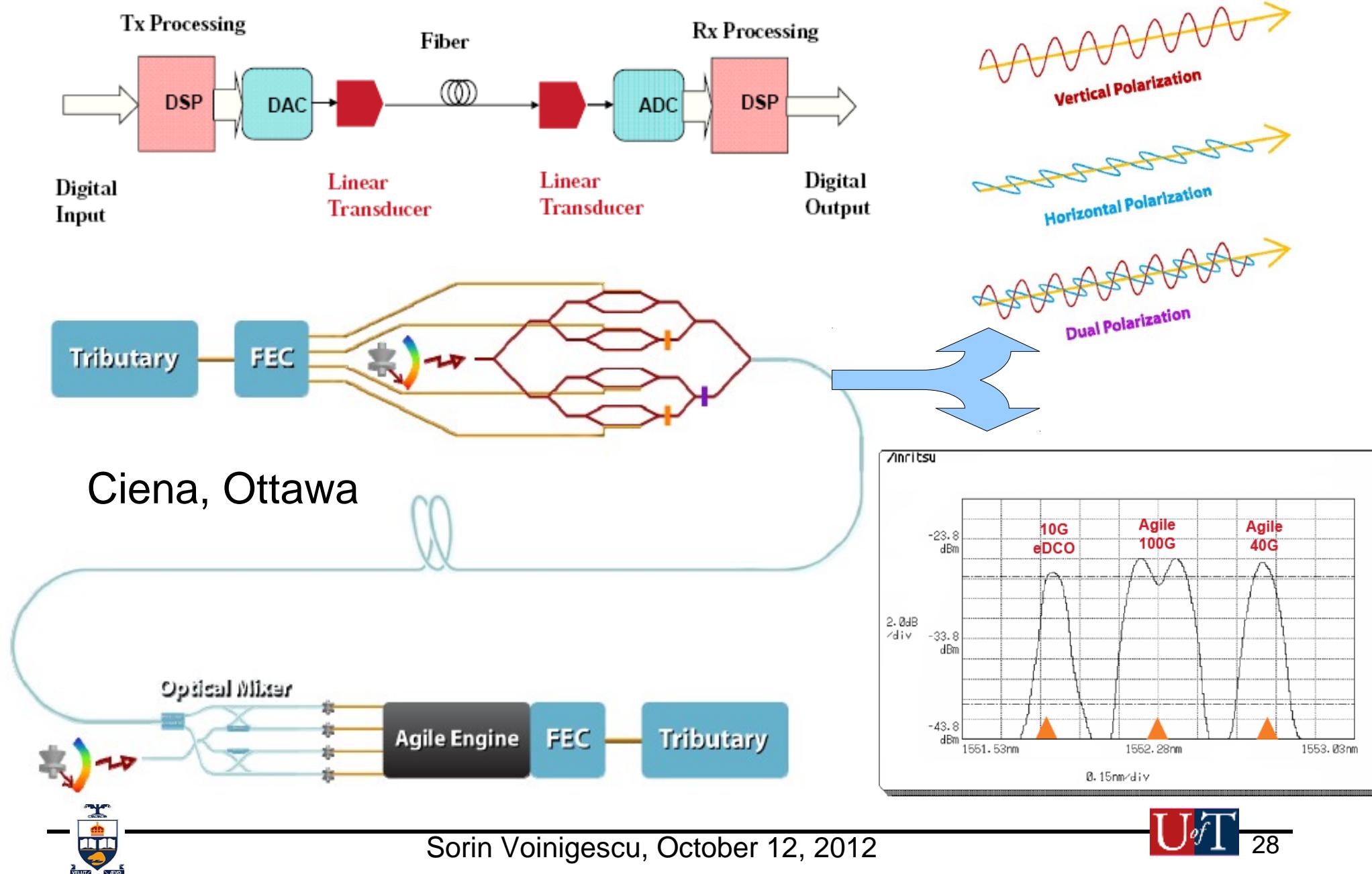
- Can we improve efficiency by increasing the modulation rate per carrier at fixed P_{OUT} ?
- Example: 0.3 Tb/s with 1 W PA => 3.3 pJ/b
 - But 0.3 Tb/s with 64 QAM modulation requires 50-Gb/s serial baseband lanes,
 - difficult to realize efficiently with up-conversion transmitter architecture



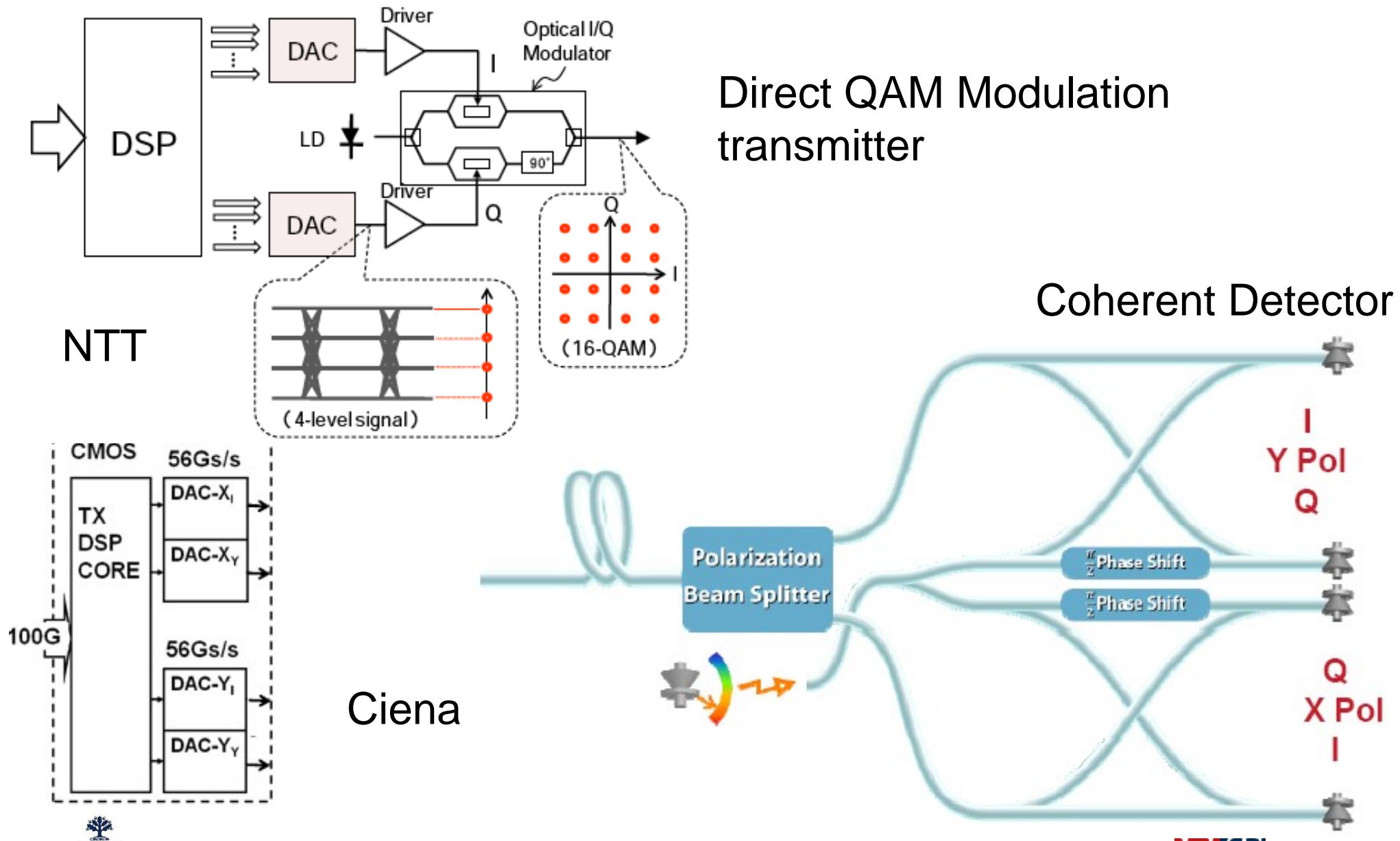
Potential Solution: Direct Modulation TX Radio



Like Coherent Fiberoptics links: 110 Gb/s TX-RX



200+ Gb/s Dual-Polarization TX/RX (ii)



How can we get to 1 Tb/s per carrier?

- Fiber: Dual-polarization, 16 QAM at 125 Gbaud
 - 8 baseband lanes at 125 Gb/s
 - Power consumption is not that critical here....
 - Need phase equalization in receiver
 - Need large swing (>5V) 6-bit 125 GS/sec DACs
- Wireless: 256 QAM at 125 Gbaud
 - Power consumption is critical
 - Need amplitude and phase equalization in receiver

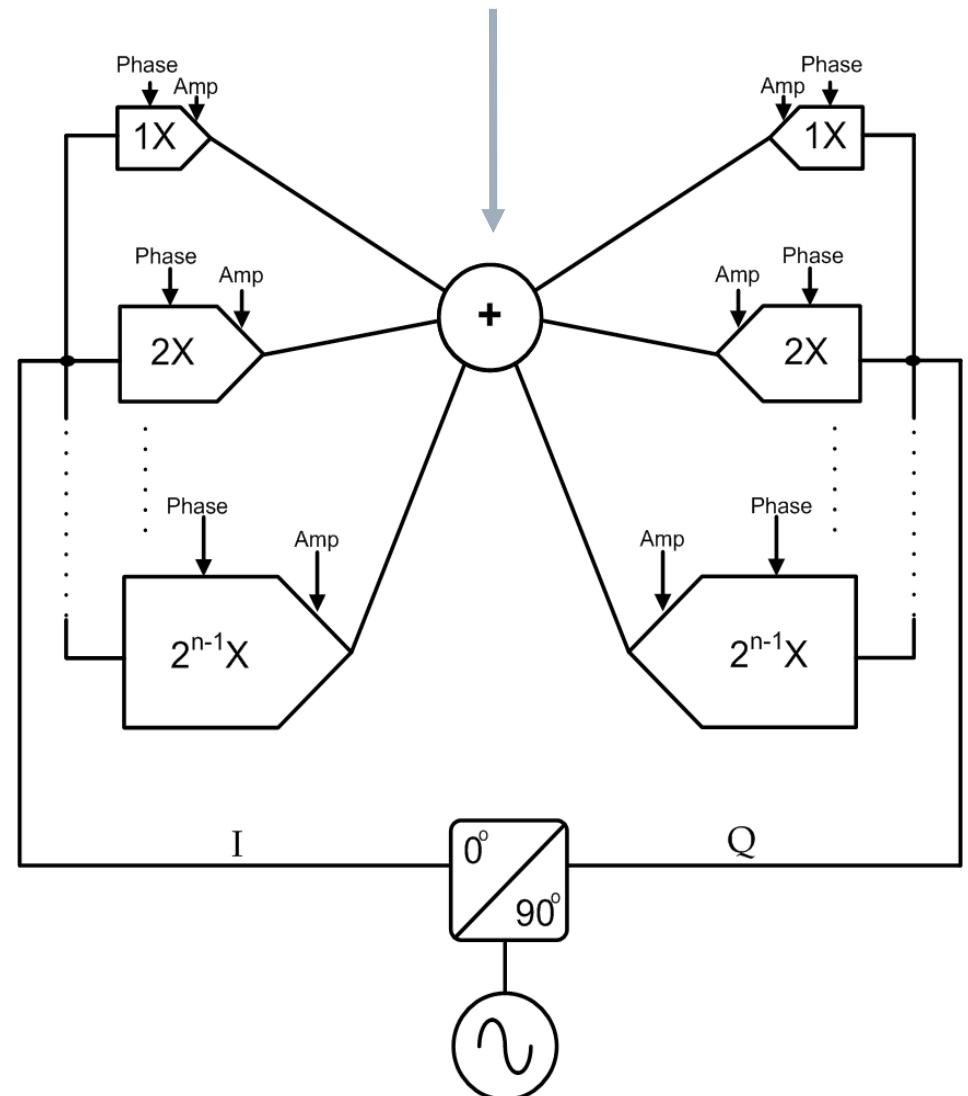


Direct Modulation TX Radio

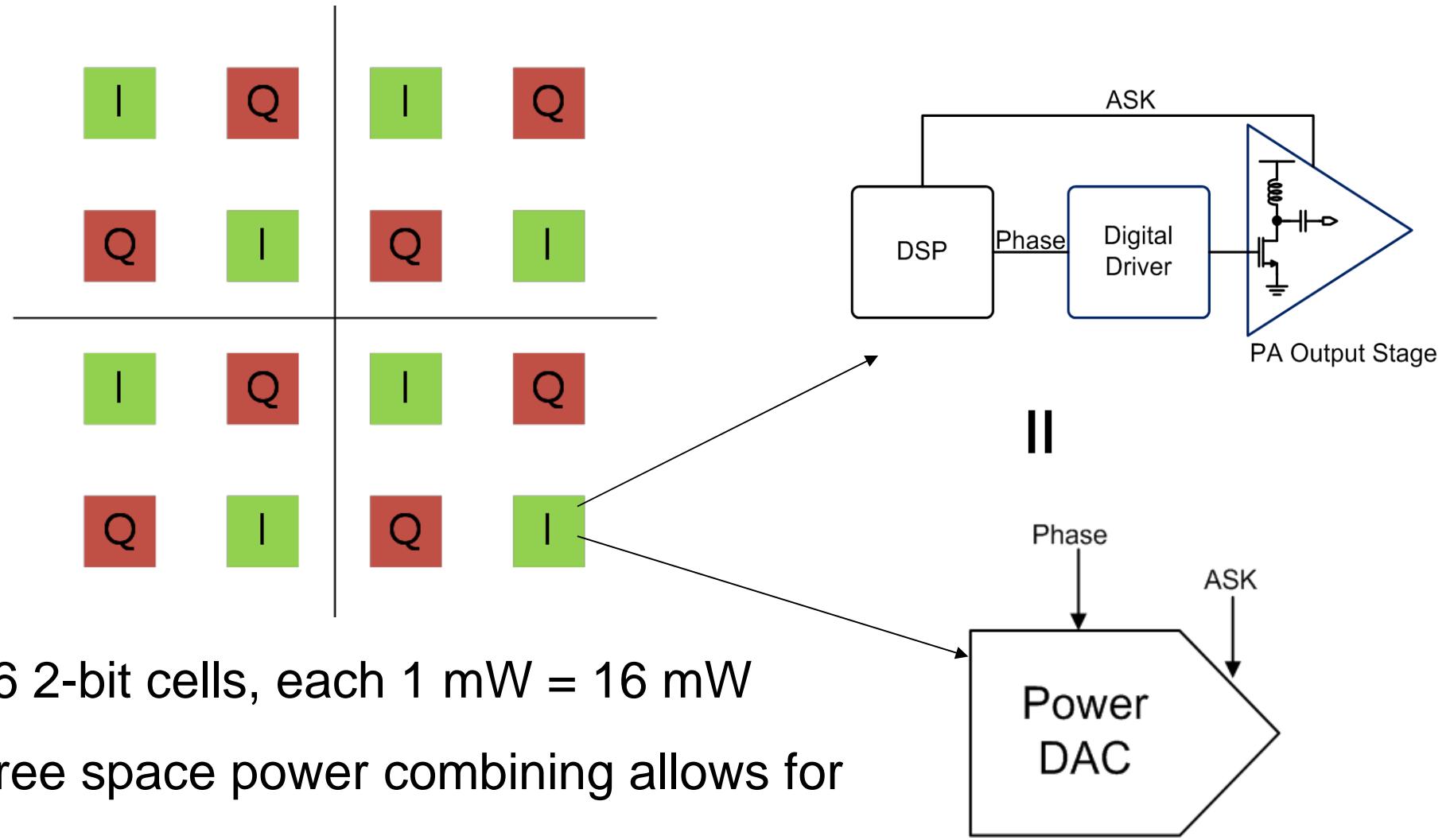
- 2-bit polar-modulated, binary weighted PA cells driven in quadrature
- No back-off needed for linearity
- Phase/Amp bits @ 1-100 Gbps

[A. Balteanu et al. IMS 2012]

- On chip free-space power combiner

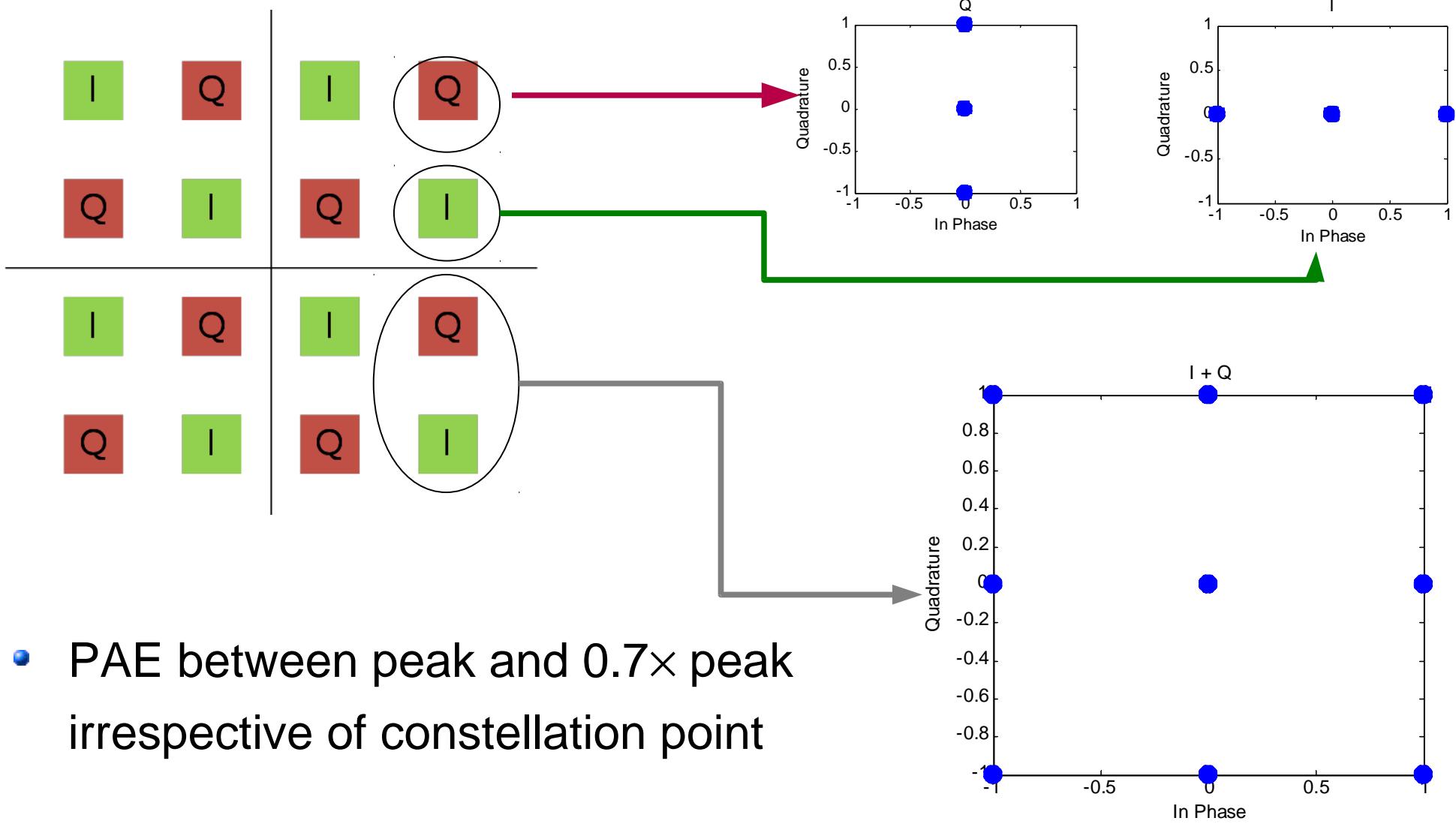


IQ DAC TX with Antenna Level Segmentation



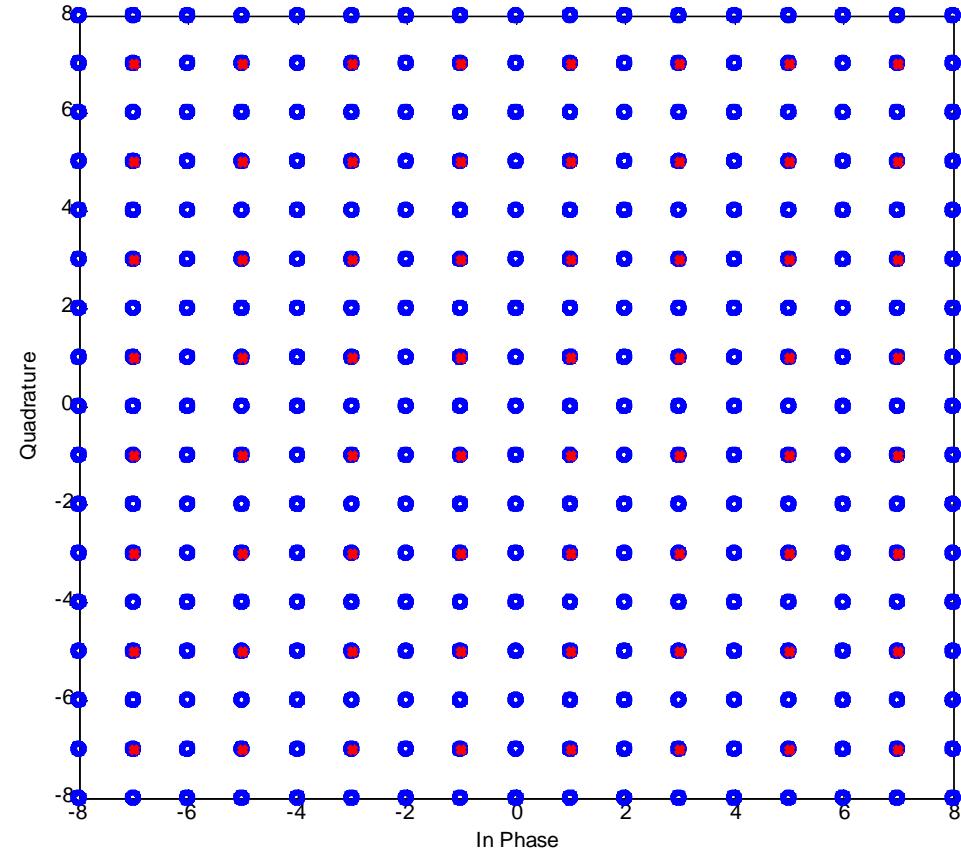
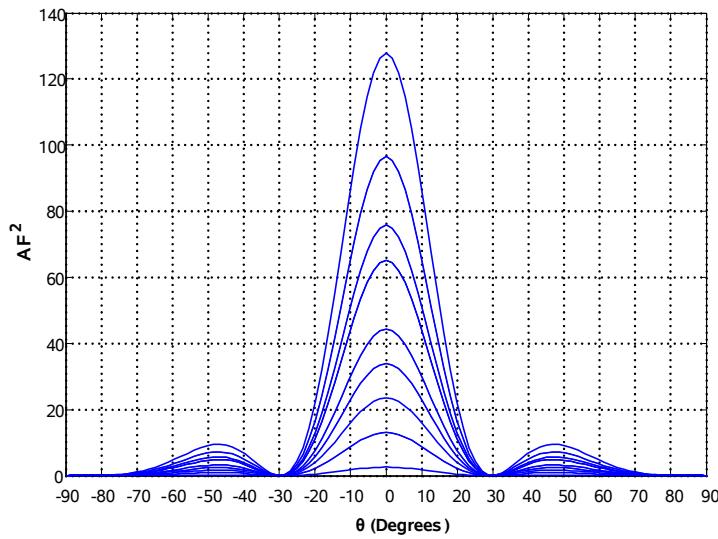
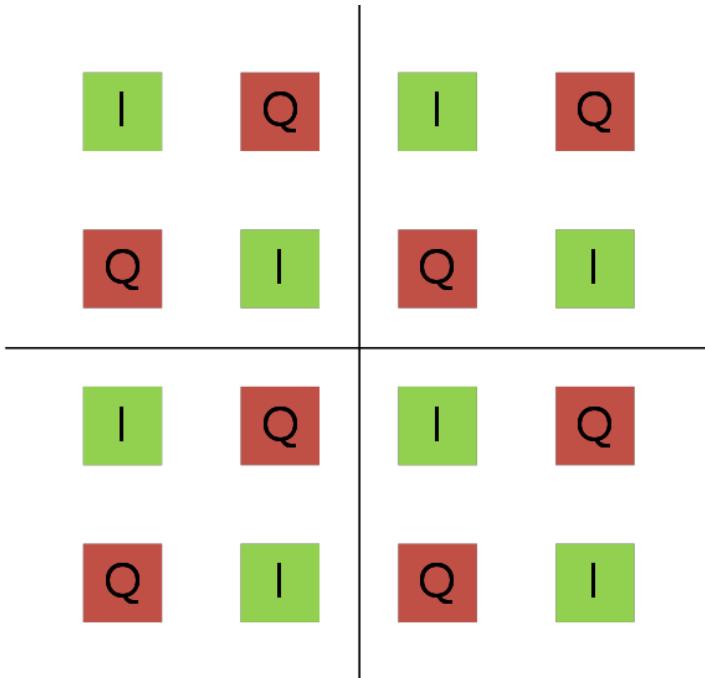
- 16 2-bit cells, each 1 mW = 16 mW
- Free space power combining allows for antenna segmentation
- Reconfigurable modulation format

IQ DAC TX Constellation



- PAE between peak and $0.7 \times$ peak
irrespective of constellation point

Full 8I + 8Q Constellation



64 QAM Constellation Points

8I + 8Q \rightarrow 289 Constellation Points $> 2^8$
2 extra bits

Wish list for sub-millimetre wave radio

- 100 Gb/s standard CMOS baseband lanes
 - Efficiency scalable with data rate
- $P_{TX} = 10 \text{ dBm}$
- PLL with PN < -90 dBc/Hz in band at 300 GHz
- NF < 12 dB
- $P_{DC} < 1\text{W}$
- BW = 25-30%
- Antenna gain > 20 dB (lens)
- Distance: 10's cm

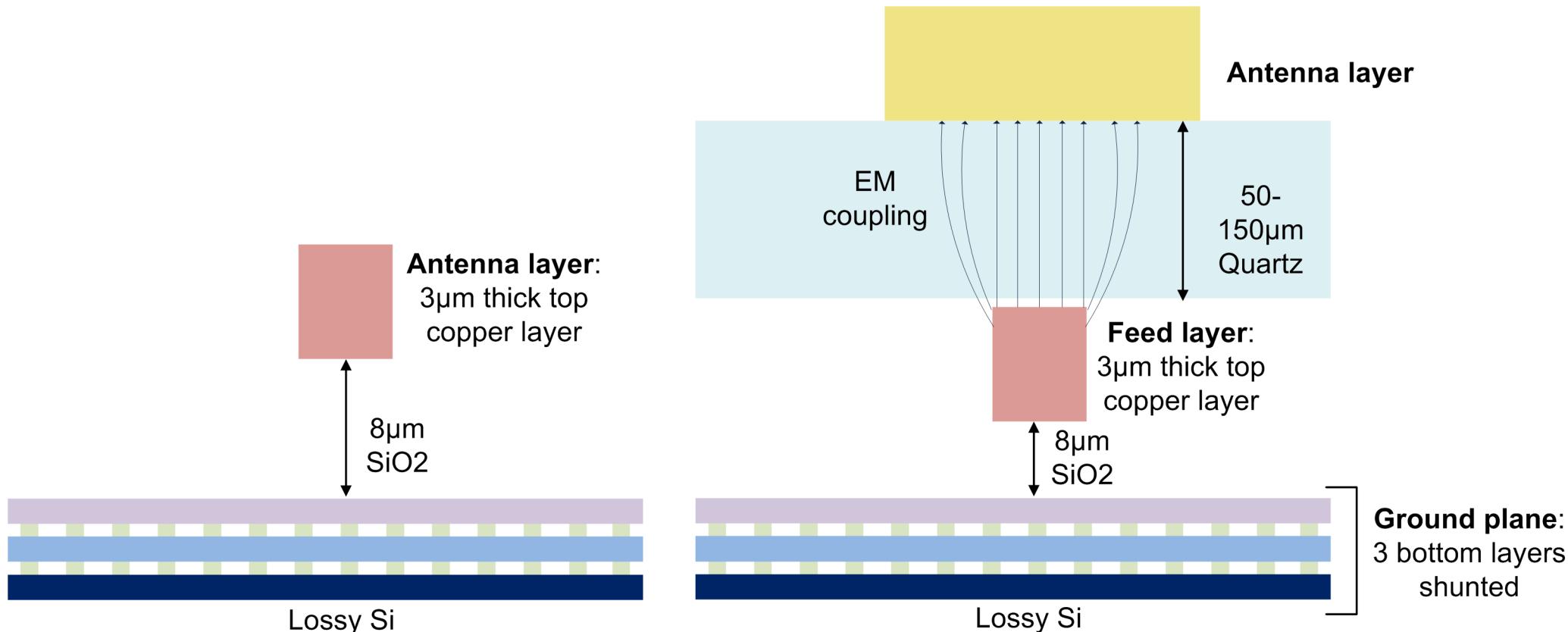


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Antenna Integration

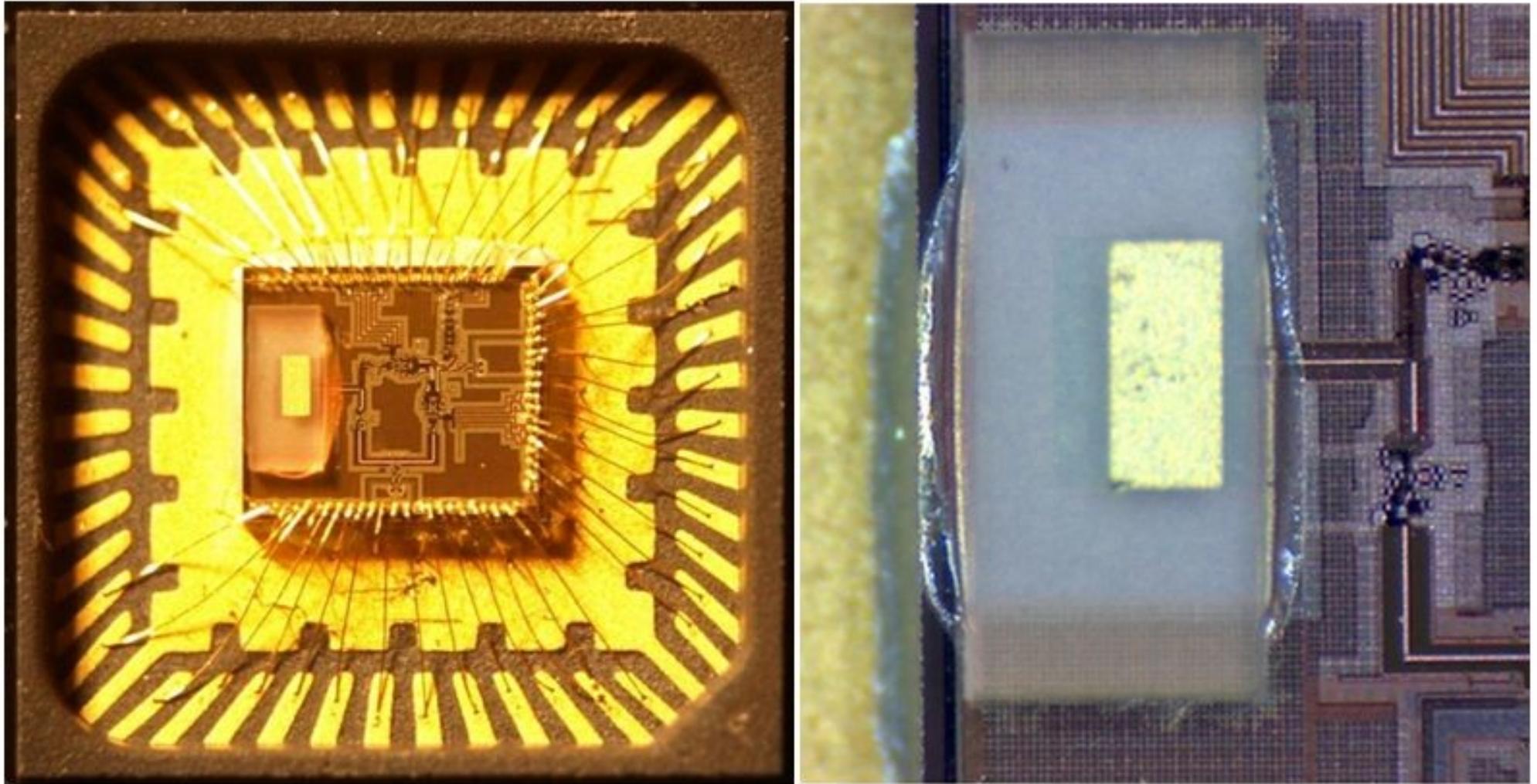


On-chip

Above IC

[J. Hasch et al, March 2010]

120/160 GHz Transceiver Packaging



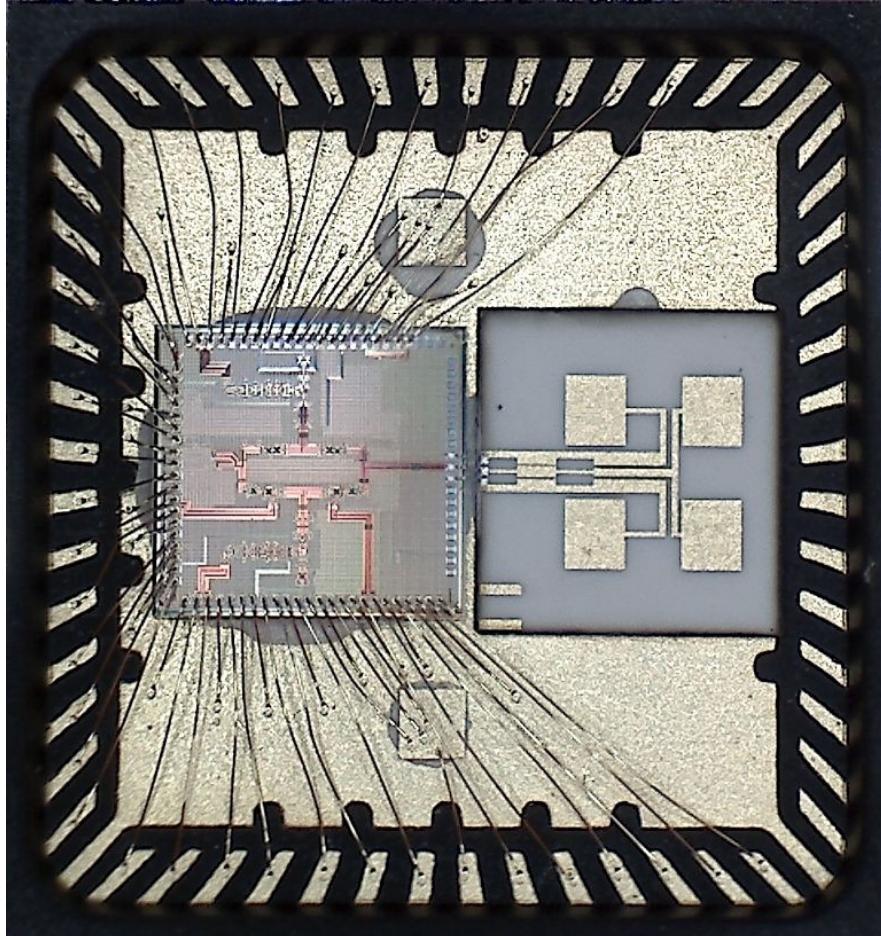
Chip: 2.2mm×2.6mm

Package: 7mm×7mm

[I. Sarkas Trans MTT, March 2012]



142-152 GHz Antenna and die in QFN package



EU SUCCESS Project

- Antenna design by Stefan Beer, Karlsruhe Institute of Technology
- Packaging by Robert Bosch GmbH
- Fundamental frequency transceiver with self-test

[I. Sarkas CSICS 2012]

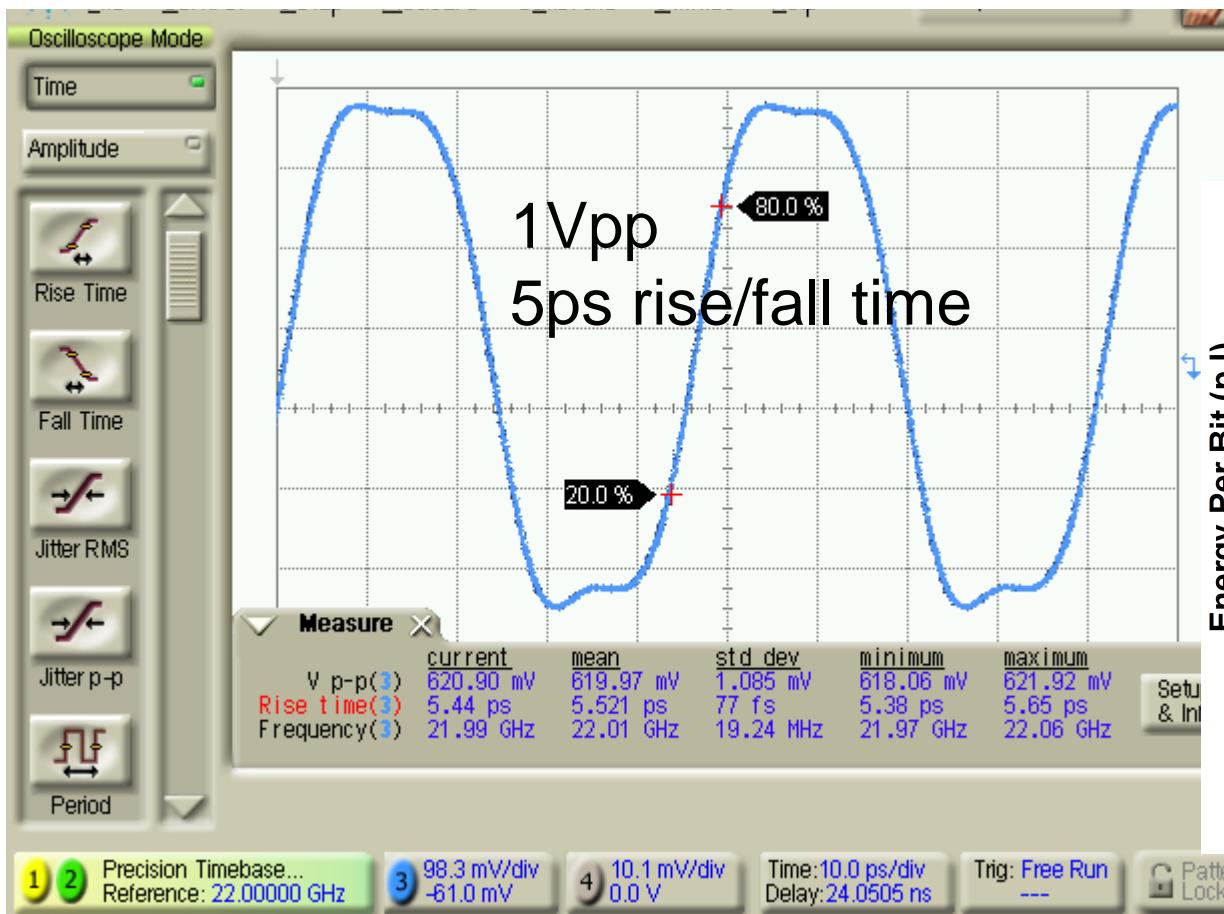
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Outline

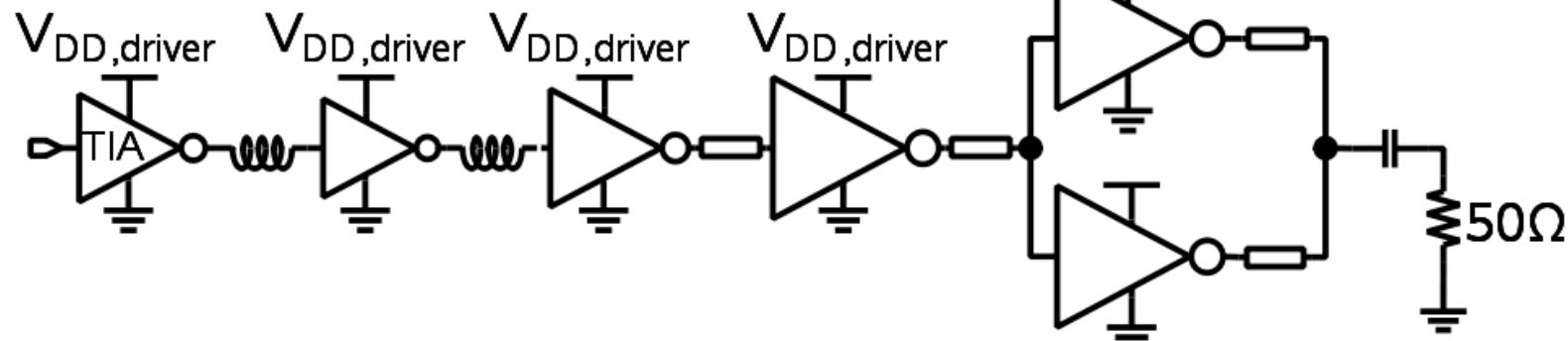
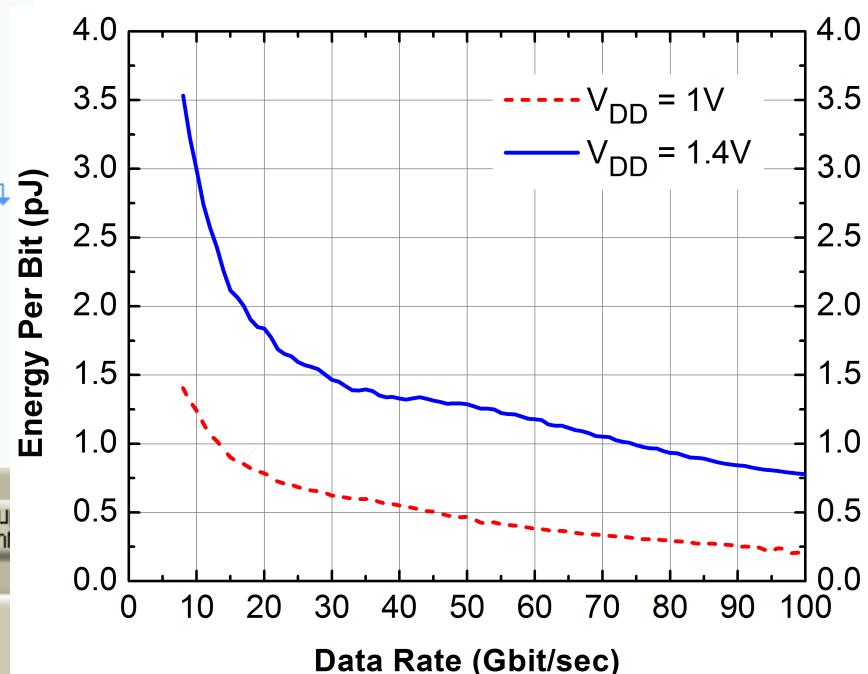
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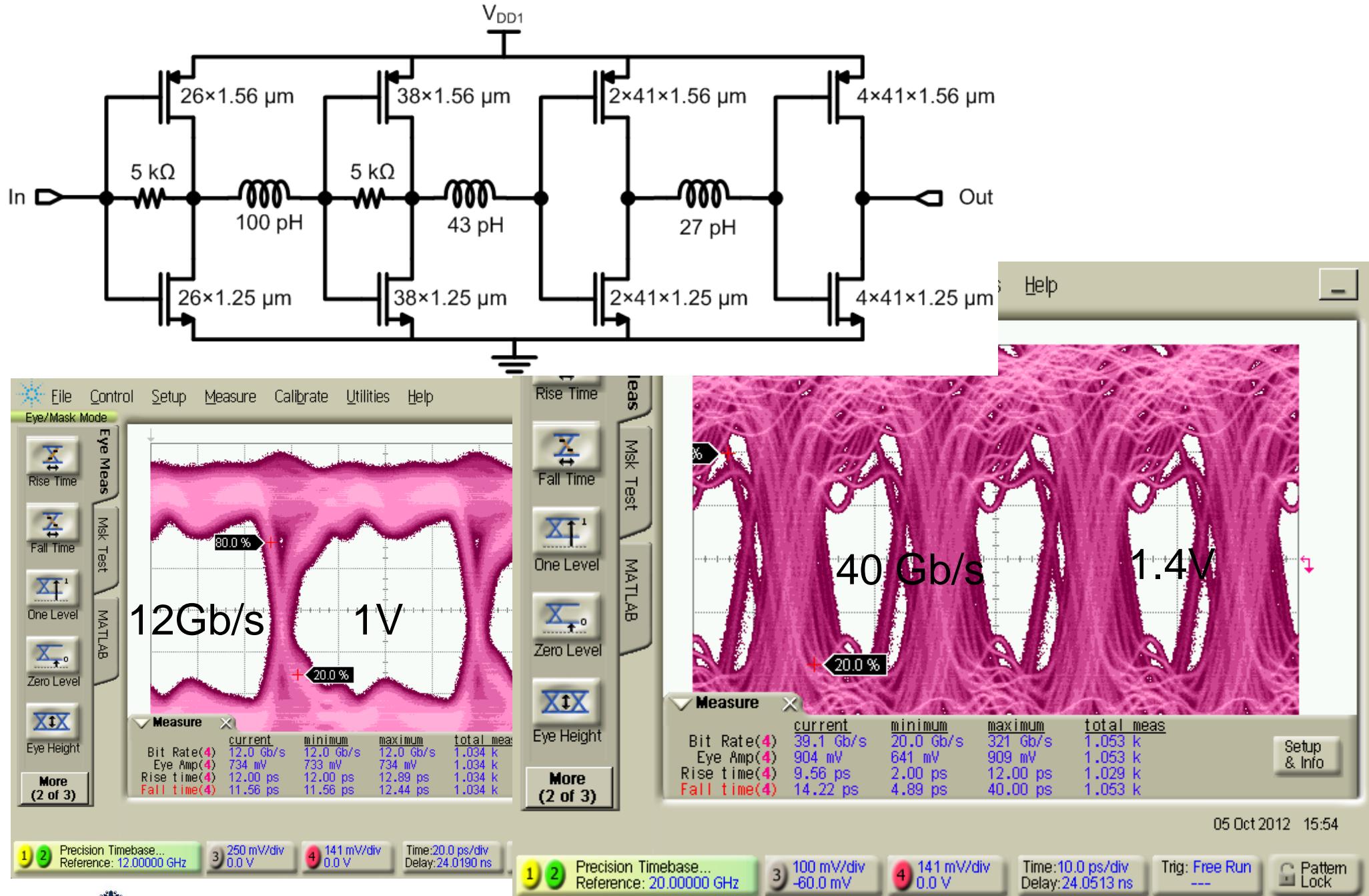
Rise/fall time, efficiency/bit in 45-nm SOI



[I. Sarkas, ISSCC 2012]

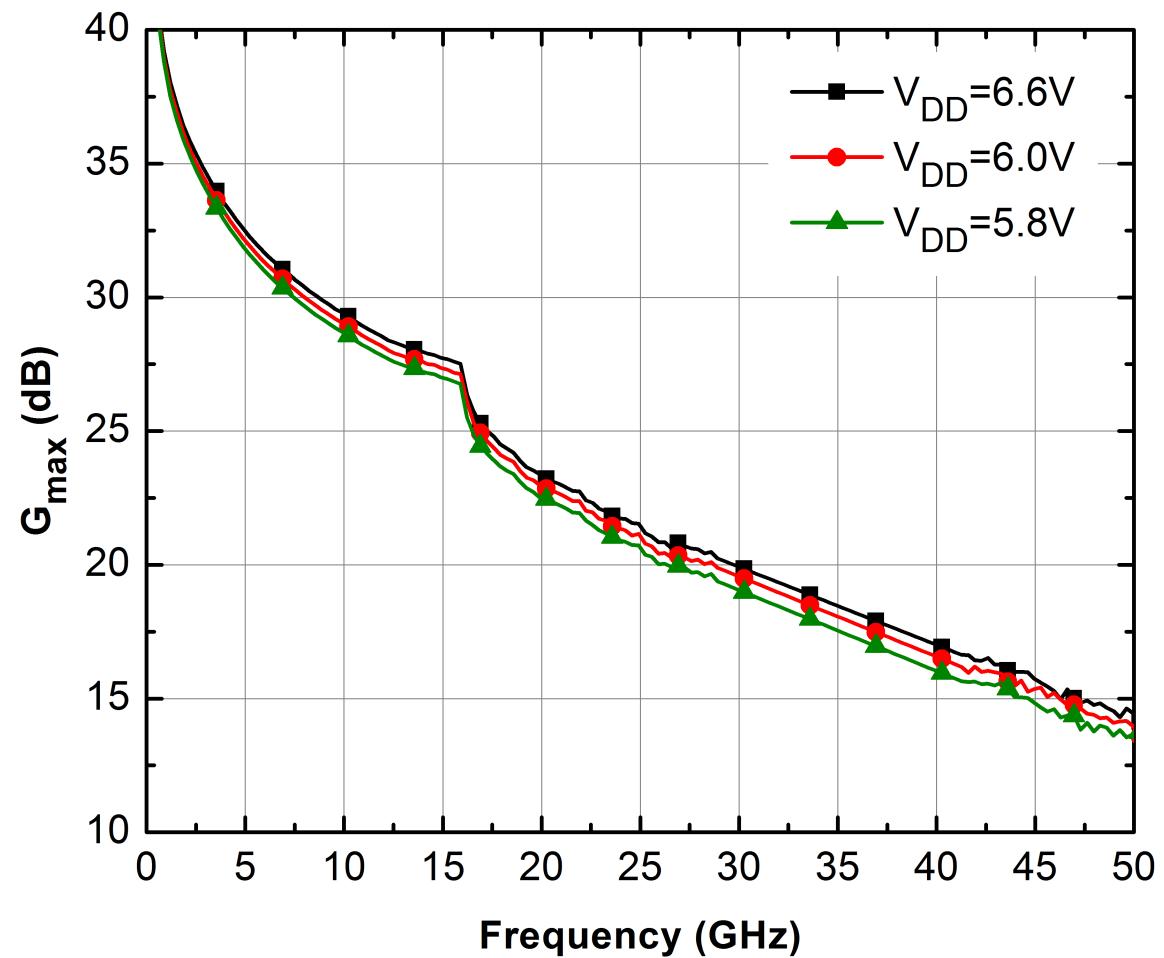
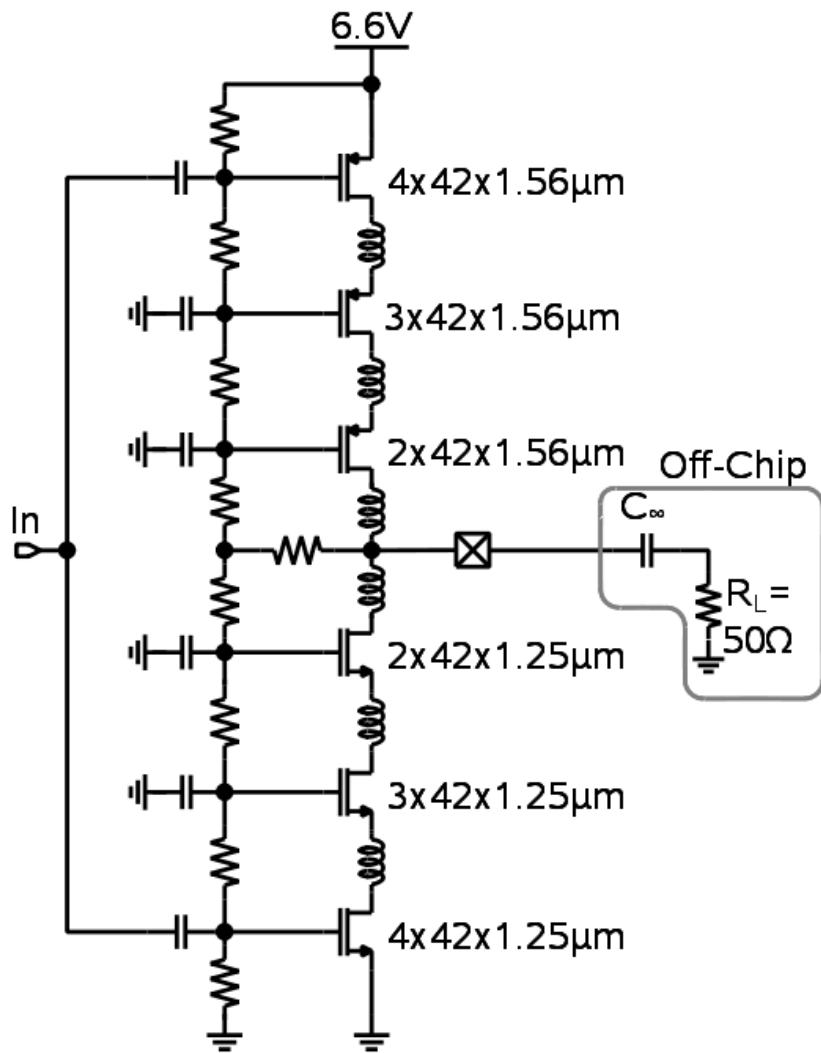


40+ Gb/s inductively-peaked CMOS logic

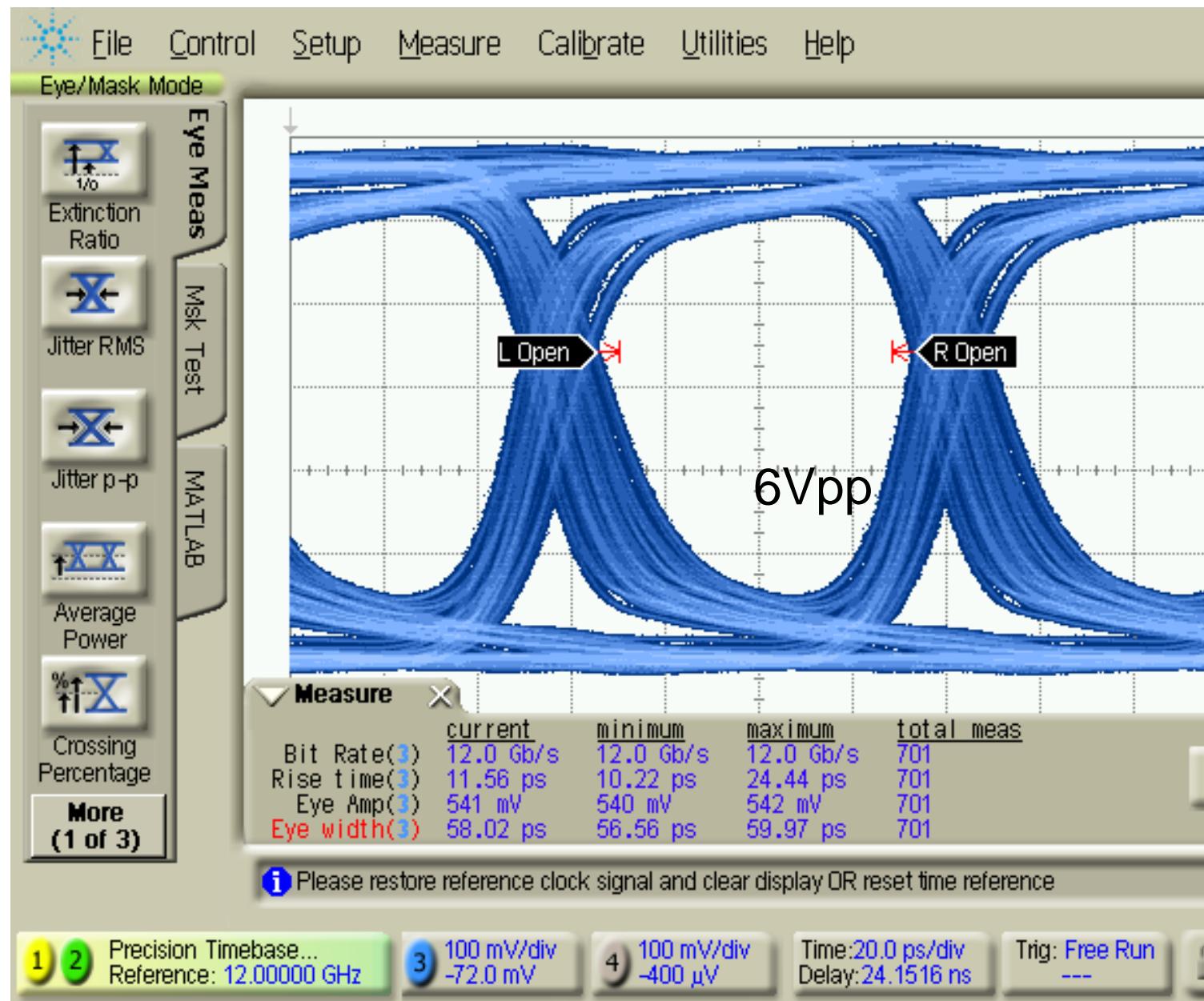


Broadband, large swing stacked CMOS LOGIC

[I. Sarkas, ISSCC 2012]



Eye diagrams at 12 Gb/s

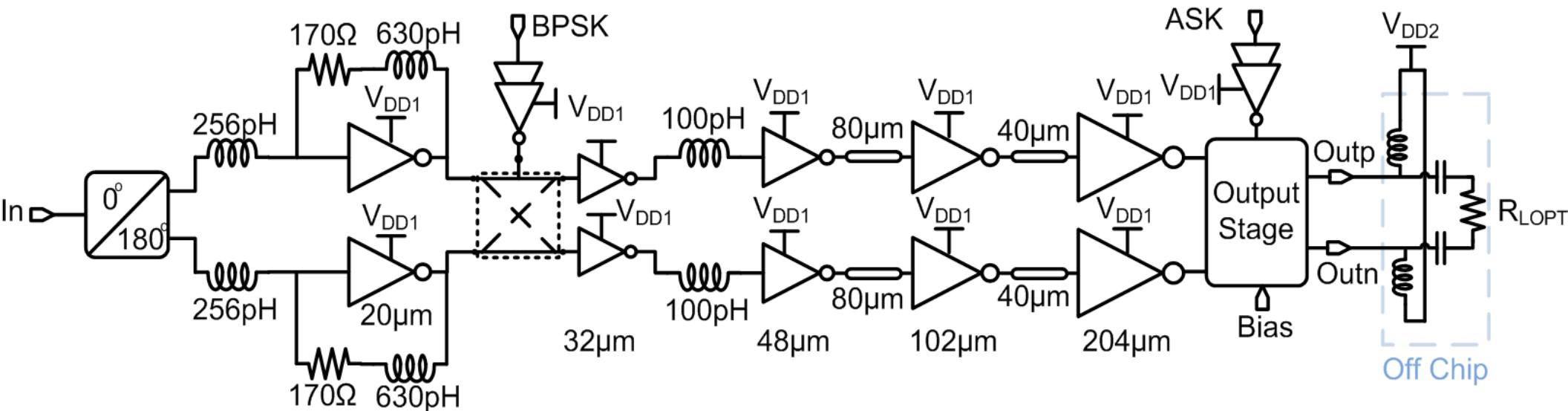


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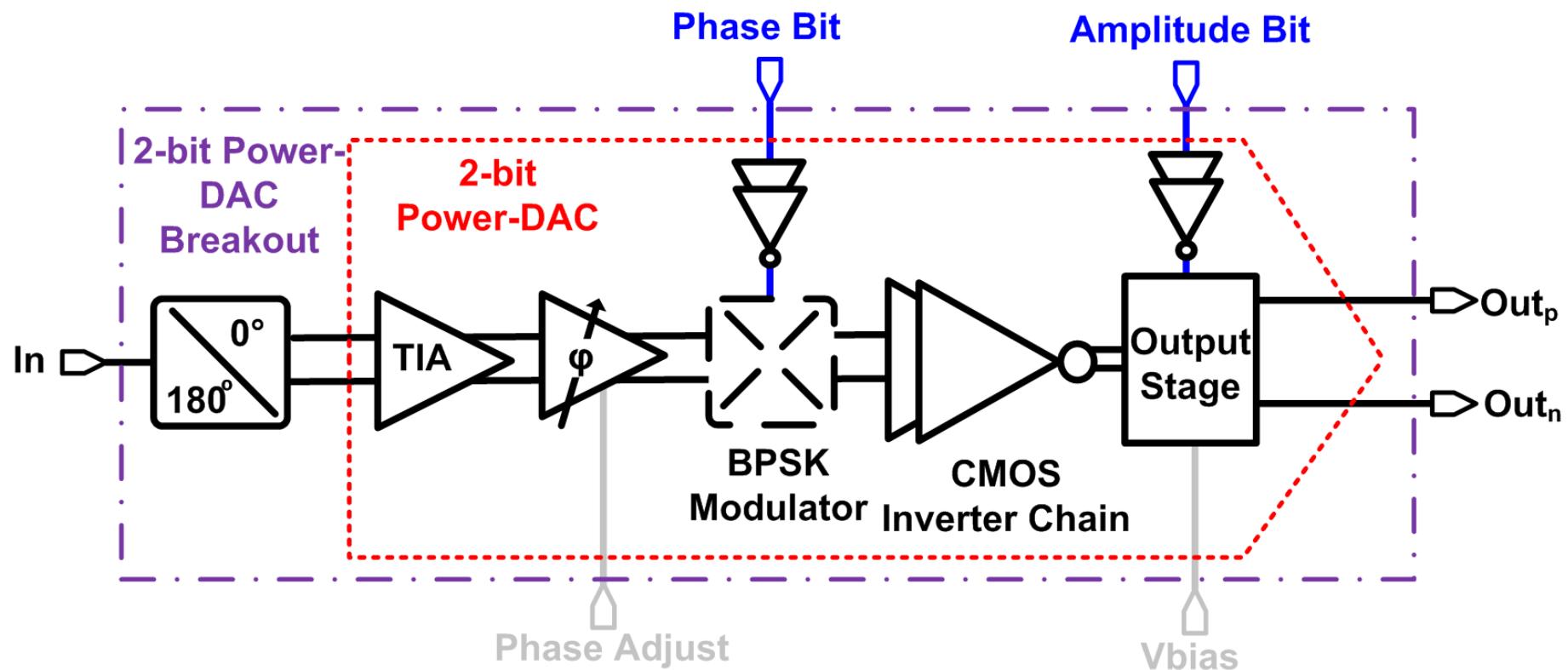


1.5-bit DAC Cell with stacked-CMOS inv.



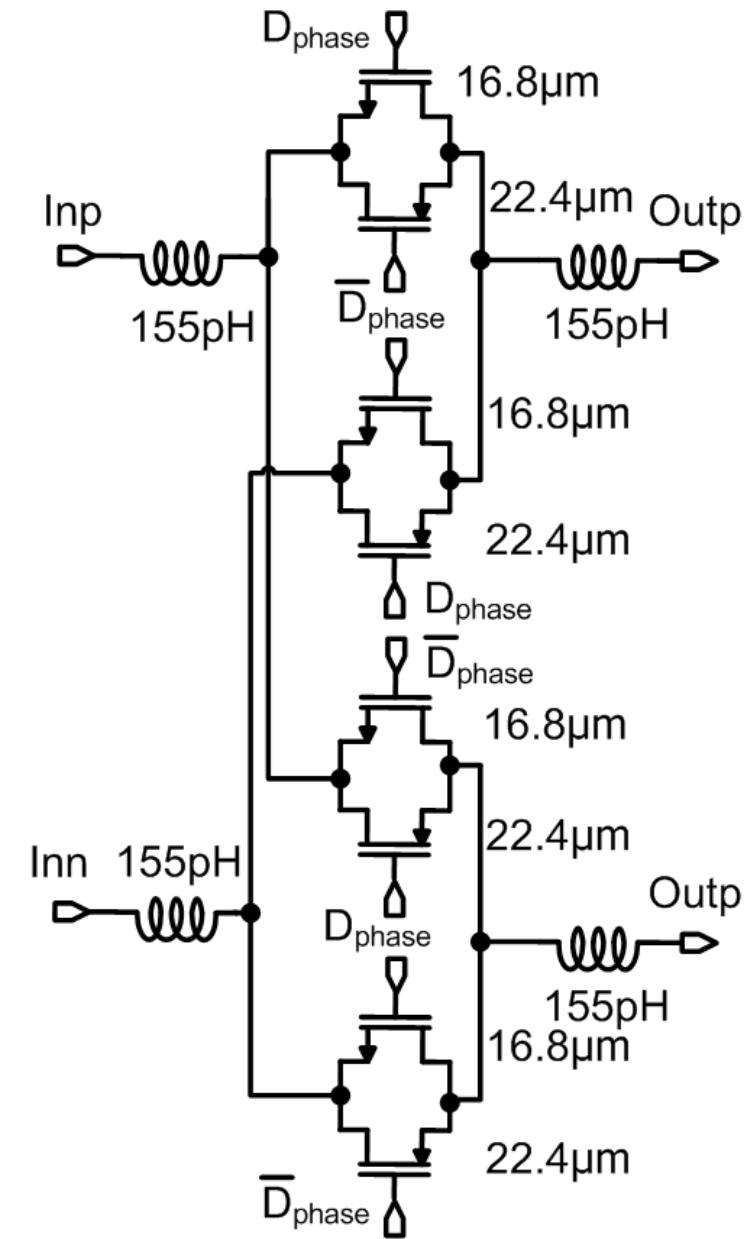
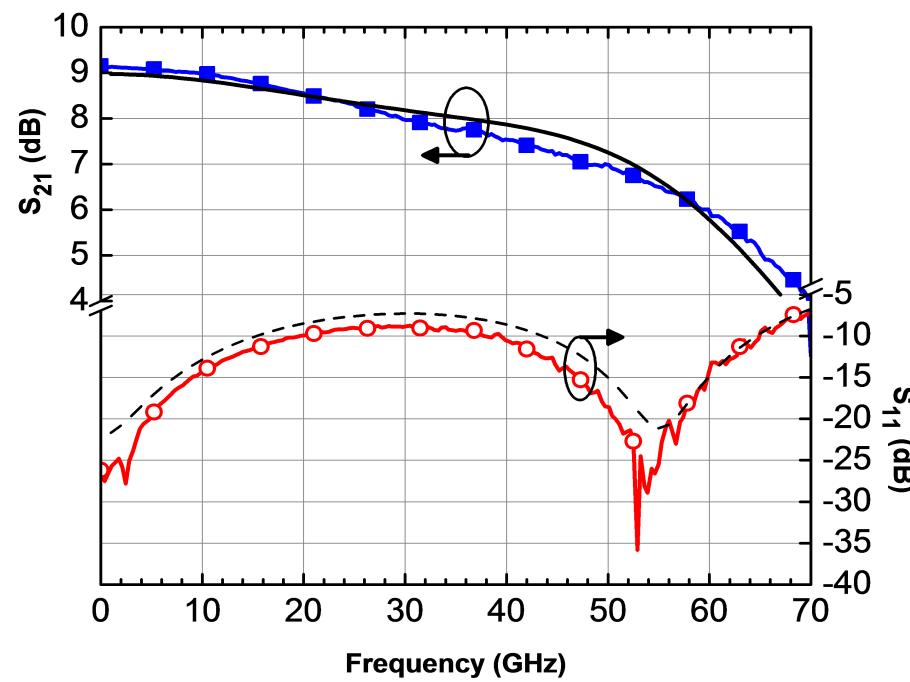
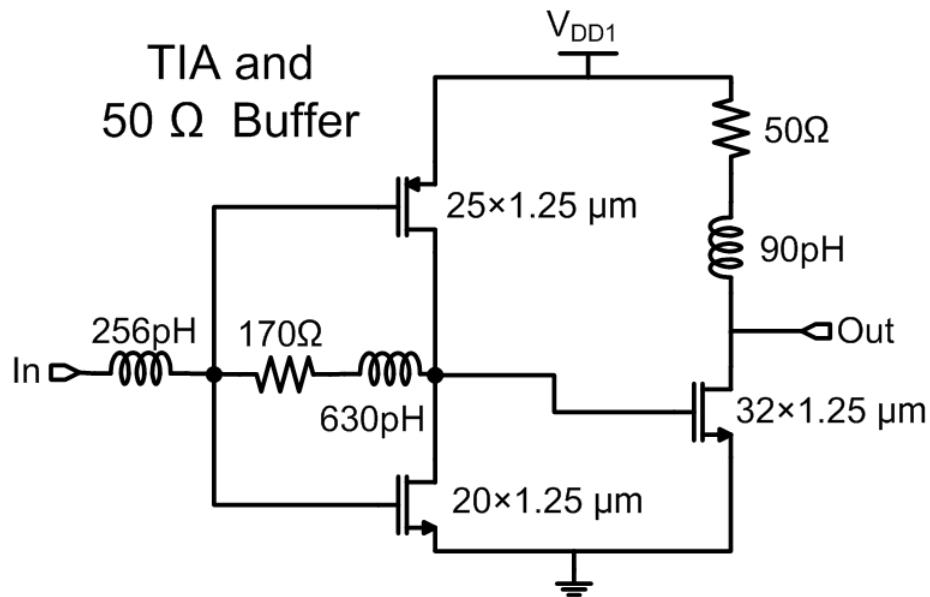
- Input balun for single ended to differential conversion
 - the only tuned component in chain
 - needed for testing
- Input CMOS TIAs for broadband matching
- CMOS Inverter based class-D driver chain

Power-DAC Cell with N-MOS output stage

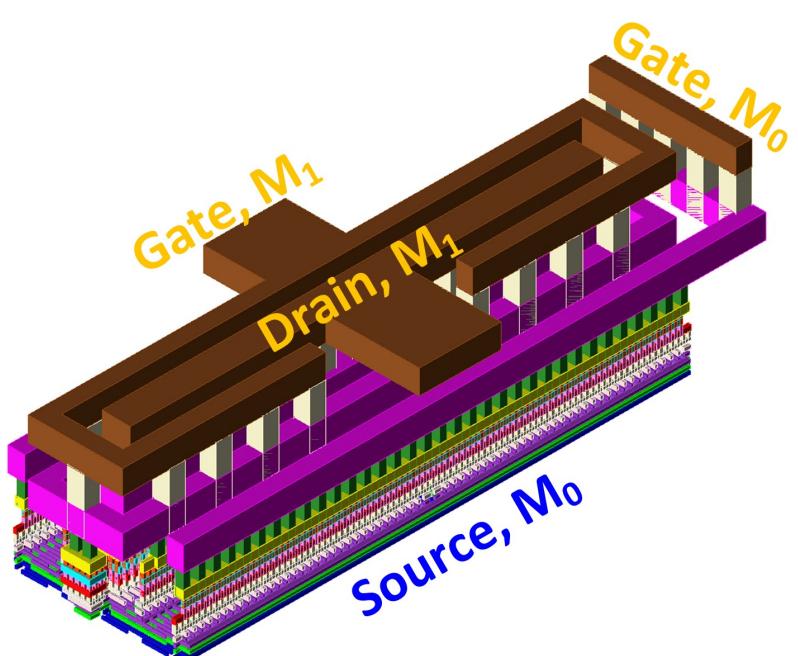
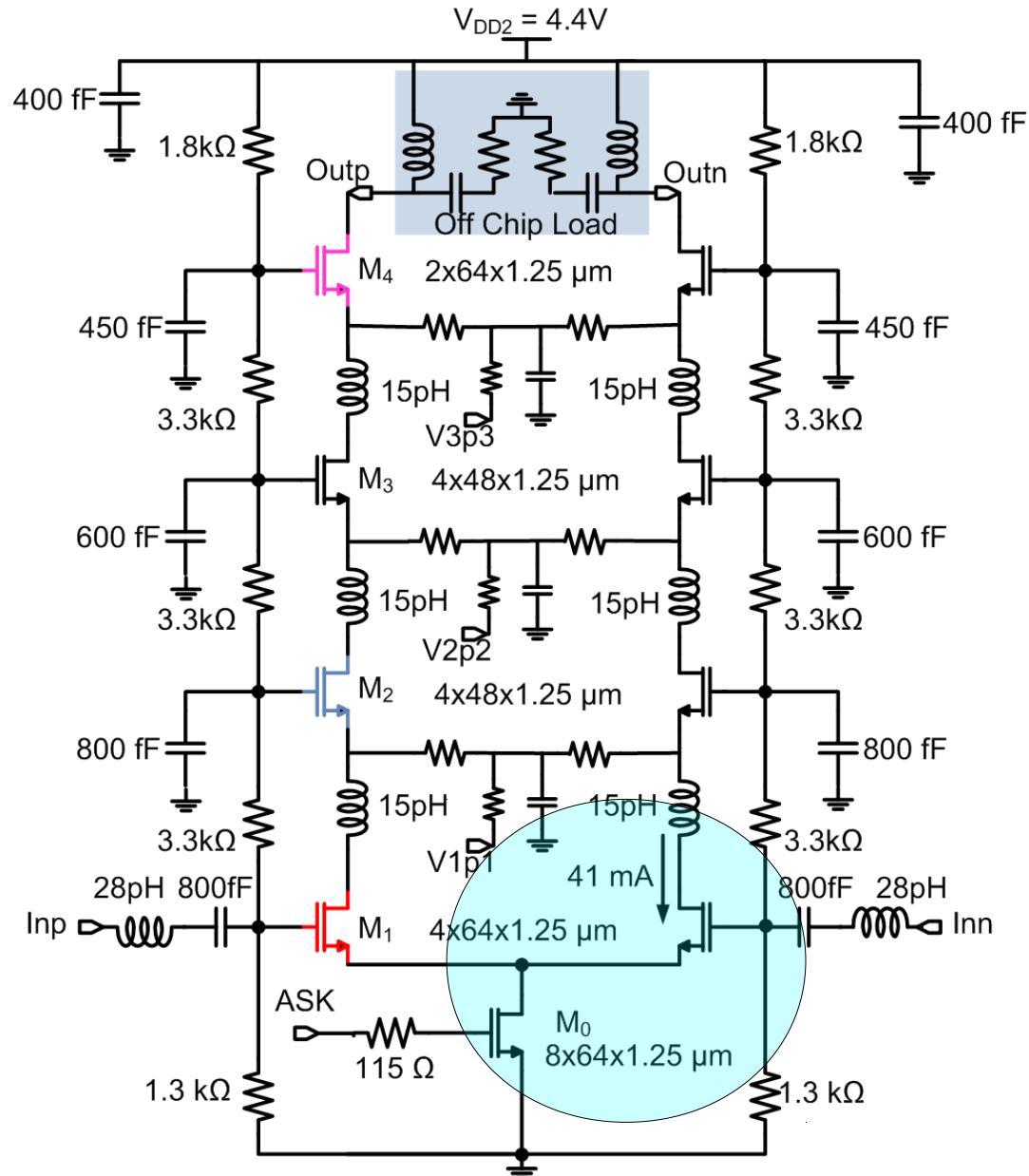


- DC – 50 GHz in 45-nm SOI
- CMOS inverter based. Purely digital
- Scalable to 240 GHz using tuned LO path

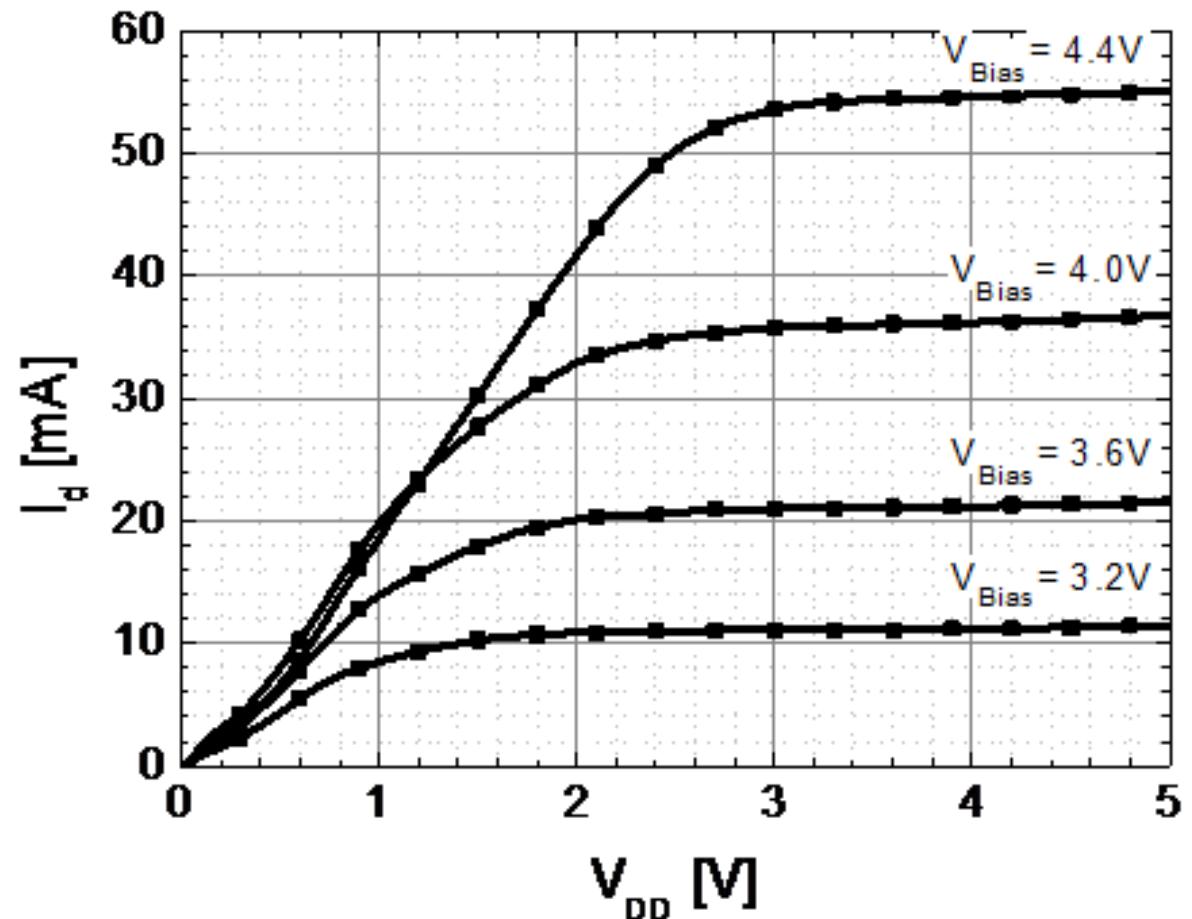
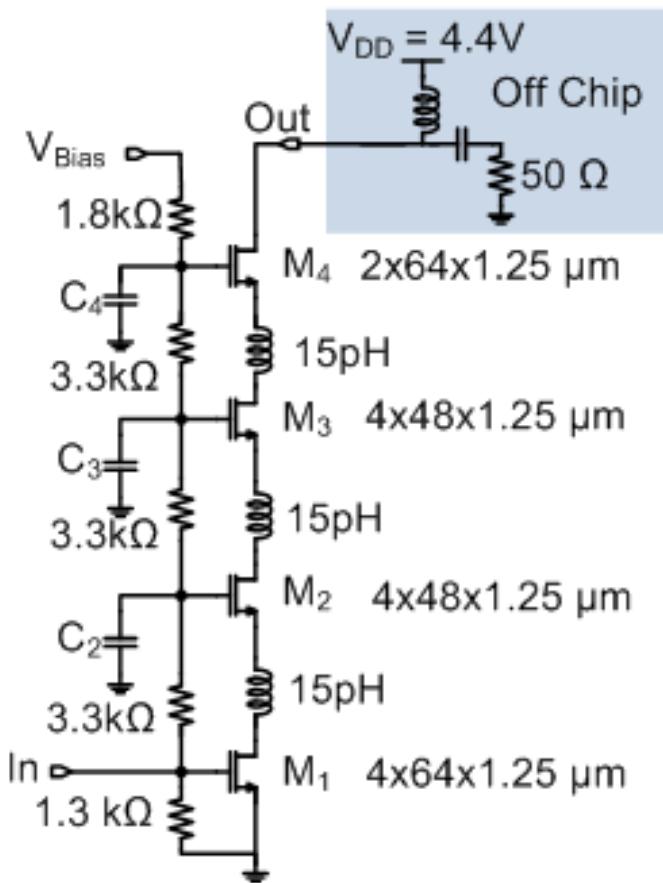
TIA, BPSK Modulator



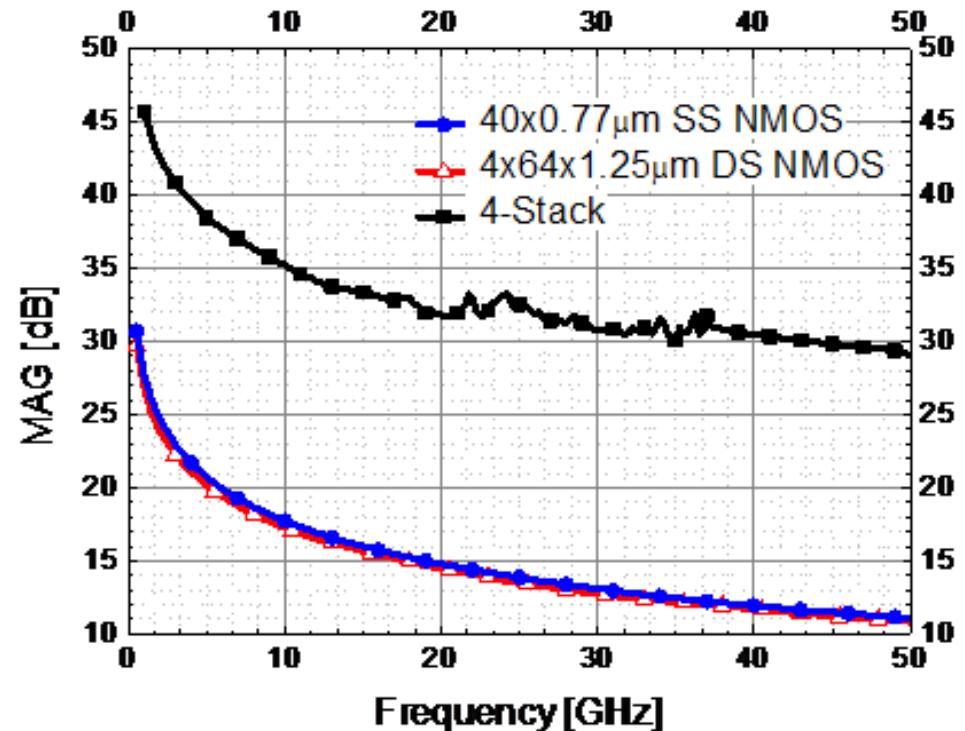
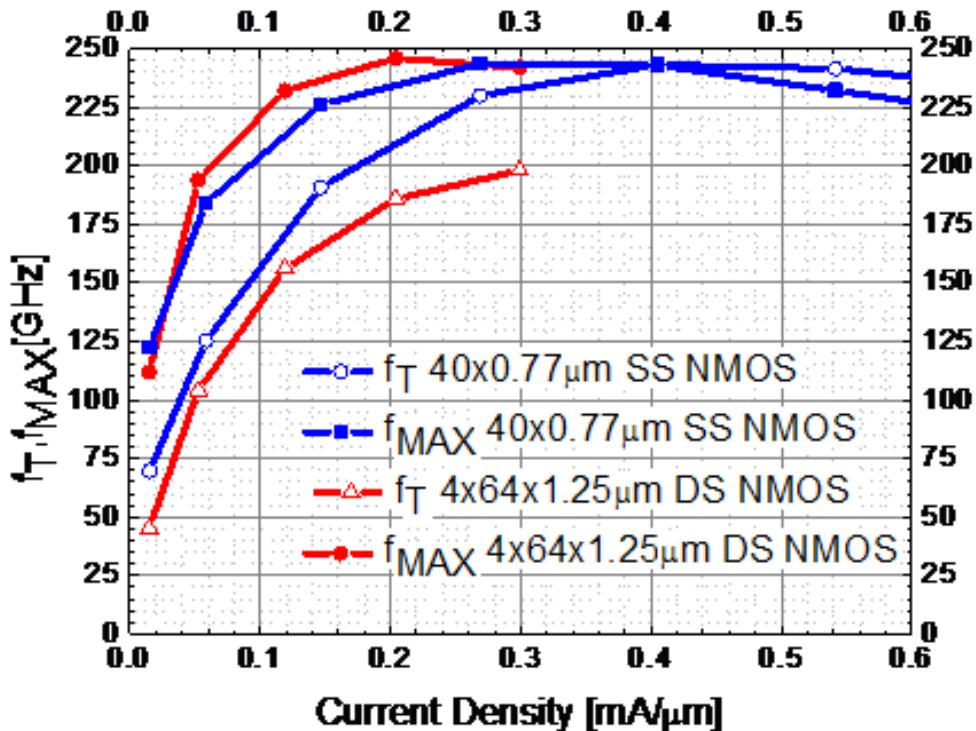
Differential output stage with On-Off switch



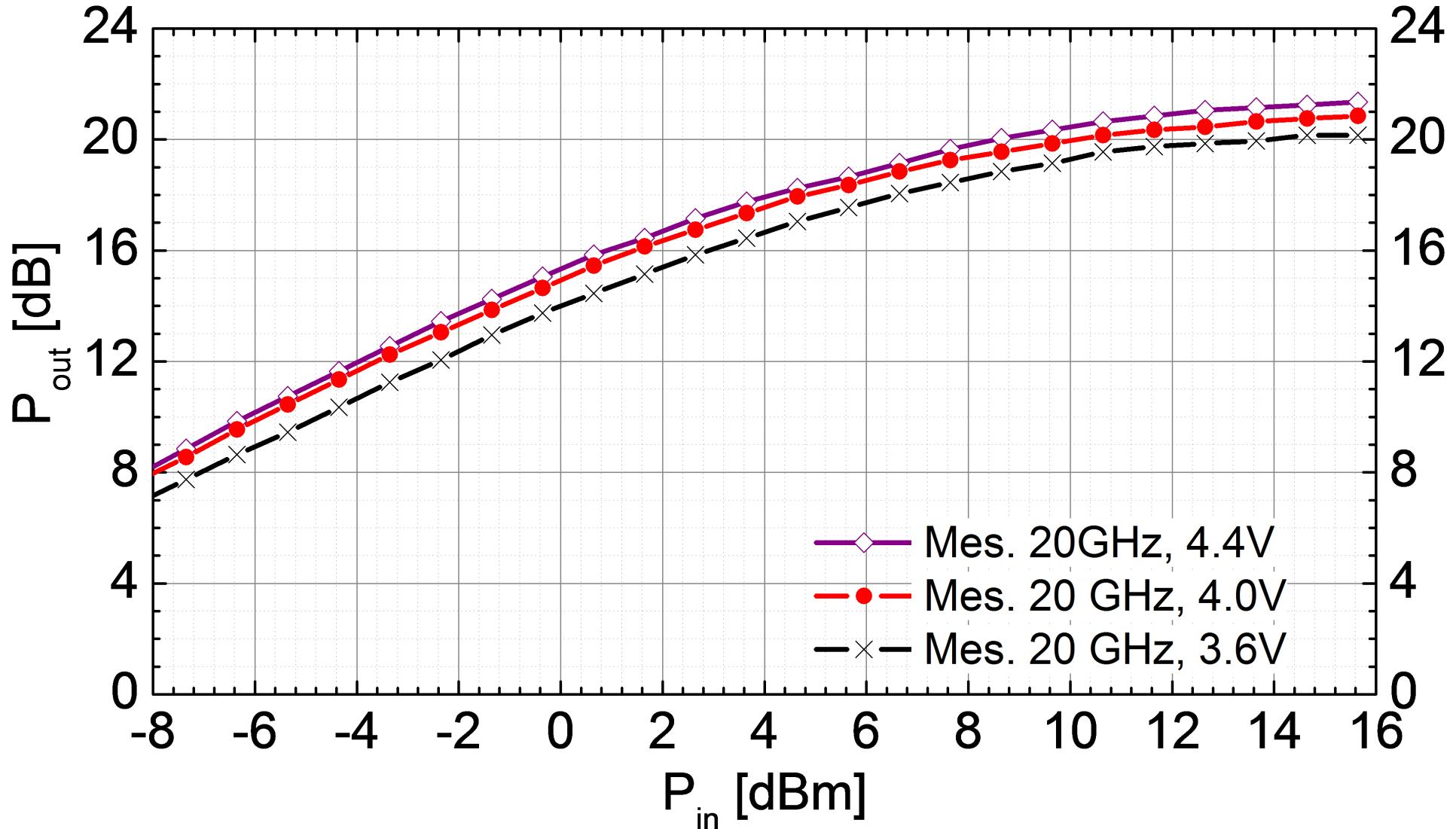
4-Stacked n-MOS Cascode



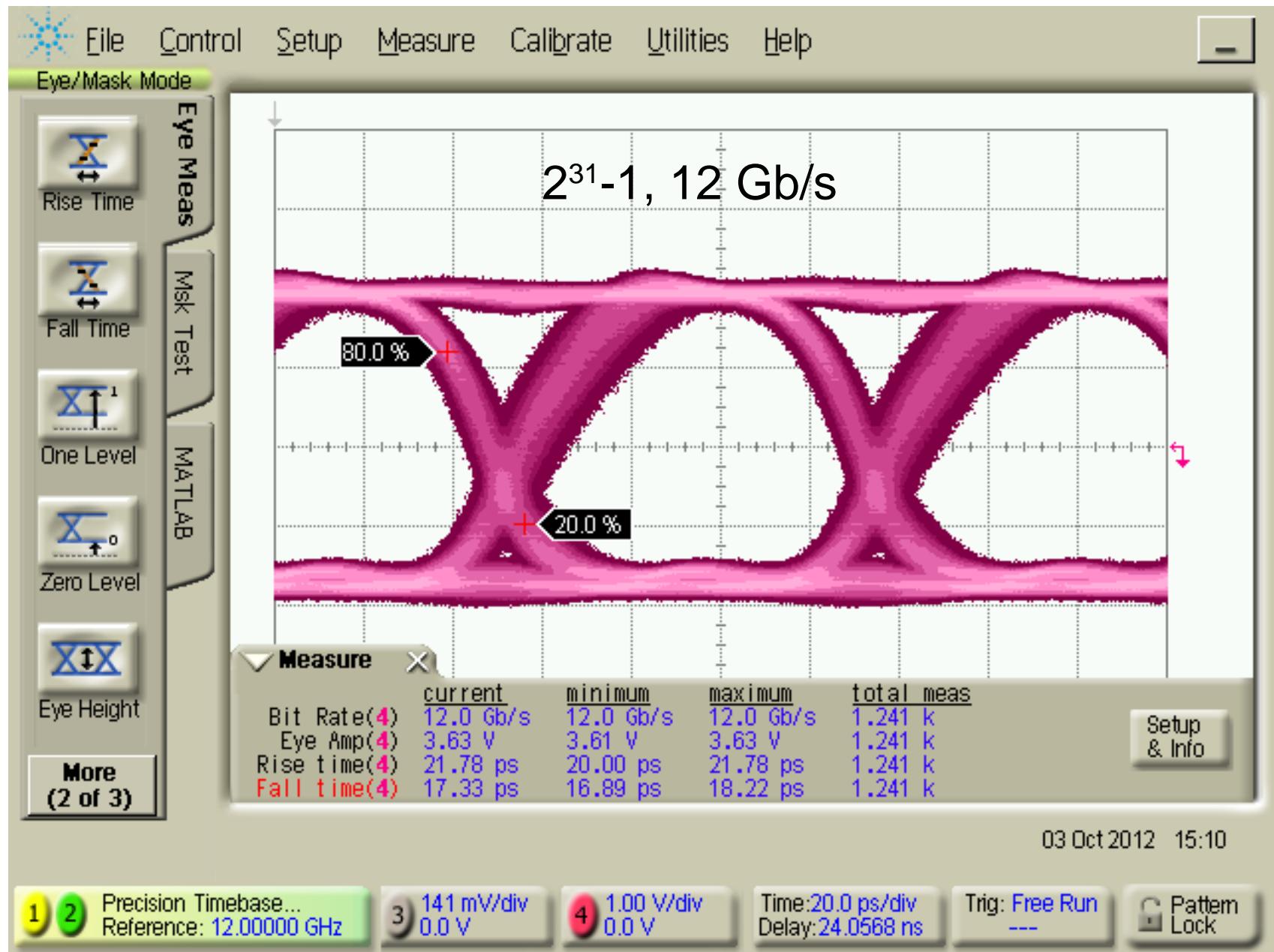
4-Stacked n-MOS Cascode (ii)



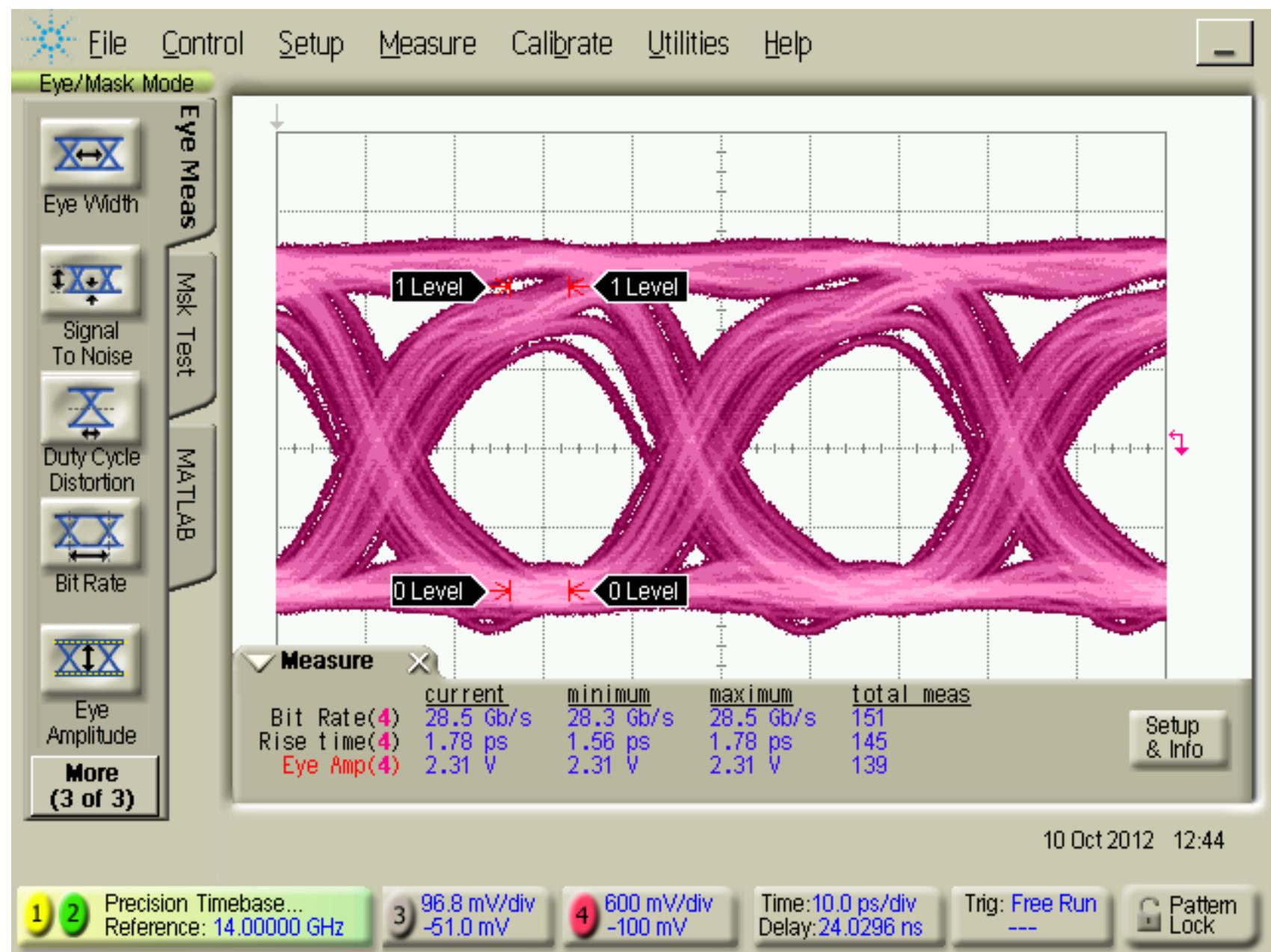
4-Stacked n-MOS Cascode (iii)



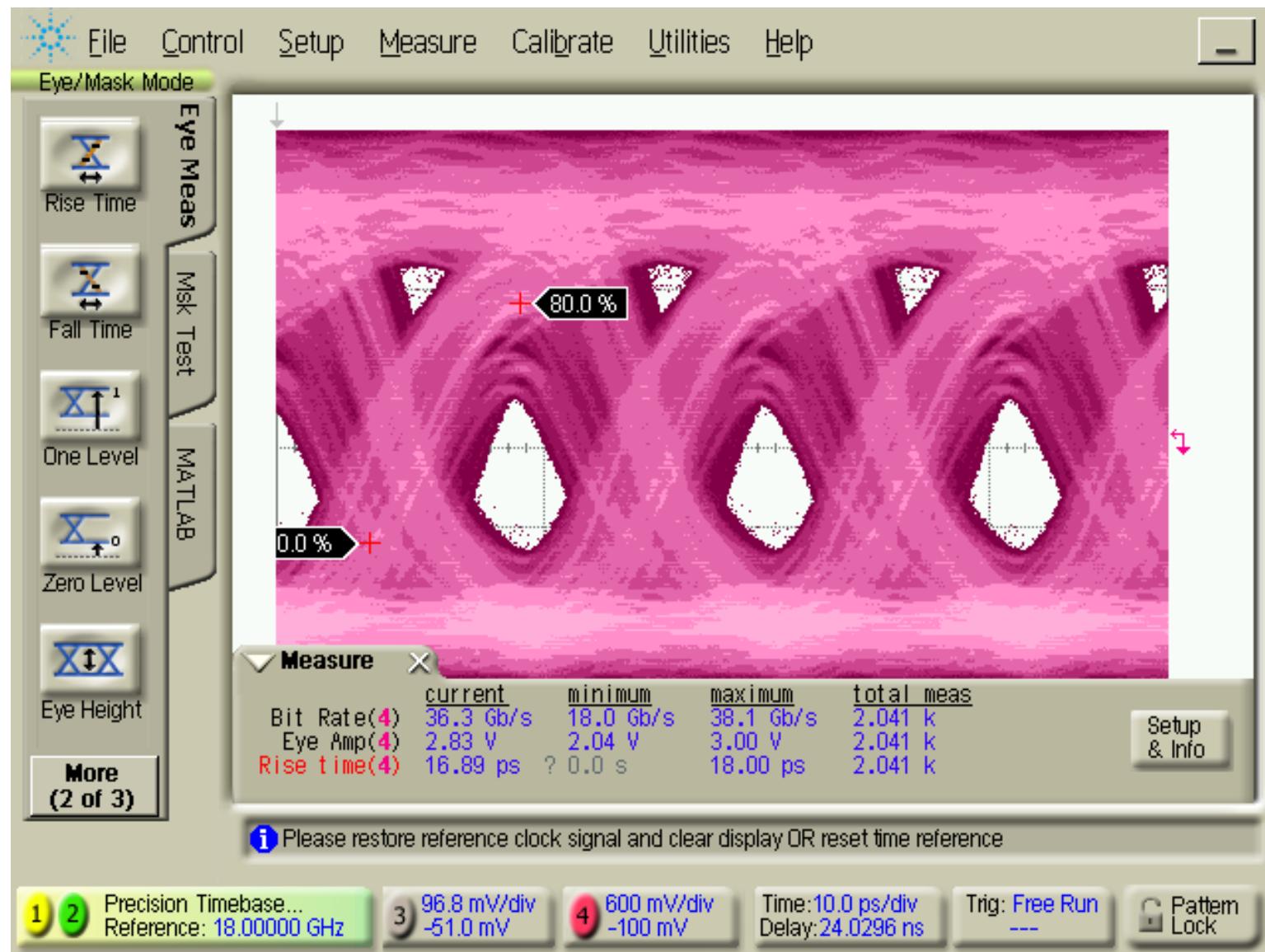
4-Stacked n-MOS Cascode (iv)



DAC Cell: 28 Gb/s Eyes

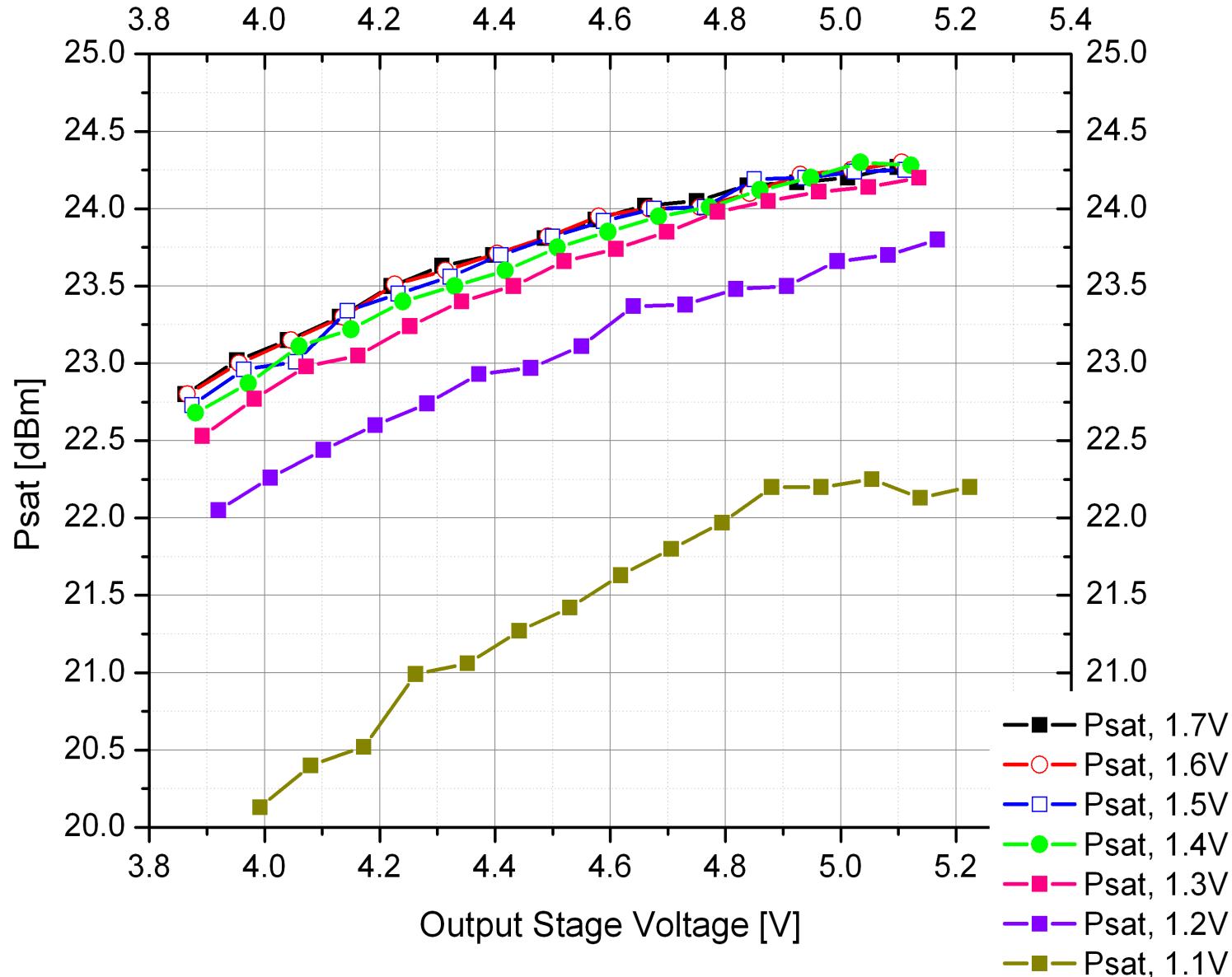


DAC Cell: 36 Gb/s Eyes

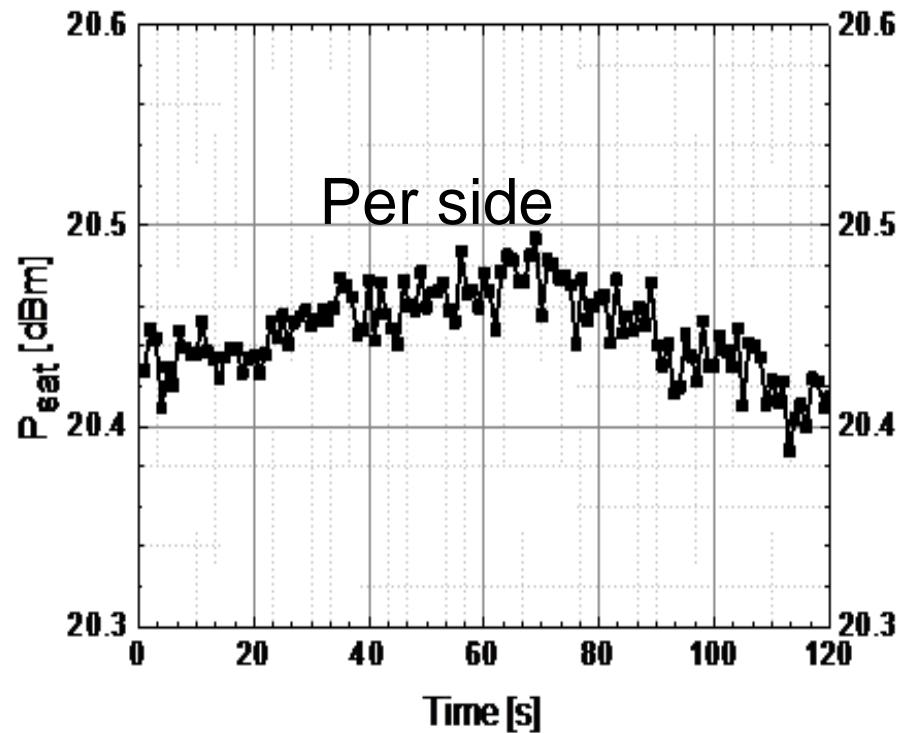
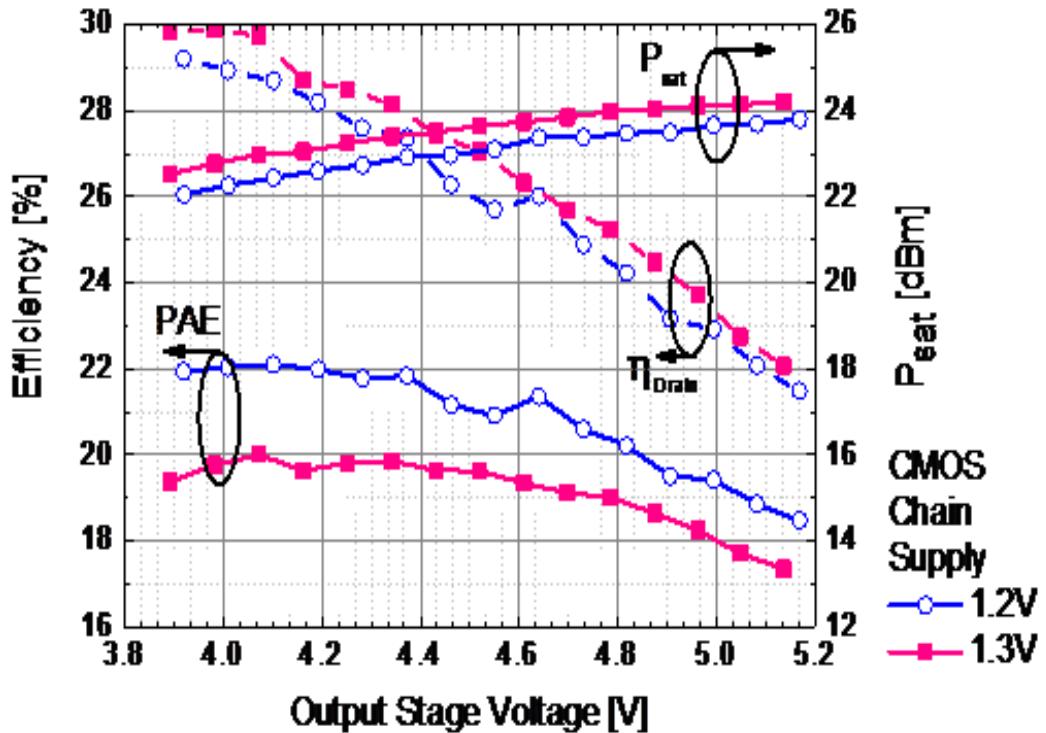


45-GHz IQ DAC Cell: Eyes, P_{SAT}

P_{SAT} Over Supply Voltages @ 45 GHz

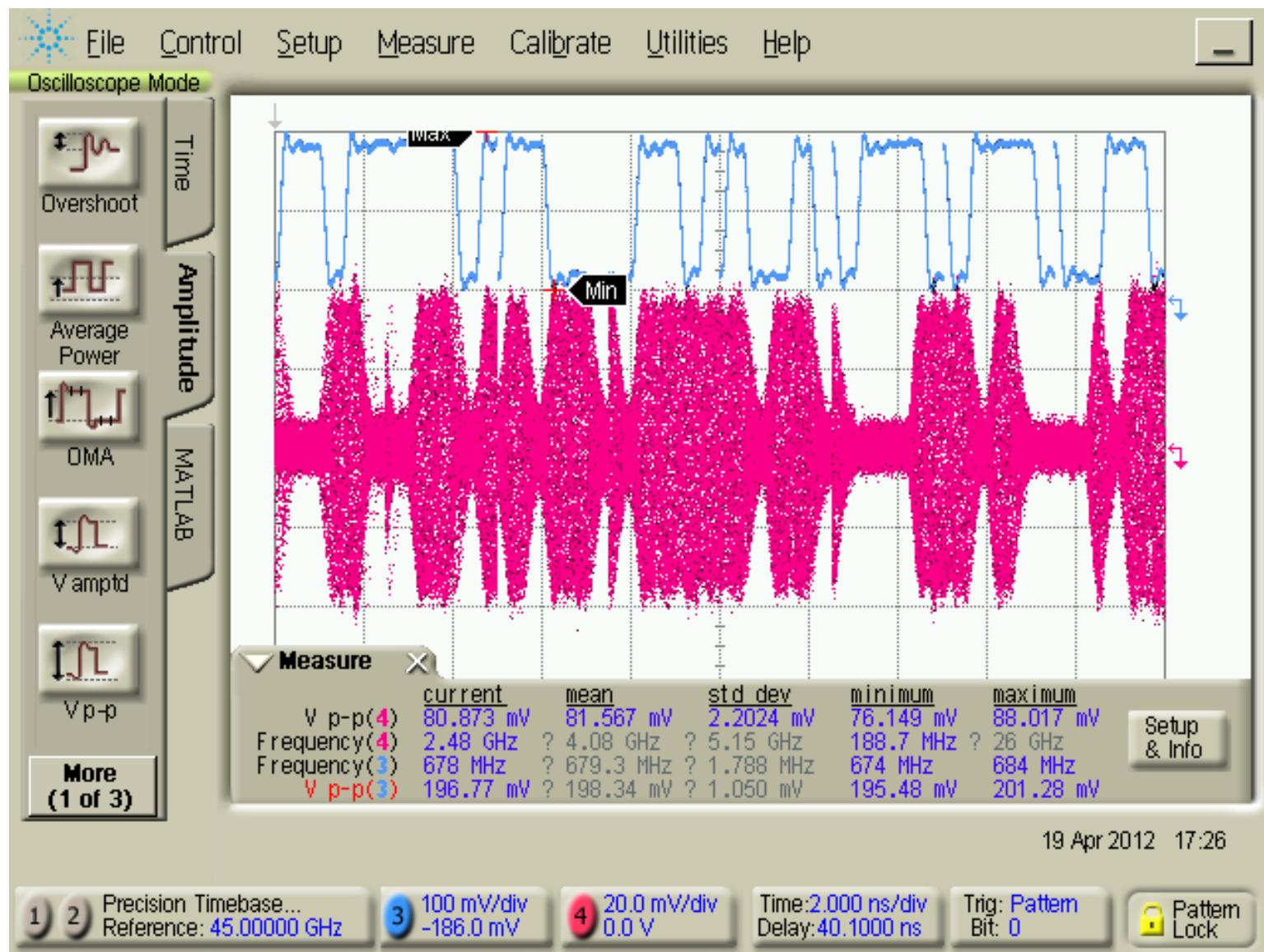


P_{out} of 45-GHz DAC cell vs. time

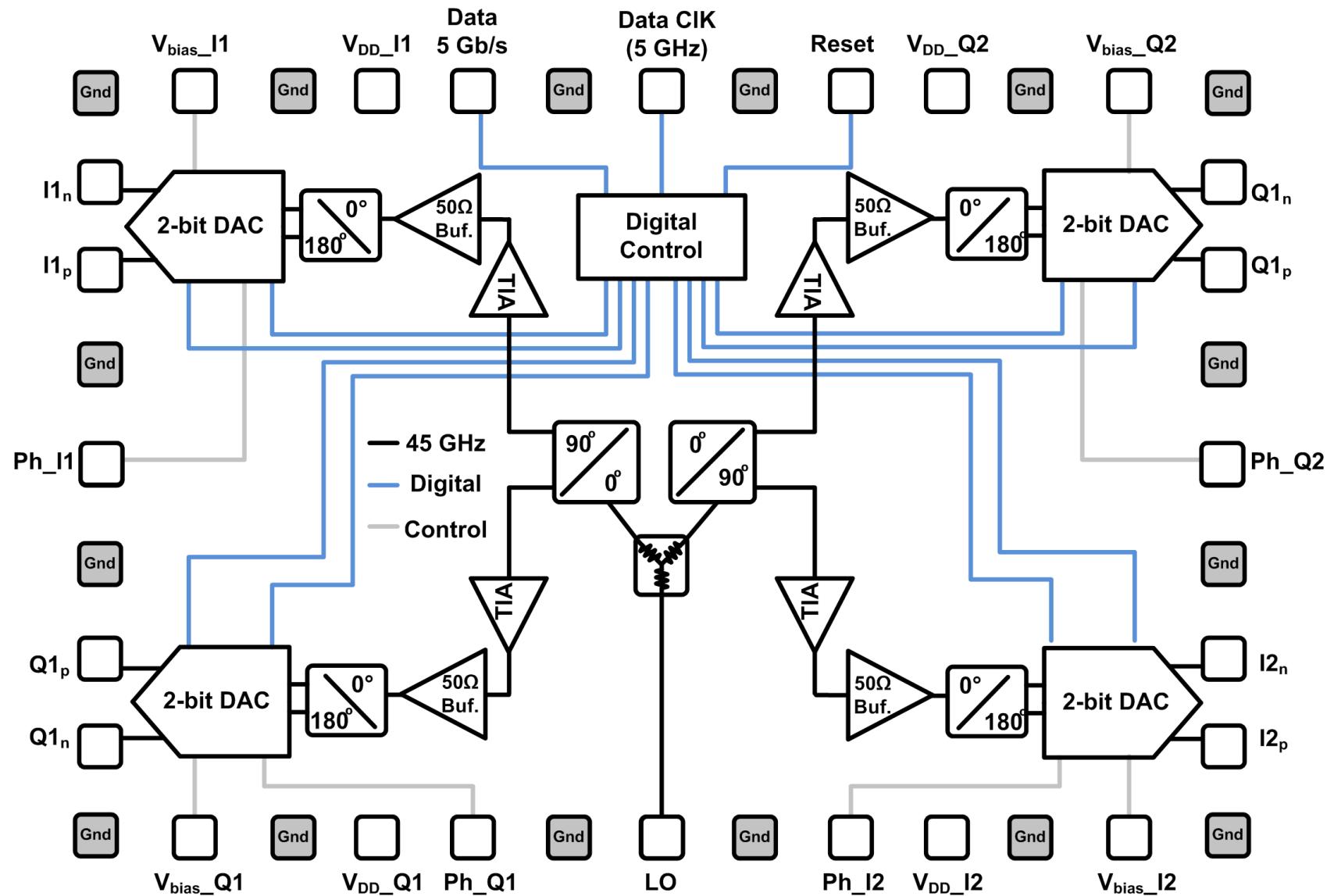


- $P_{\text{sat}} = 23 \text{ dBm}$, $\eta_{\text{Drain}} = 30\%$, PAE = 20%, 4.1V/1.3V
- $P_{\text{sat}} = 24.3 \text{ dBm}$, $\eta_{\text{Drain}} = 22\%$, PAE = 16.3%. 5.1V/1.4V

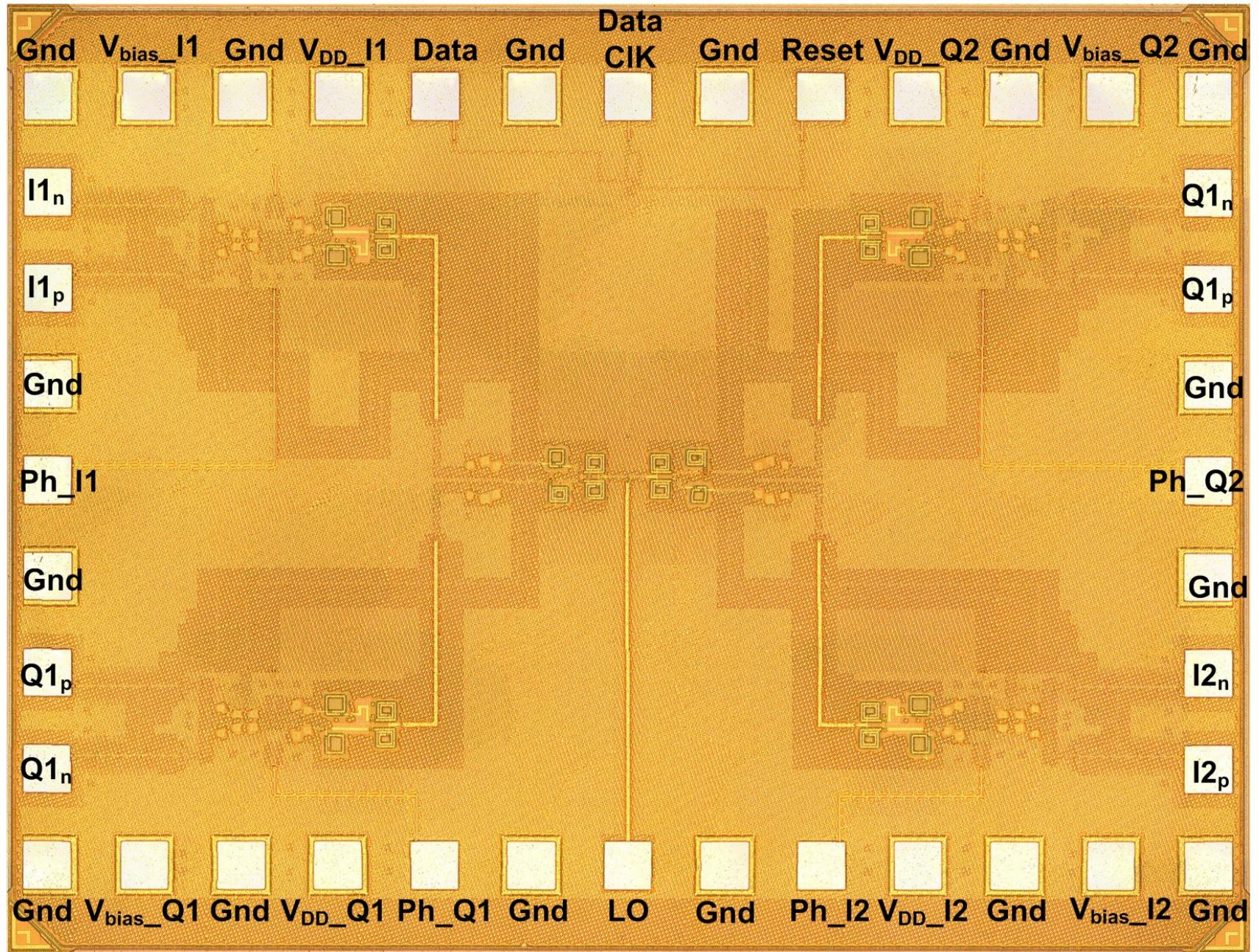
2-Gb/s ASK+ 2-Gbs BPSK Mod of 45-GHz Carrier



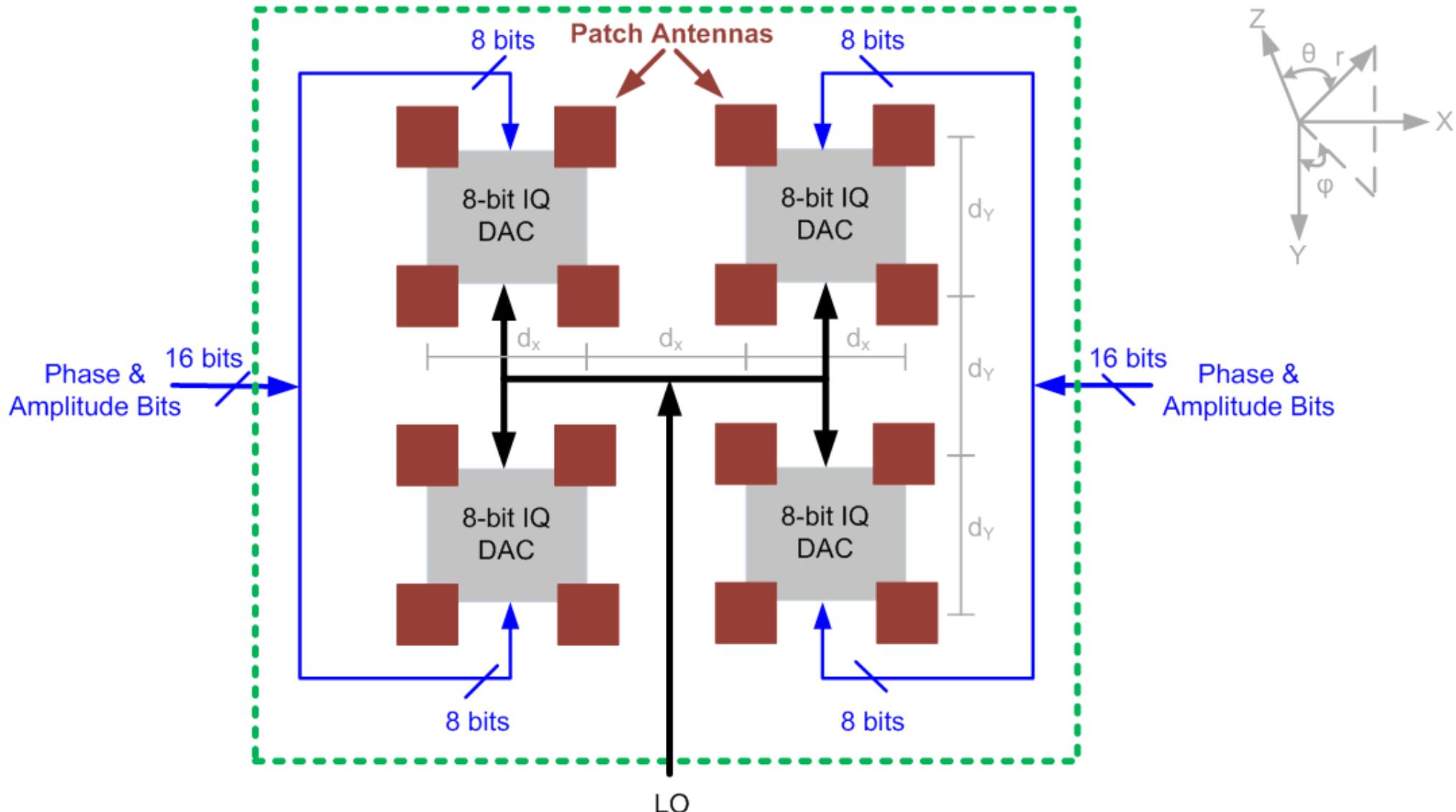
45-GHz 8-bit IQ DAC chiplet



Die photo

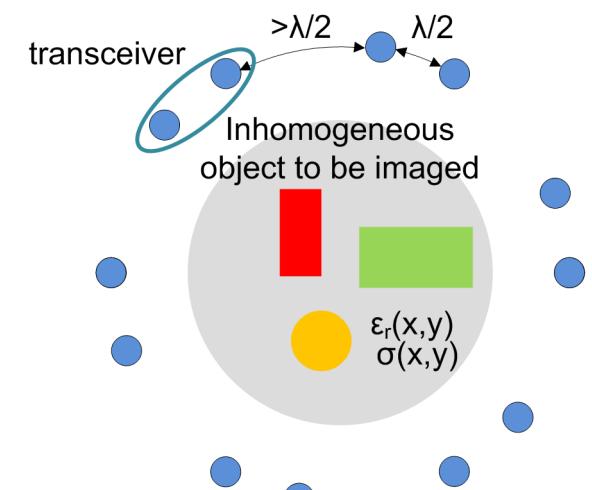
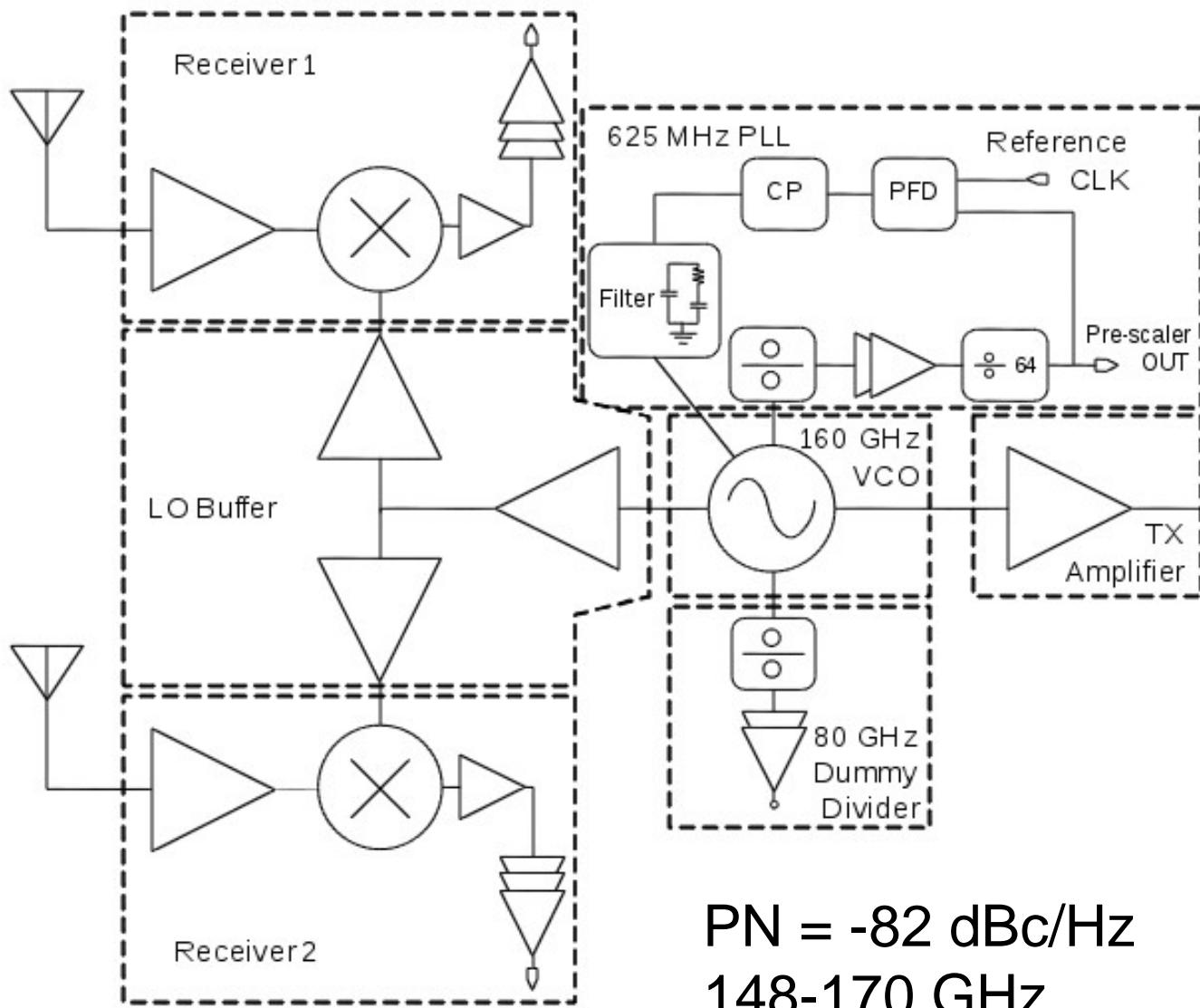


45-GHz 32-bit IQ-DAC board



- > 34 dBm, to be designed and packaged by UCSD

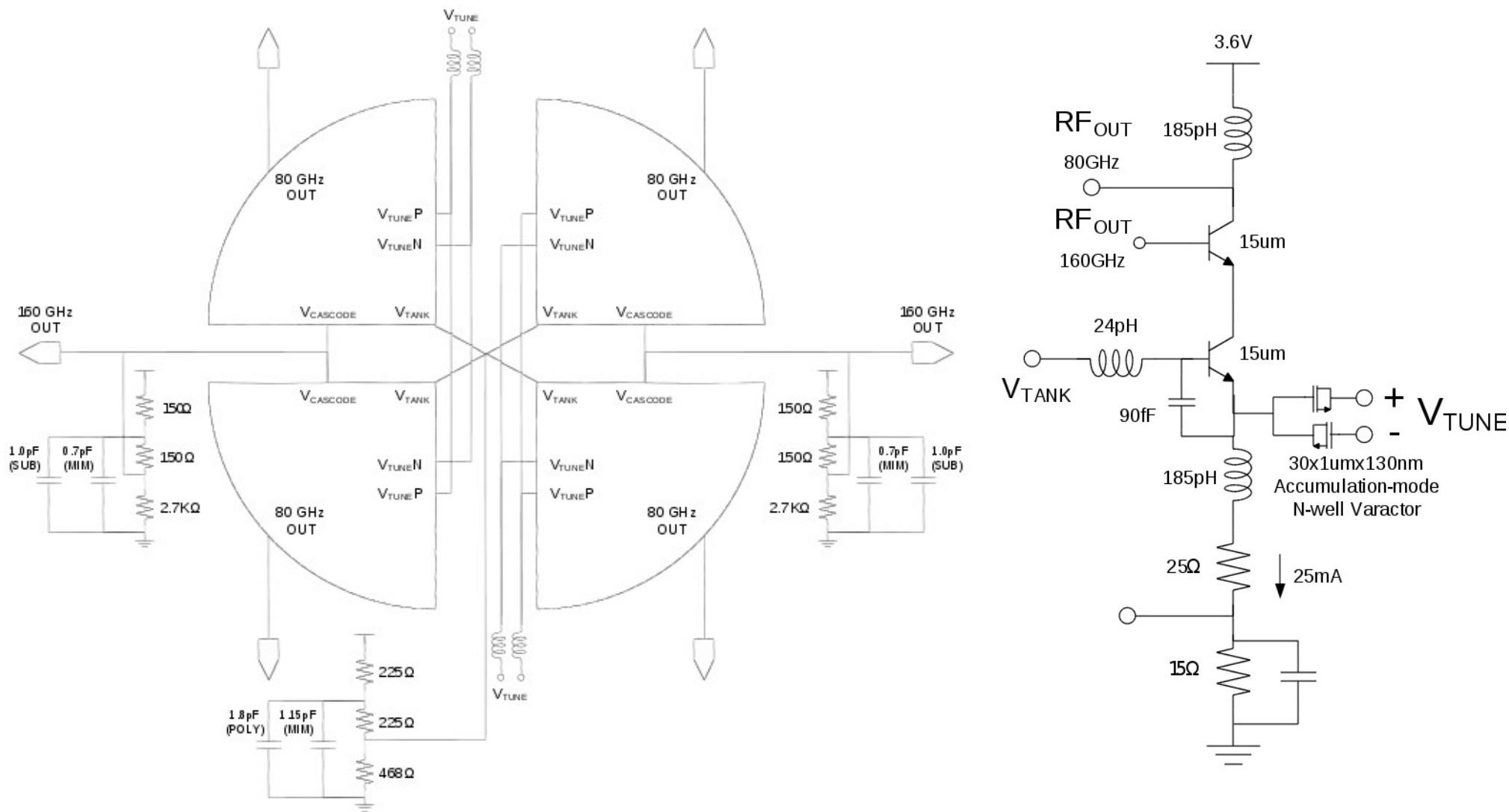
Dual Receive Channel Transceiver



I. Sarkas et al., MIKON-2012

Sorin Voinigescu, October 12, 2012

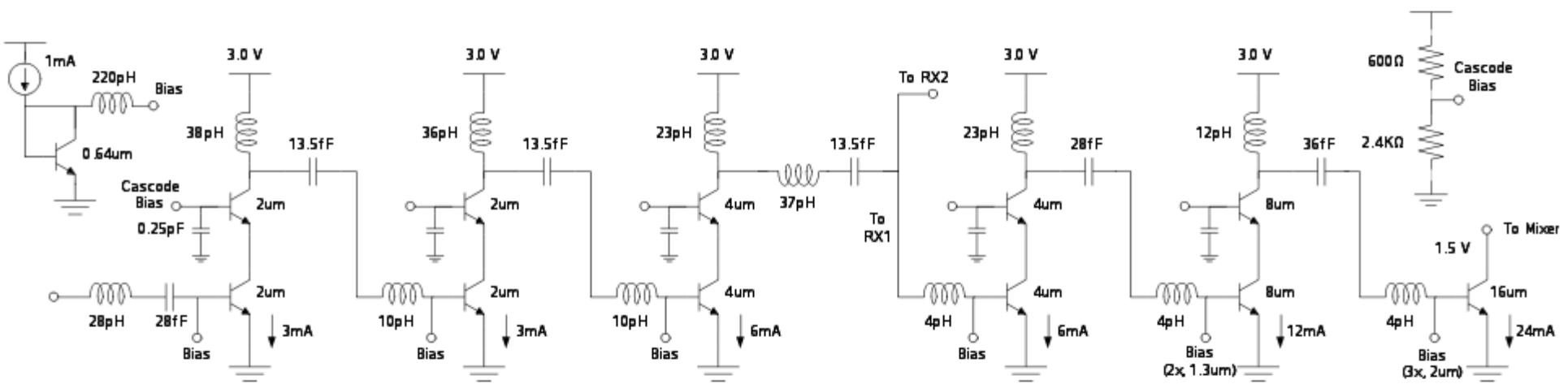
Push-Push 148-170 GHz VCO



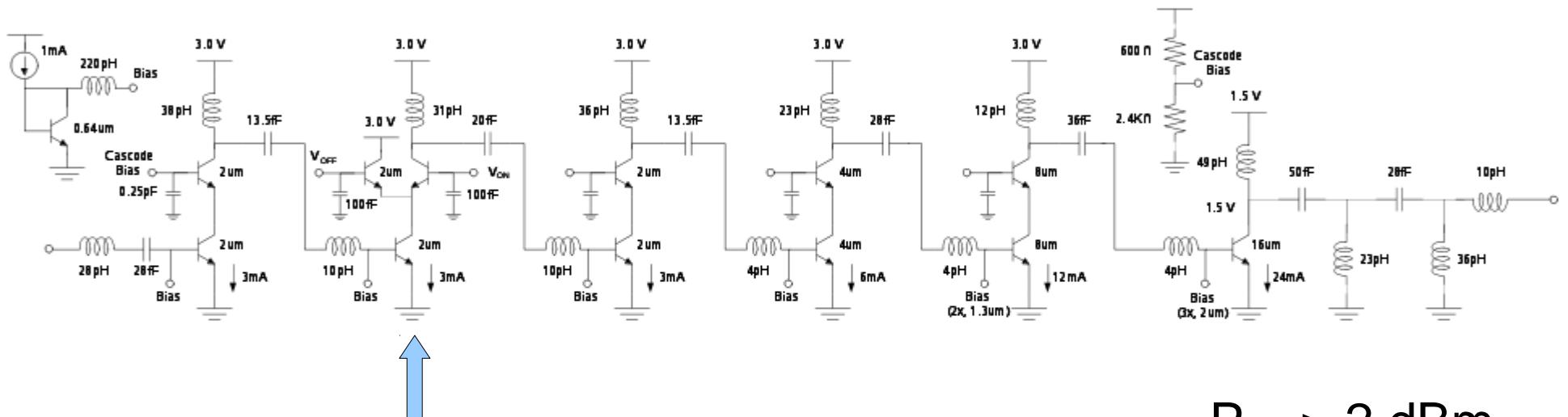
$$P_{DC} = 360 \text{ mW}, P_{OUT} = -10 \text{ dBm}, PN = -82 \text{ dBc/Hz at } 1 \text{ MHz offset}$$



148-170 GHz LO Tree and TX Amplifiers



$$P_D = 126 \text{ mW}$$



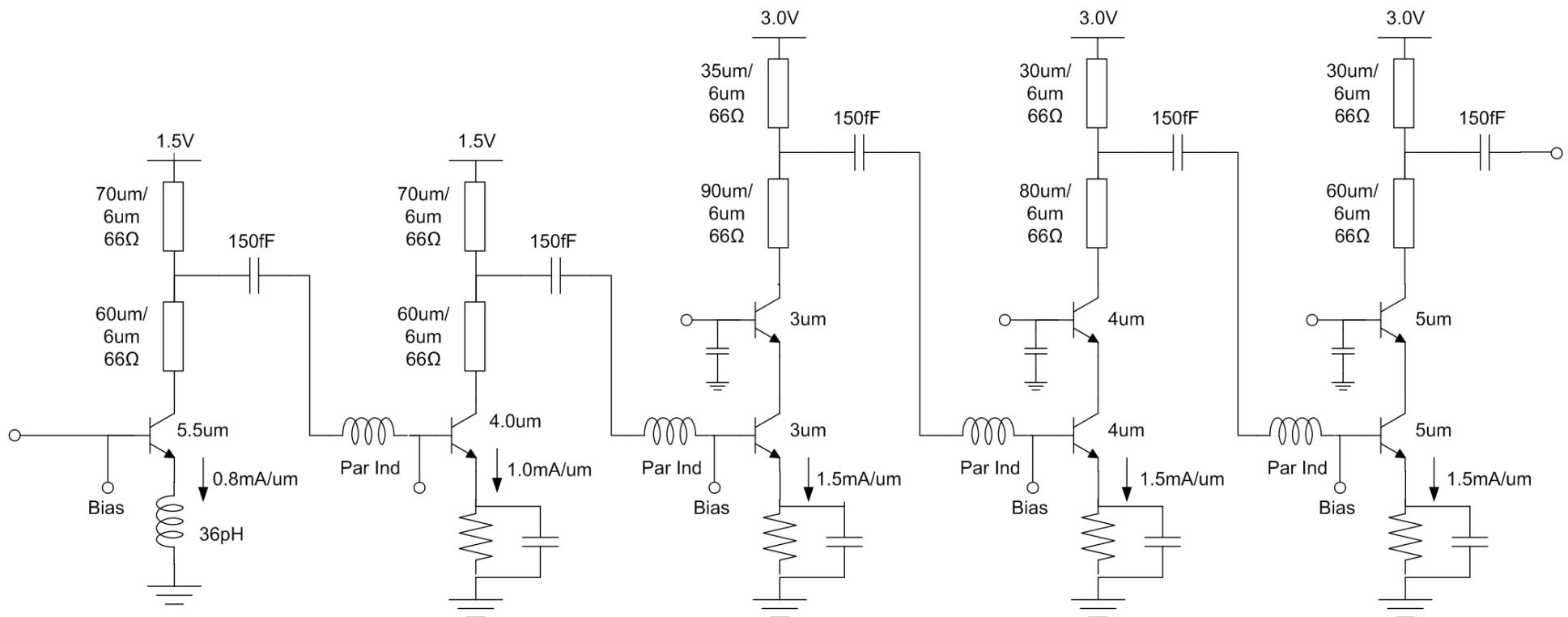
Amplitude Modulator

$$P_{\text{out}} > 2 \text{ dBm}$$

$$P_D = 117 \text{ mW}$$

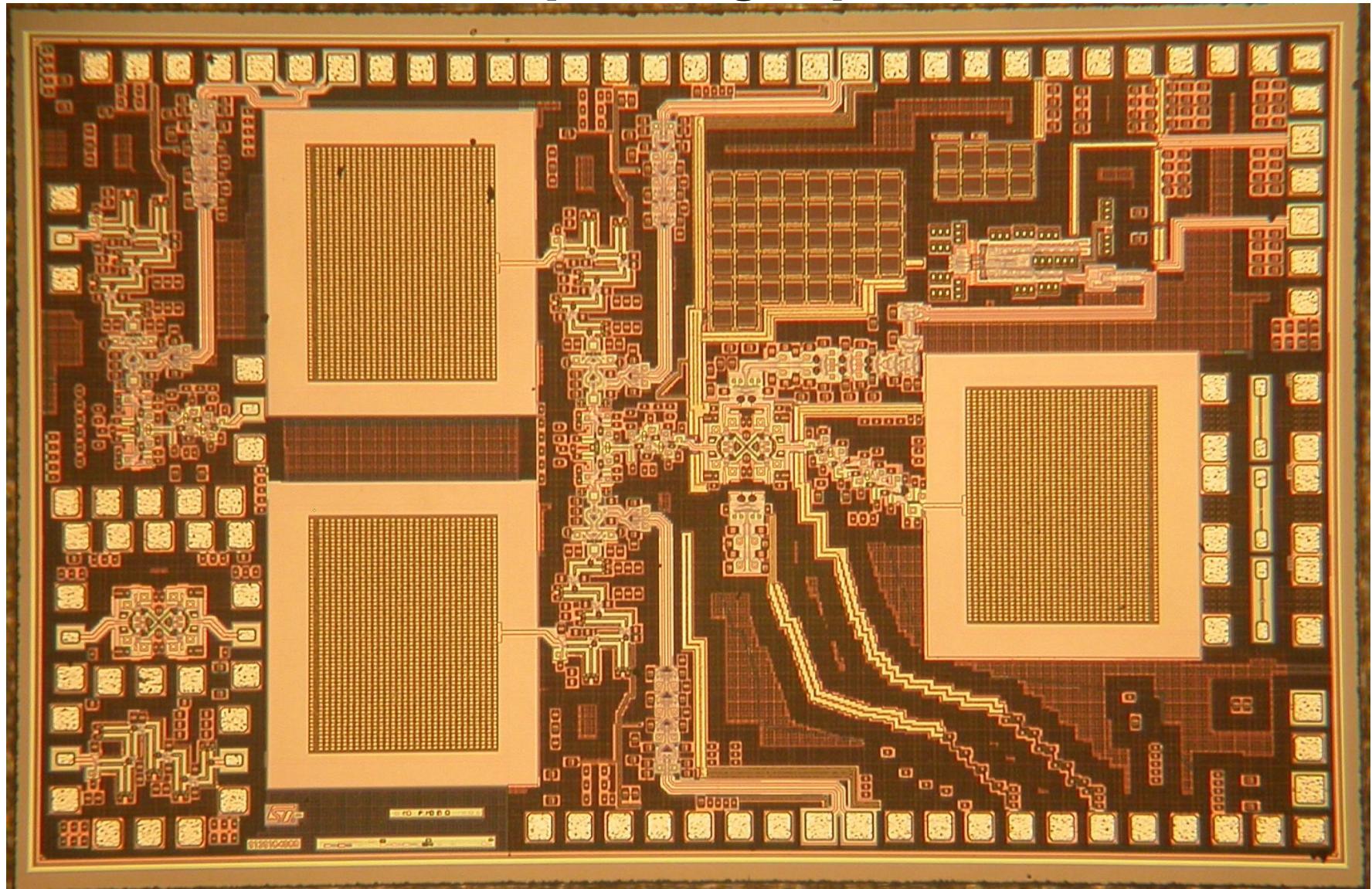


148-170 GHz Low Noise Amplifier



$P_D = 67 \text{ mW}$, Gain= 20 dB, NF < 12 dB.

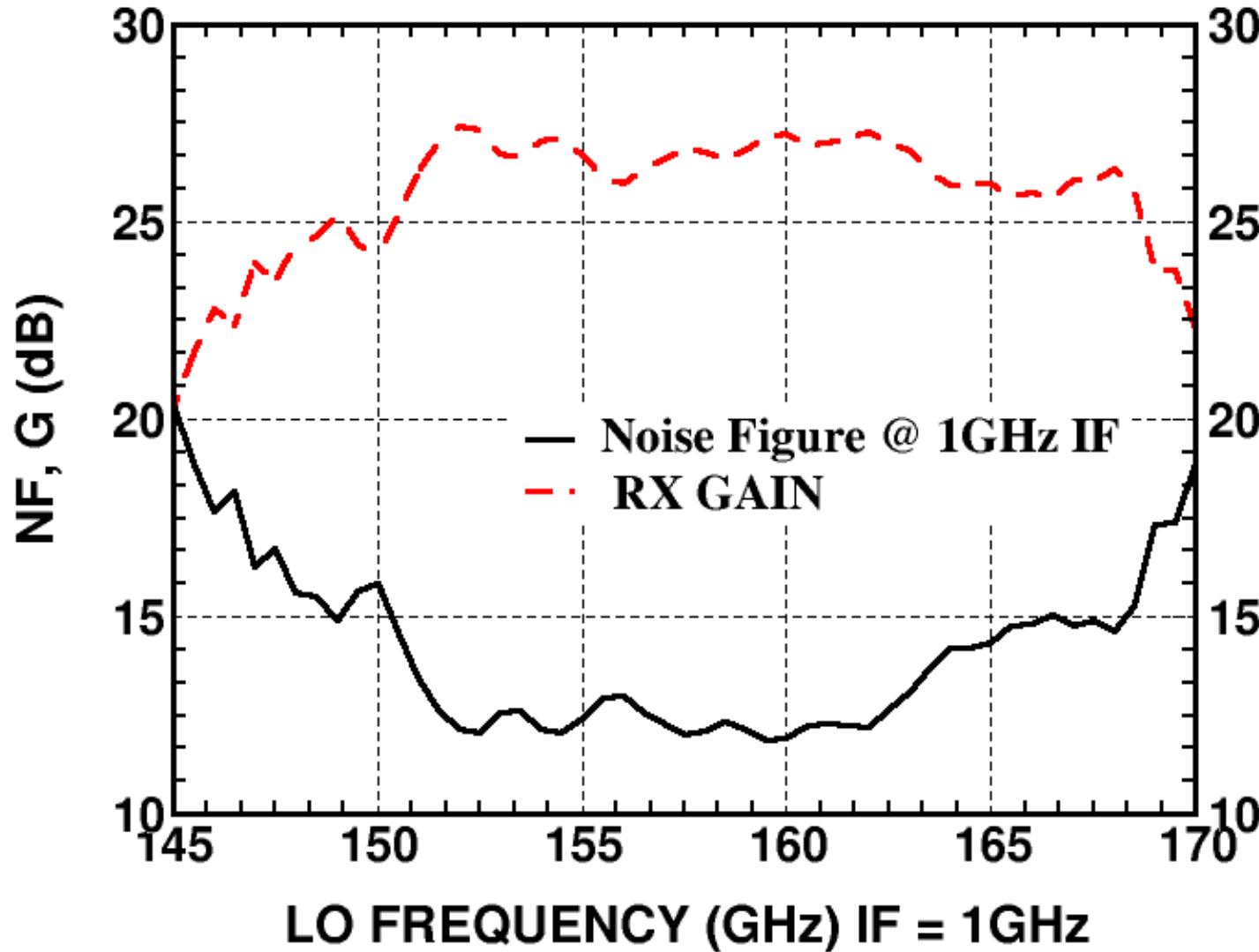
Die photograph



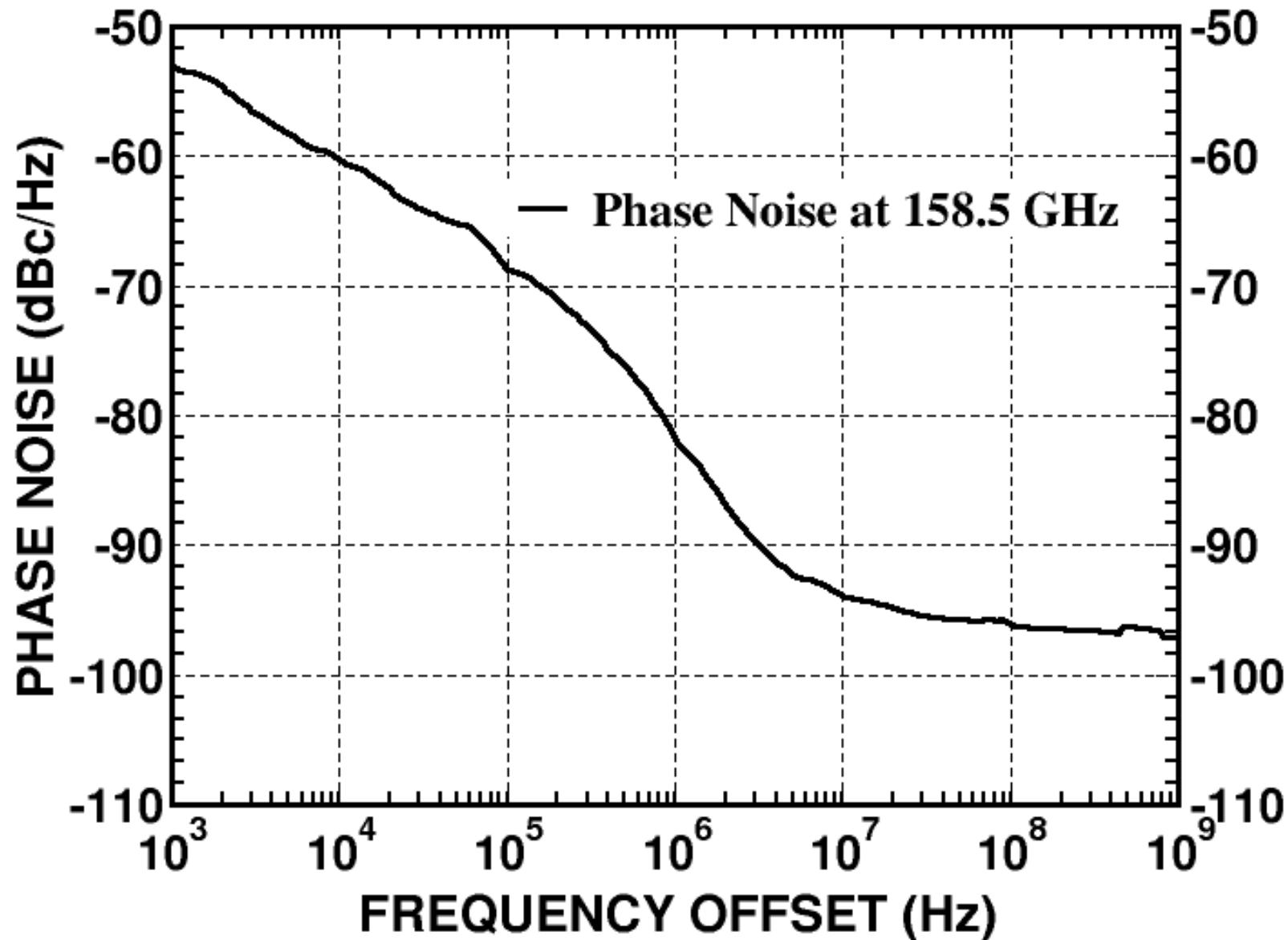
Chip: 2.1mm×2.9mm

130-nm BiCMOS9MW: SiGe HBT $f_T = 230$ GHz, $f_{MAX} = 280$ GHz

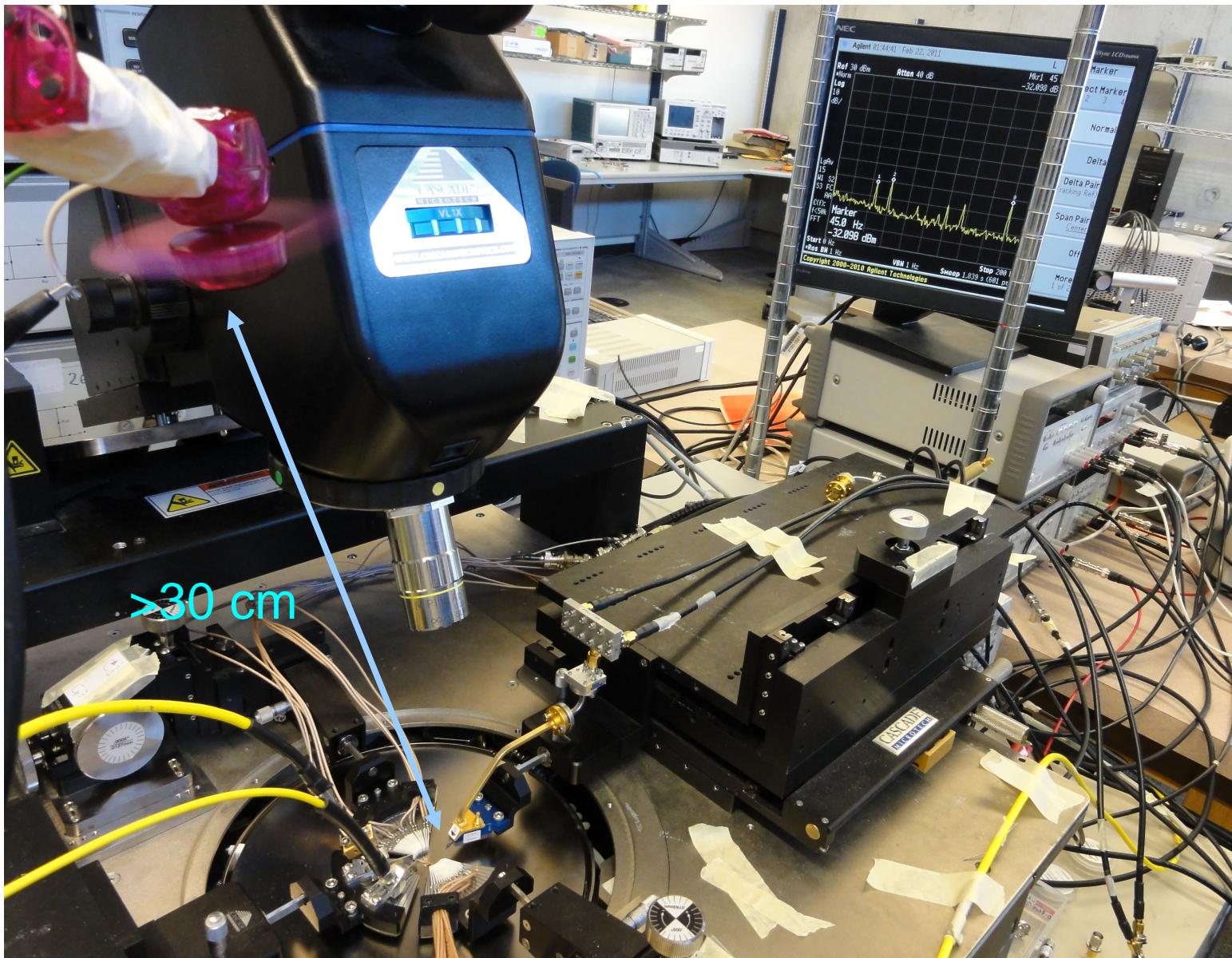
RX Breakout Gain and Noise Figure



Transceiver PLL Phase Noise

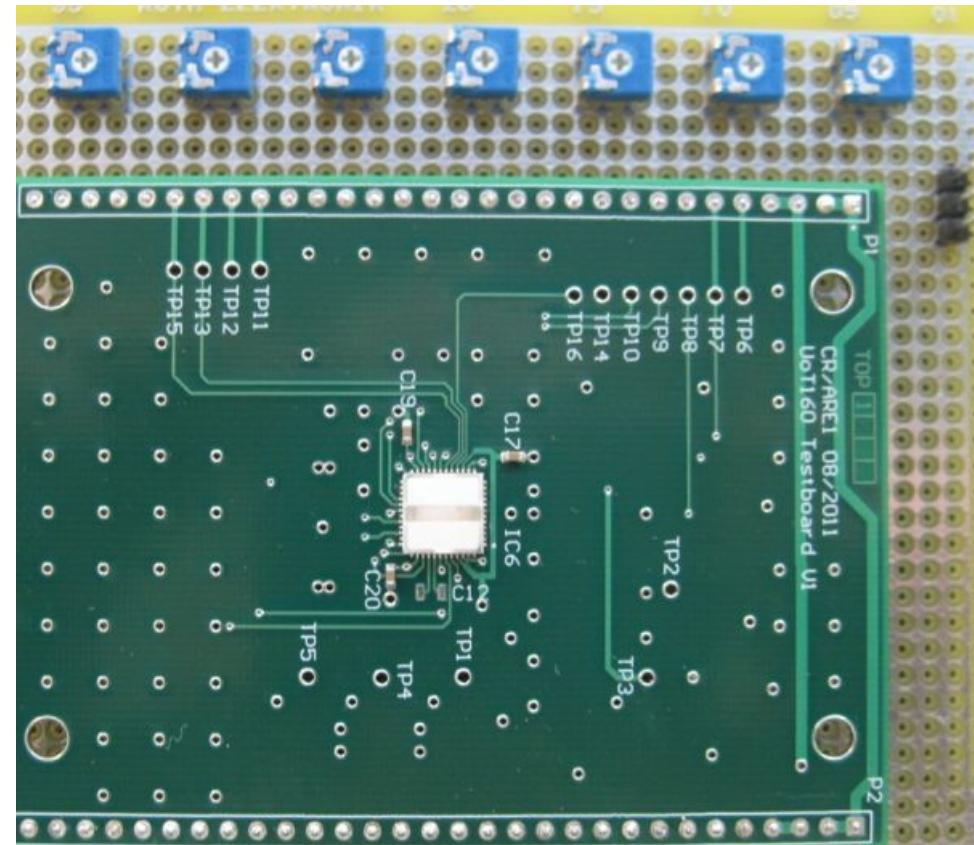
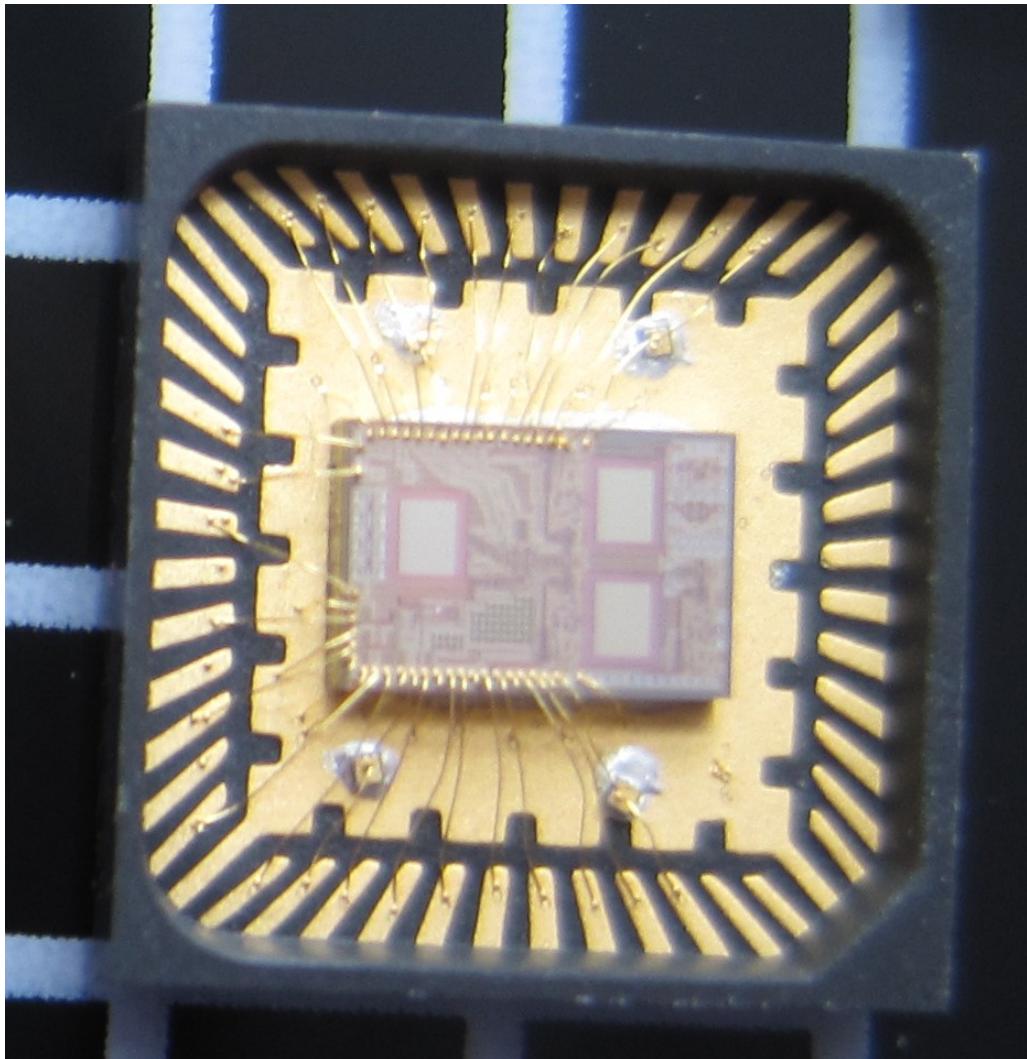


On-die Doppler Test



>30 cm

Packaging

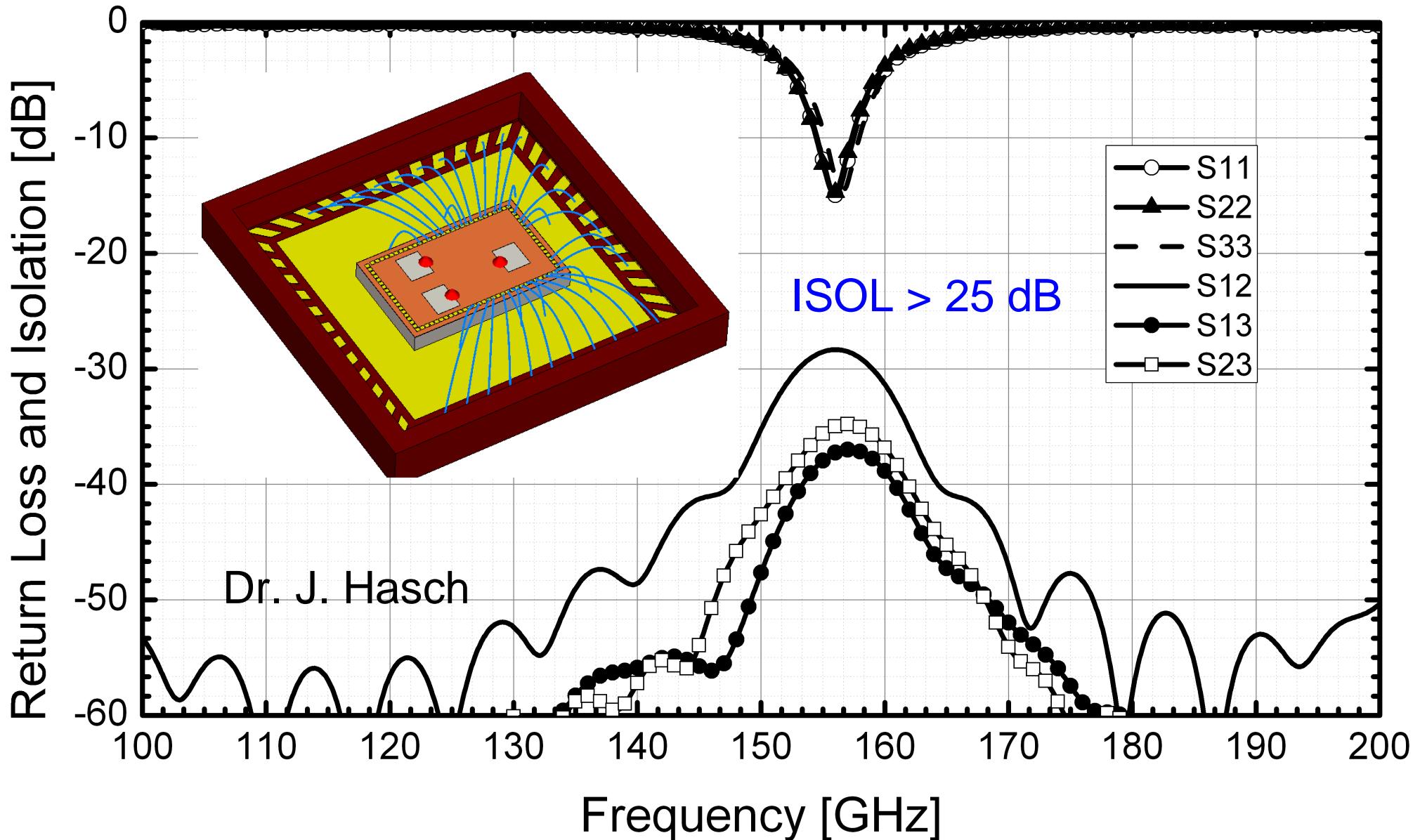


Dr. J. Hasch

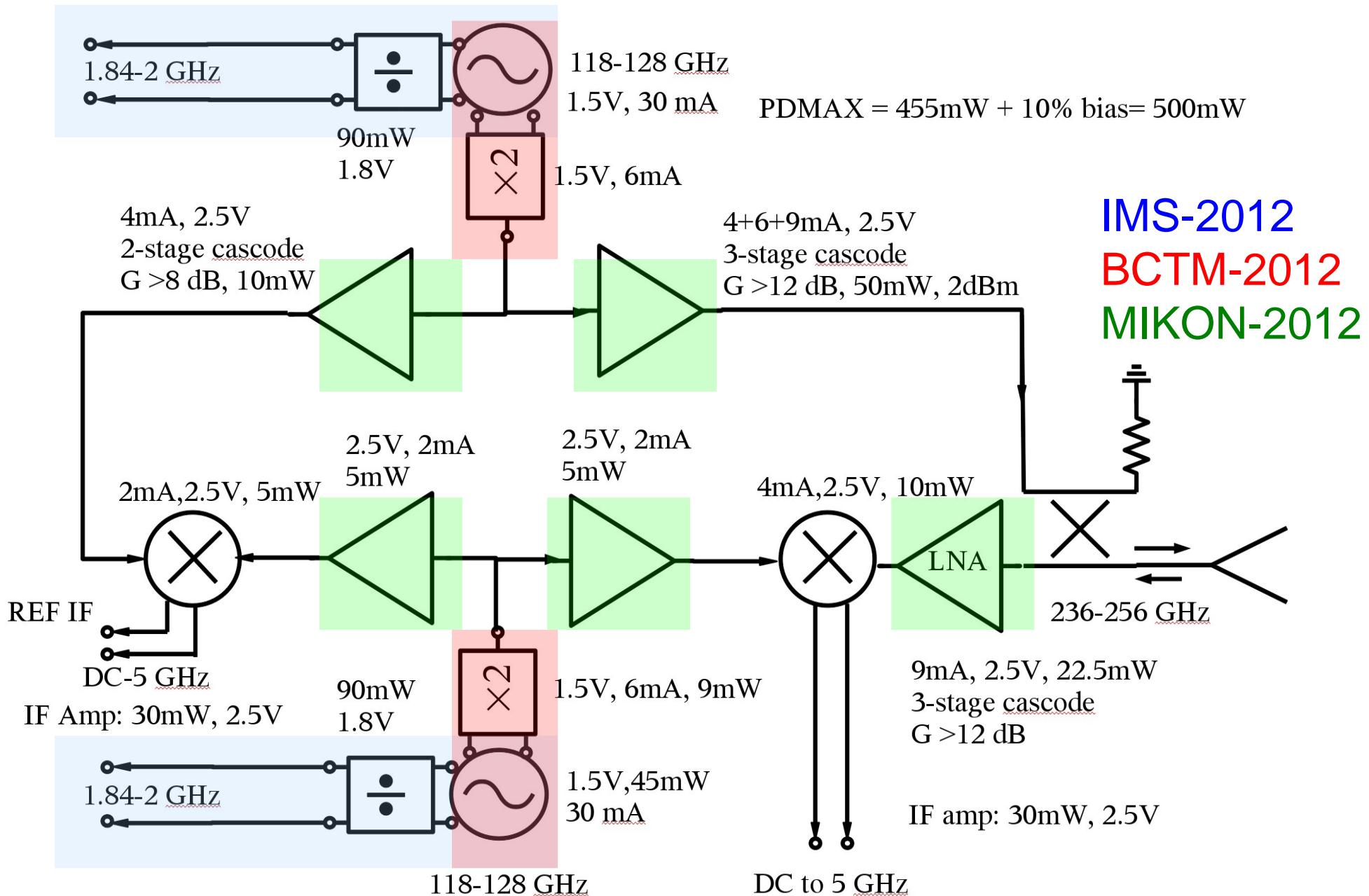


Sorin Voinigescu, October 12, 2012

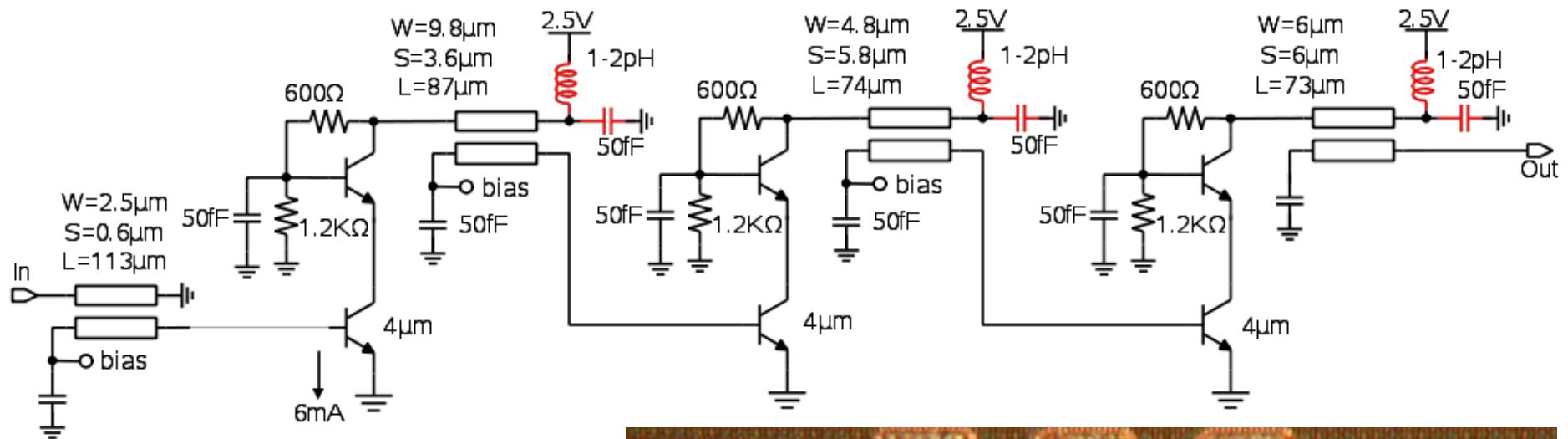
In-package Antennas Simulation



240-GHz Transceiver Blocks

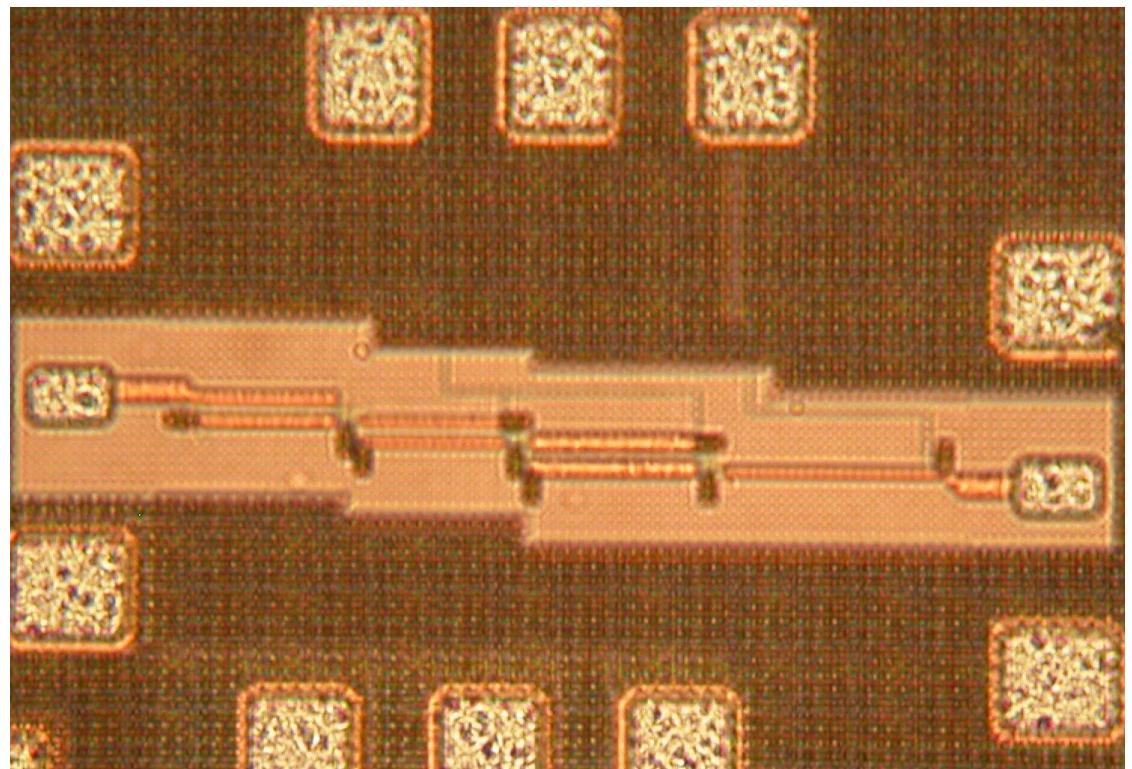


240-GHz Amplifier



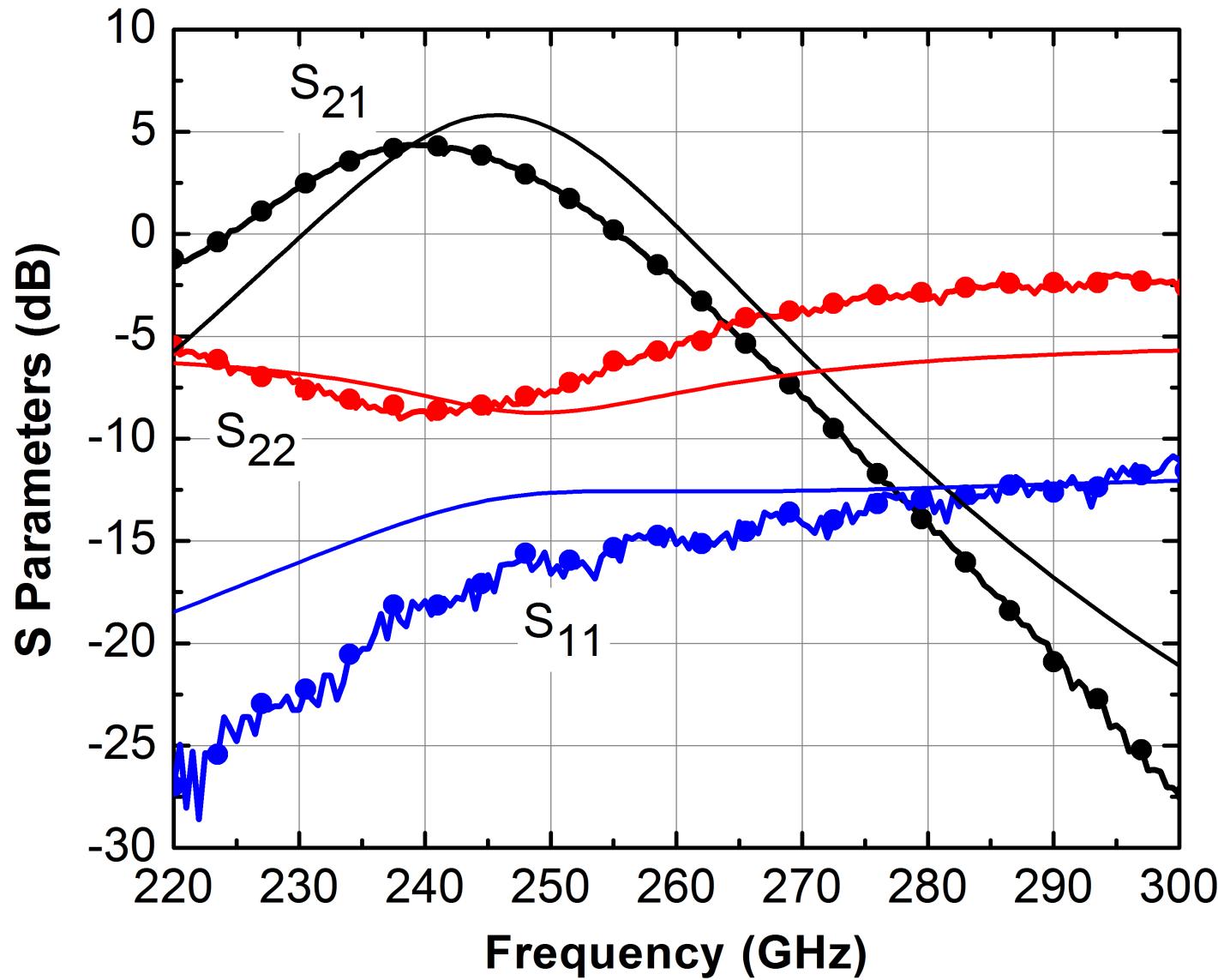
$$P_D = 37.5 \text{ mW}$$

$$G = 4.5 \text{ dB} @ 240 \text{ GHz}$$

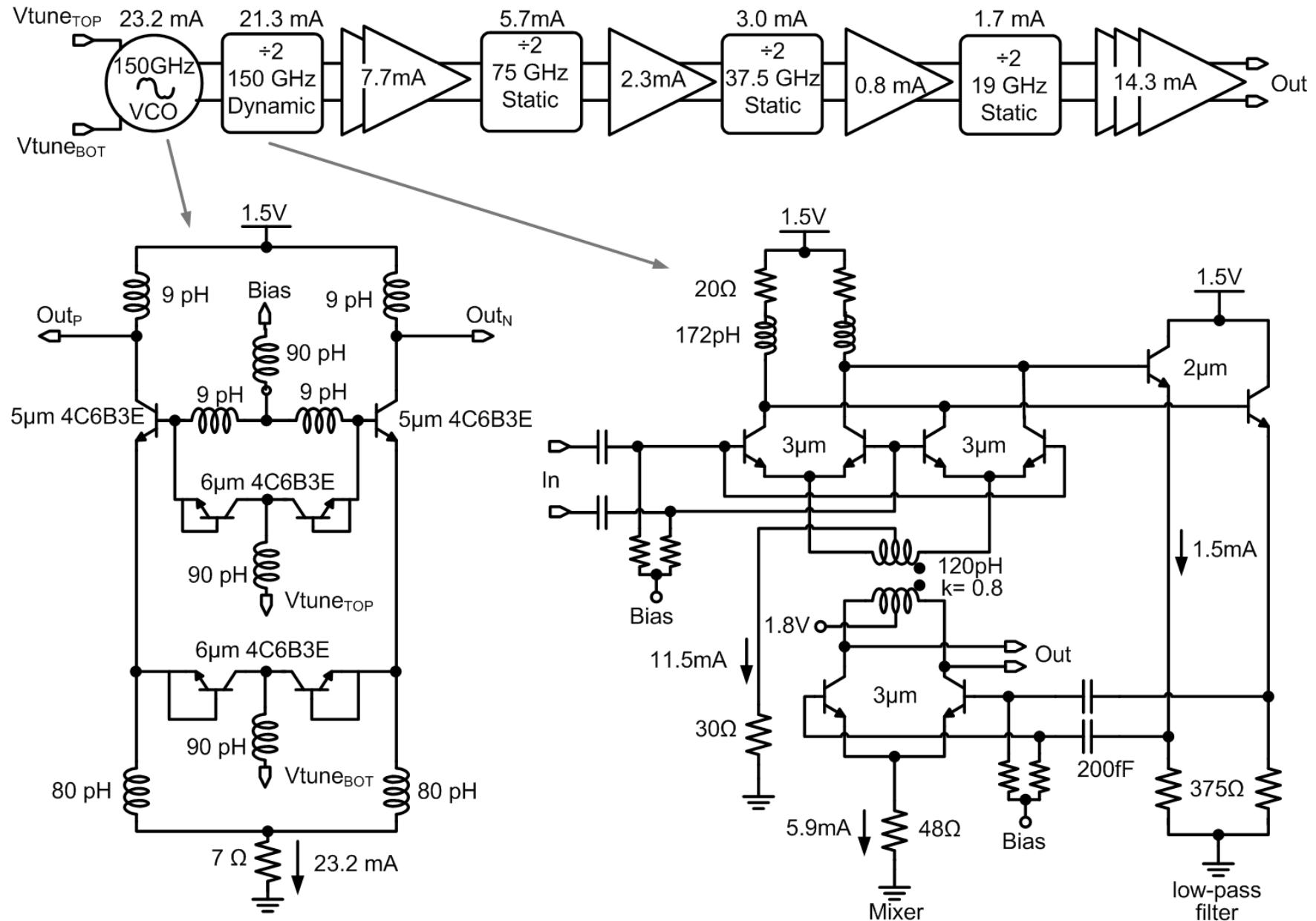


I. Sarkas et al, MIKON 2012

240-GHz Amplifier



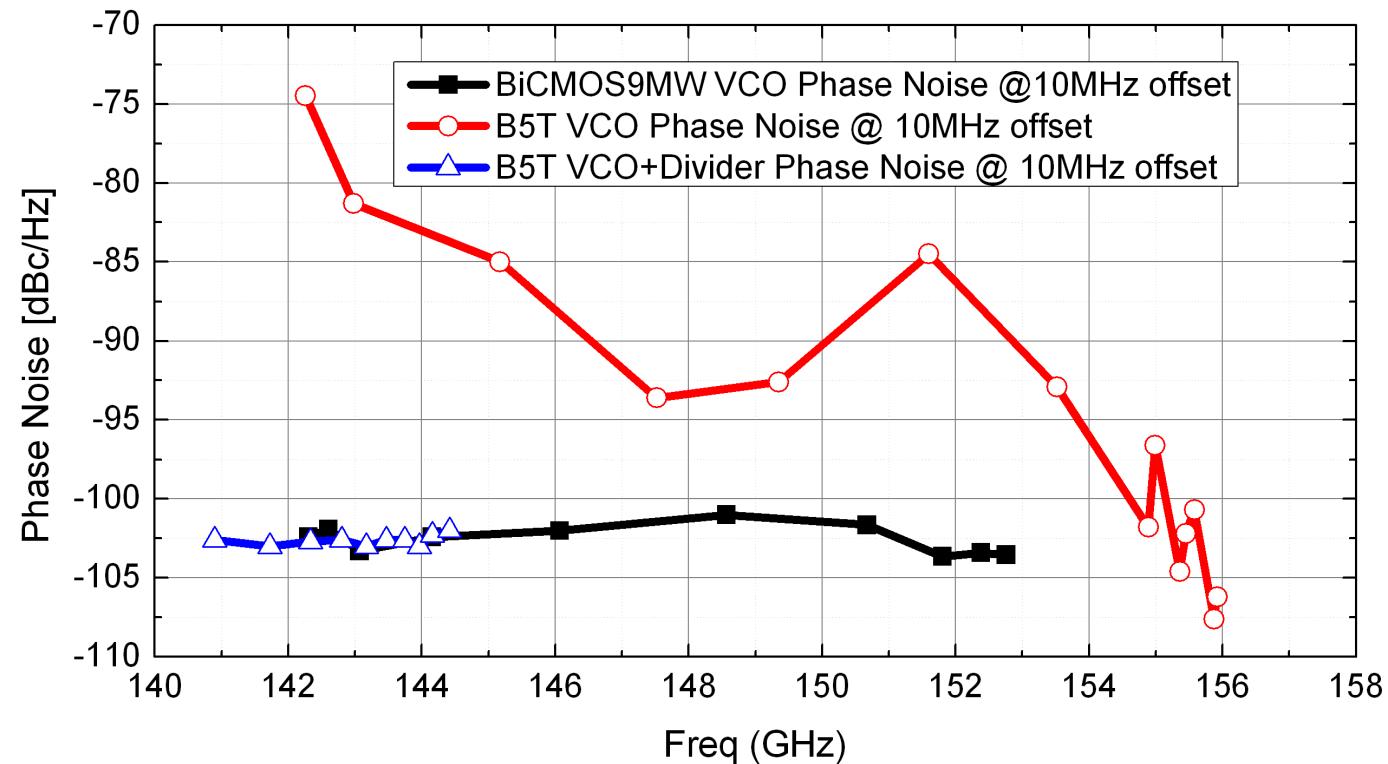
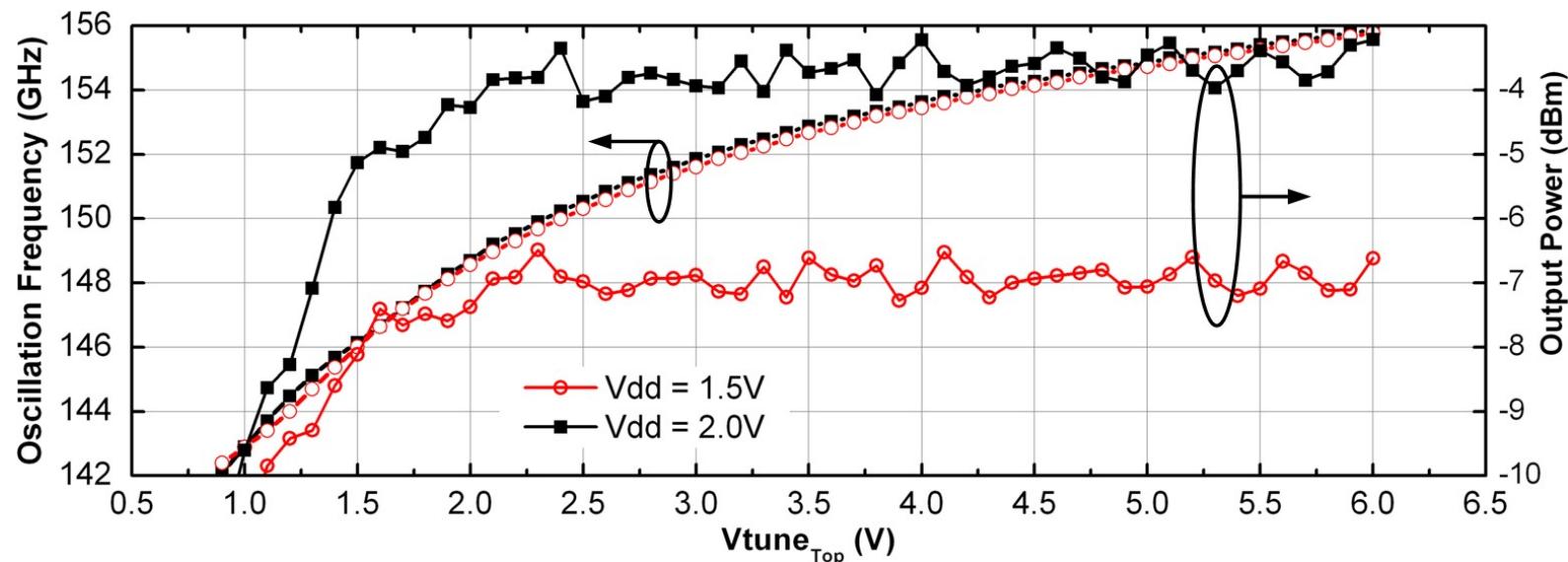
150-GHz VCO-prescaler



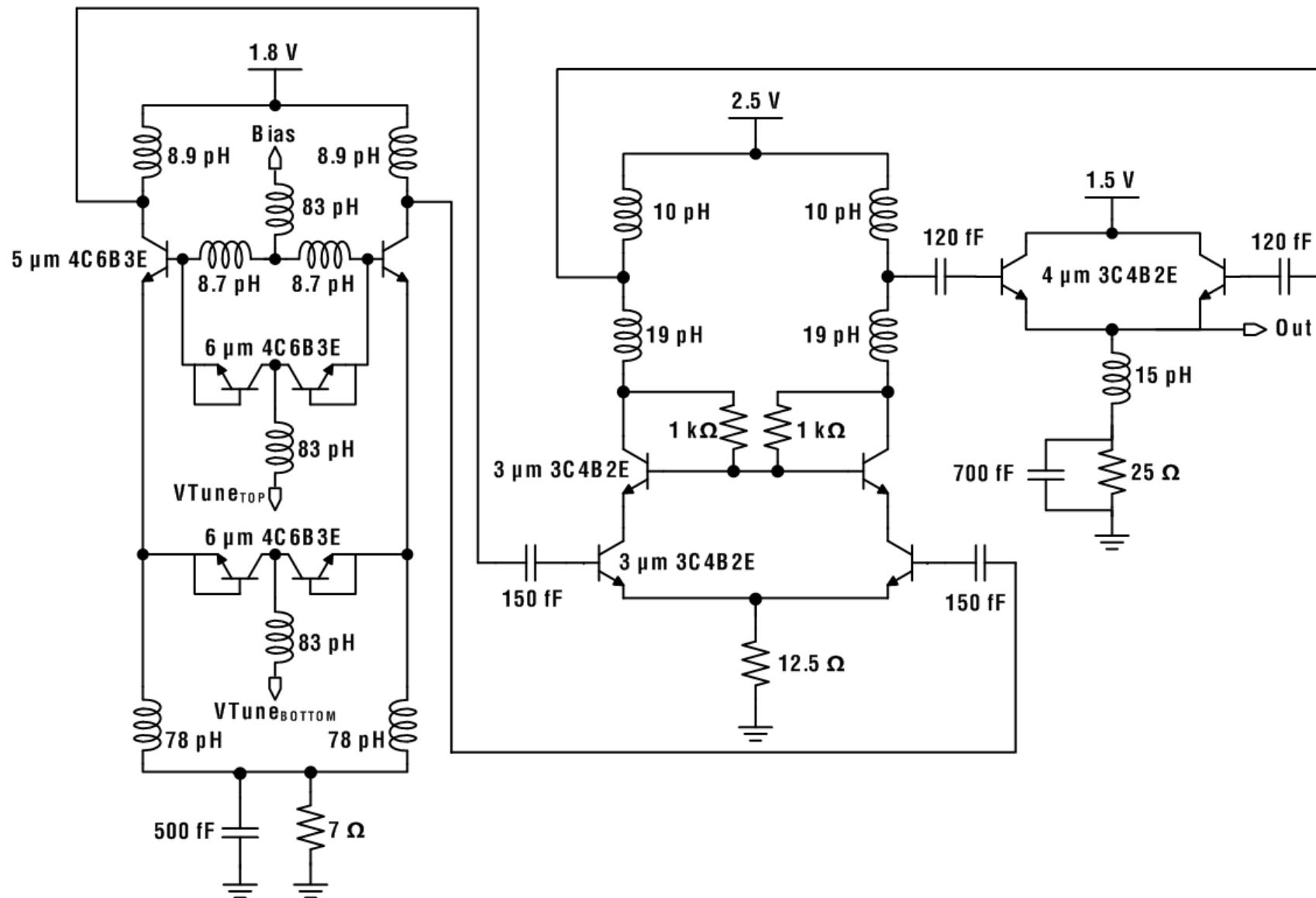
[A. Balteanu et al IMS 2012]

Sorin Voinigescu, October 12, 2012

Measurements



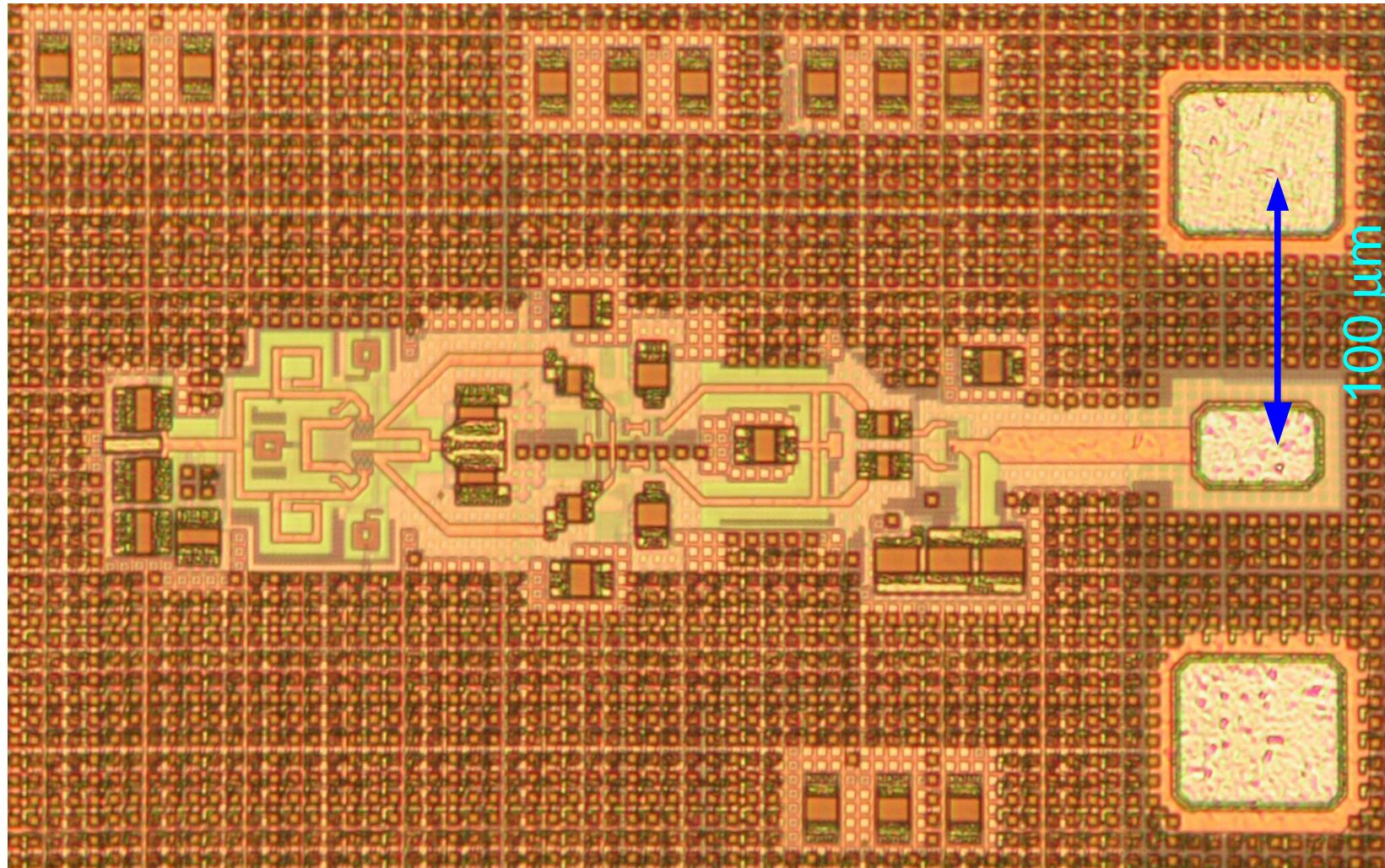
300-GHz VCO-Doubler



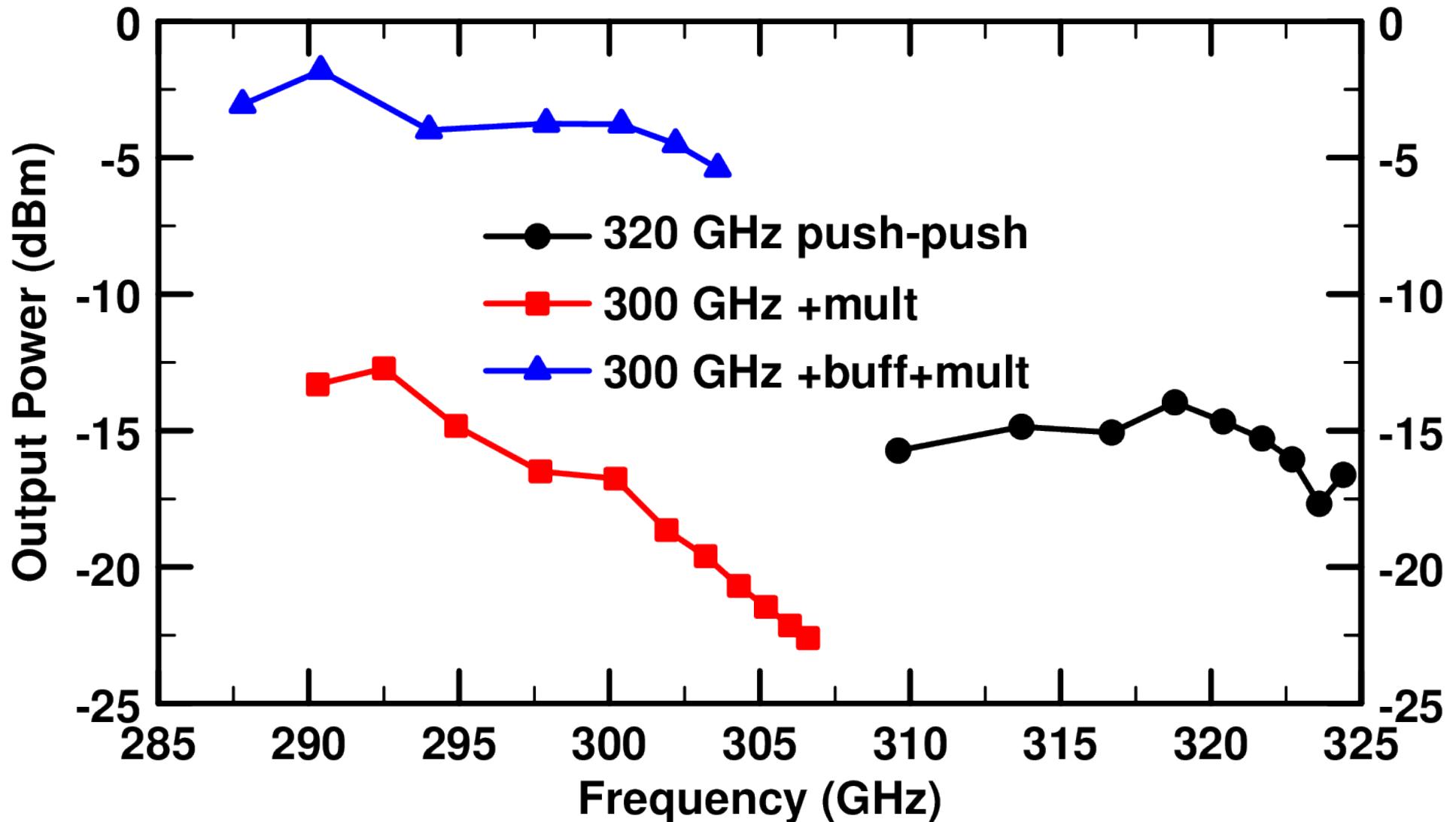
A. Tomkins et al., BCTM 2012

Sorin Voinigescu, October 12, 2012

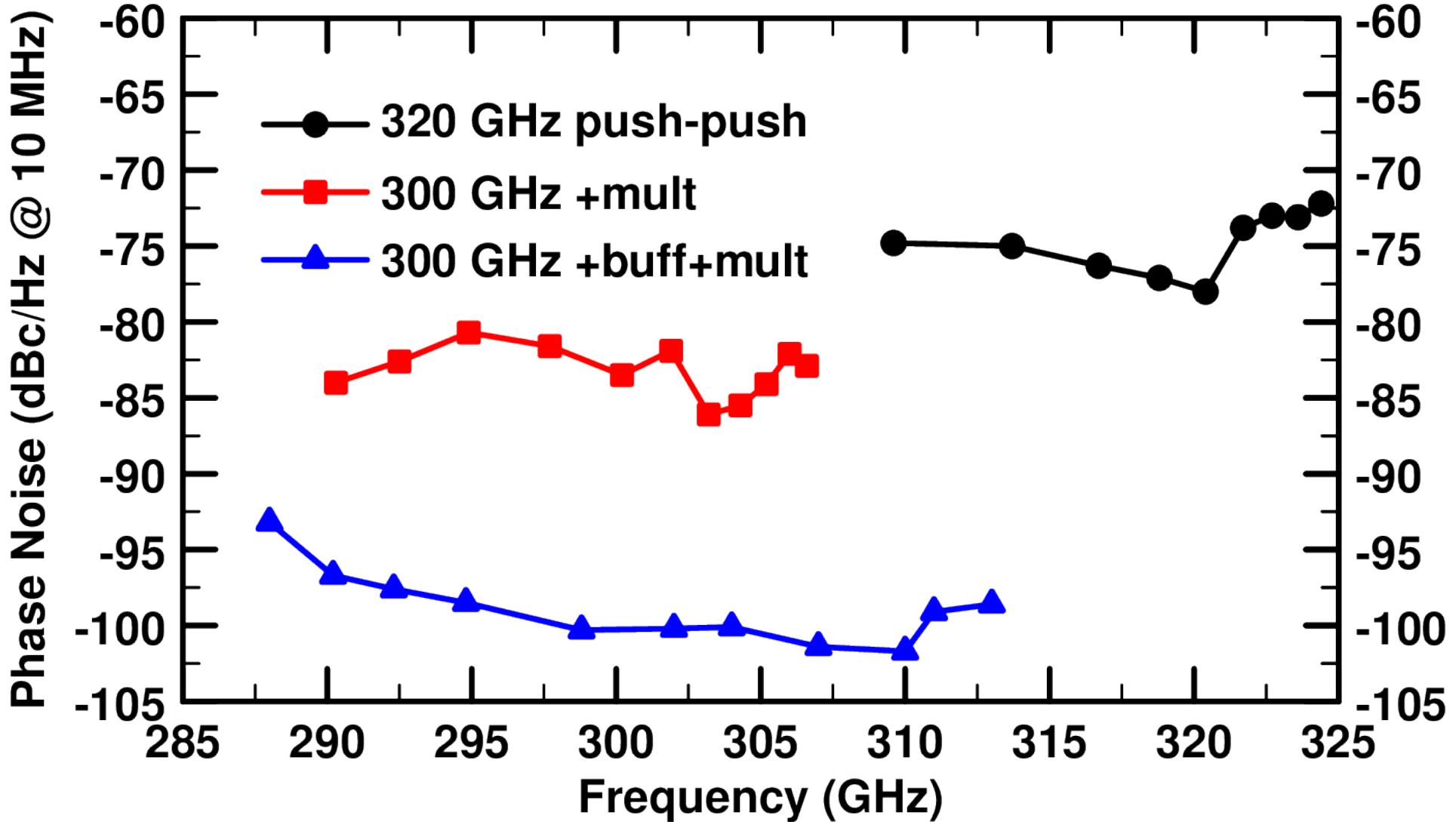
Layout



300-GHz Signal Source Comparison

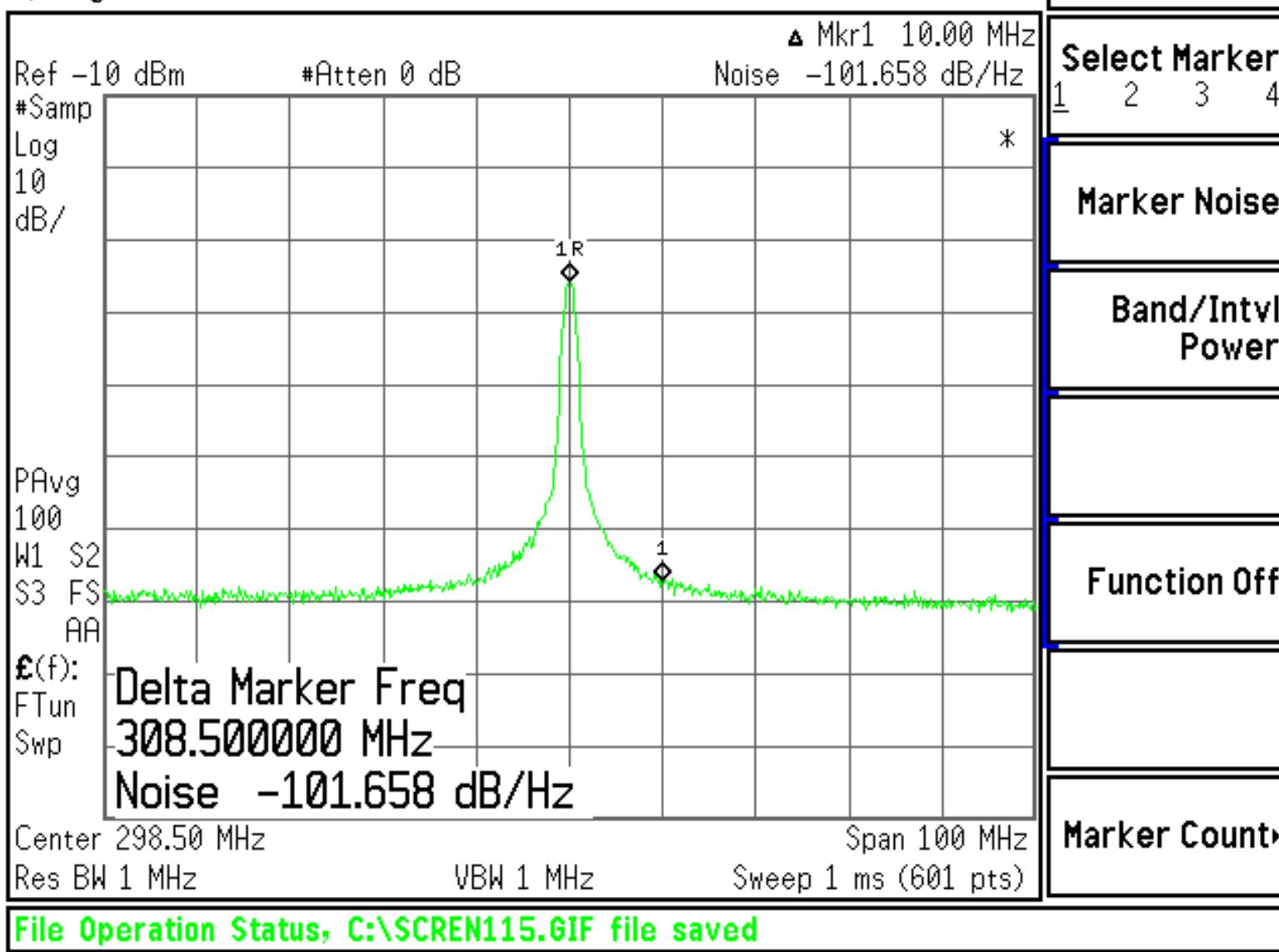


300-GHz Signal Source Comparison (ii)

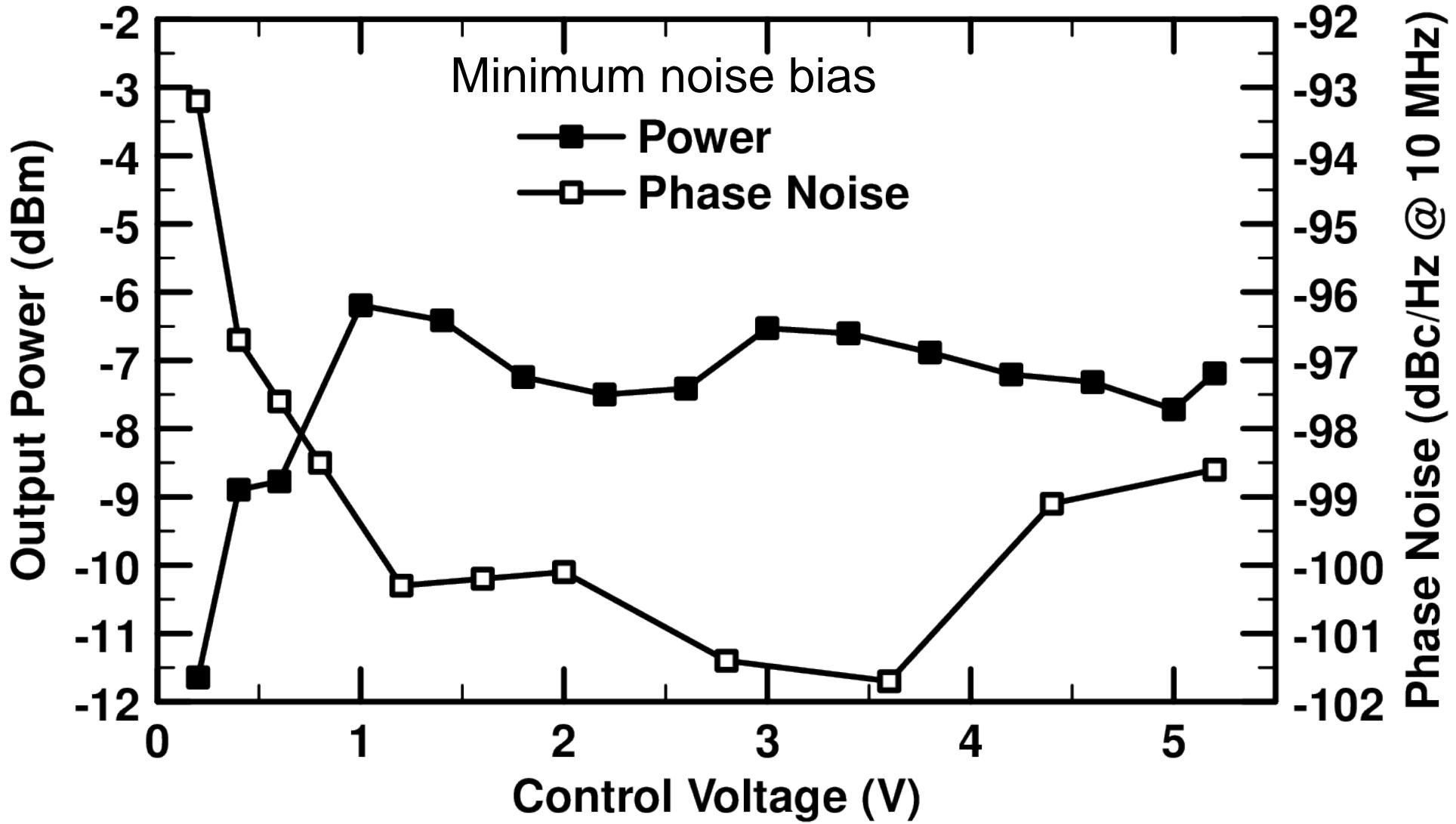


Phase Noise of VCO-doubler at 309 GHz

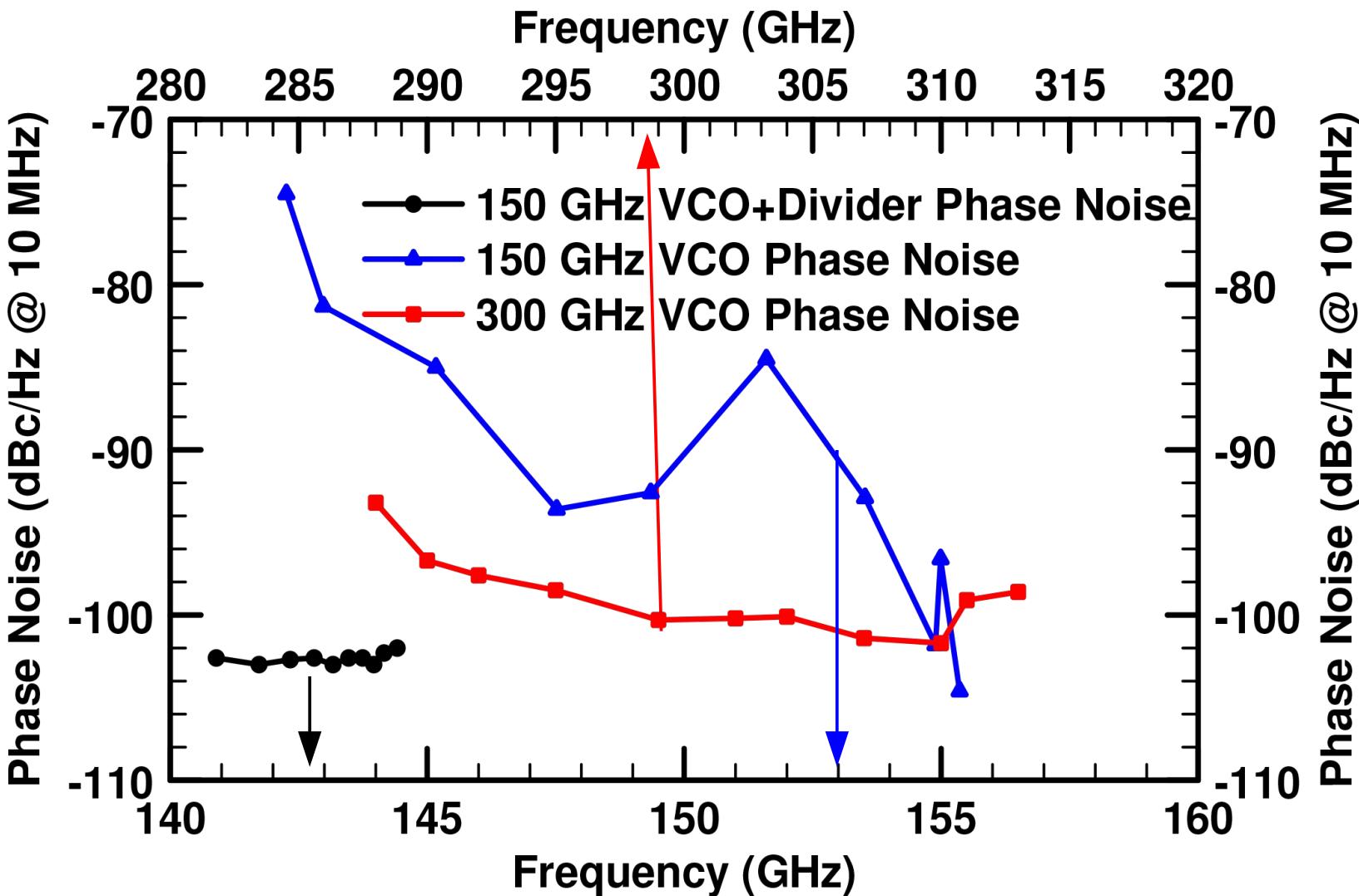
* Agilent 09:50:55 Feb 2, 2012



Measured Pout and Phase Noise 300-GHz VCO+buffer+doubler



300-GHz vs. 150-GHz Phase Noise

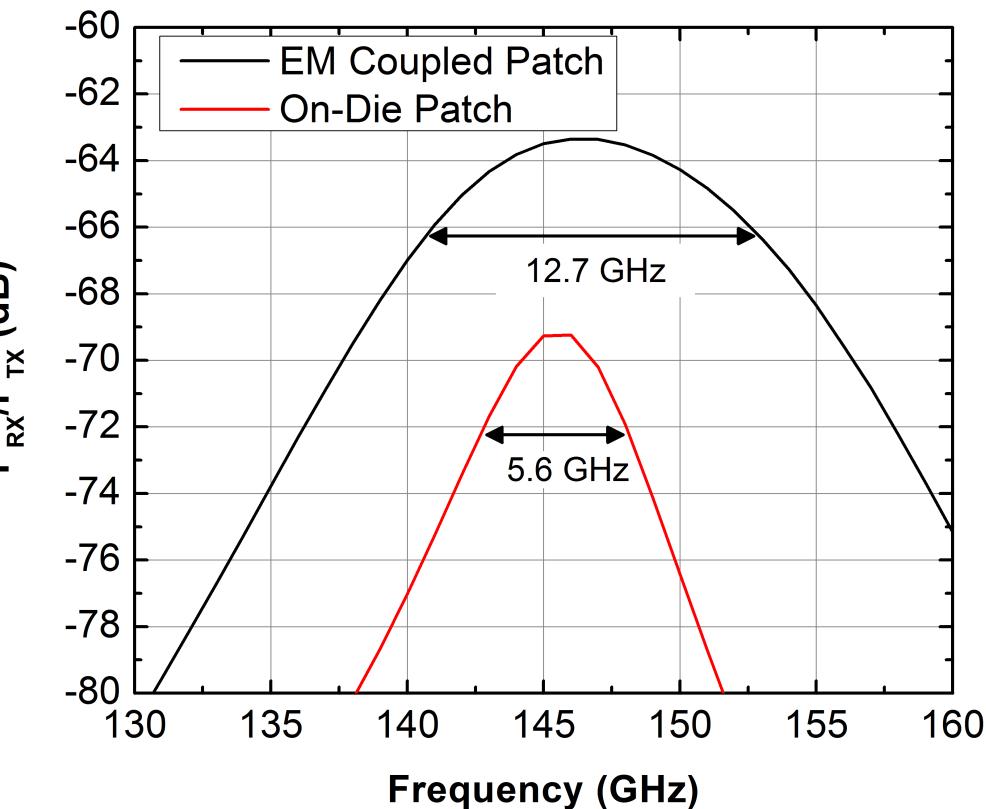
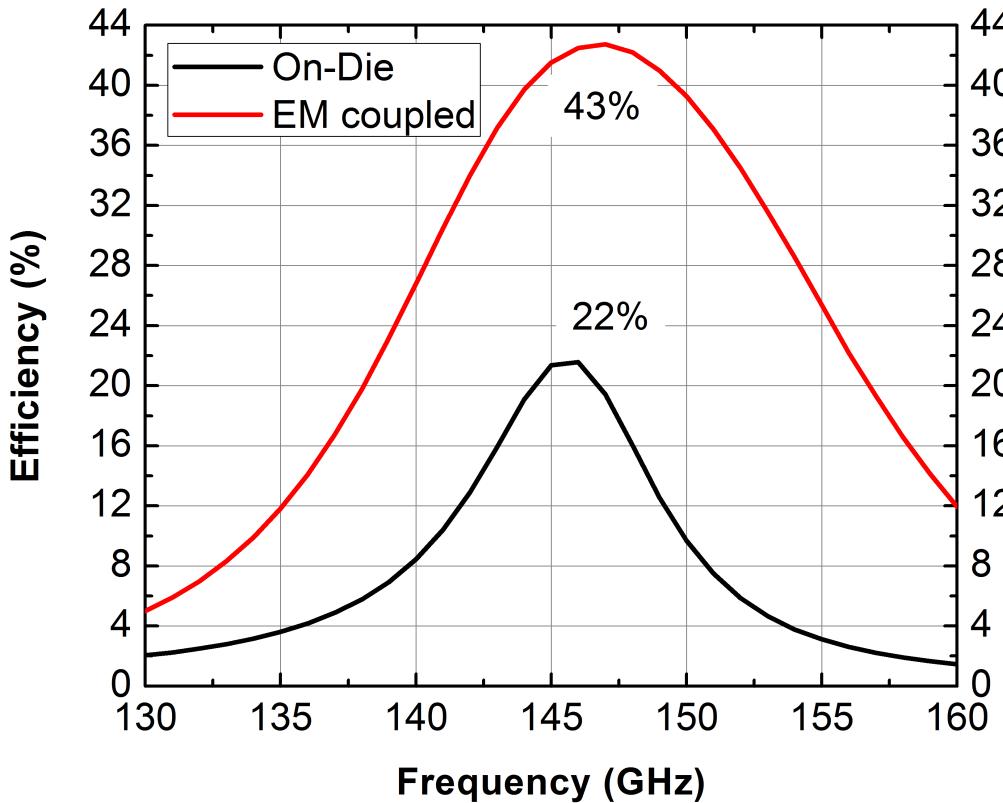


SAME VCO in BOTH!

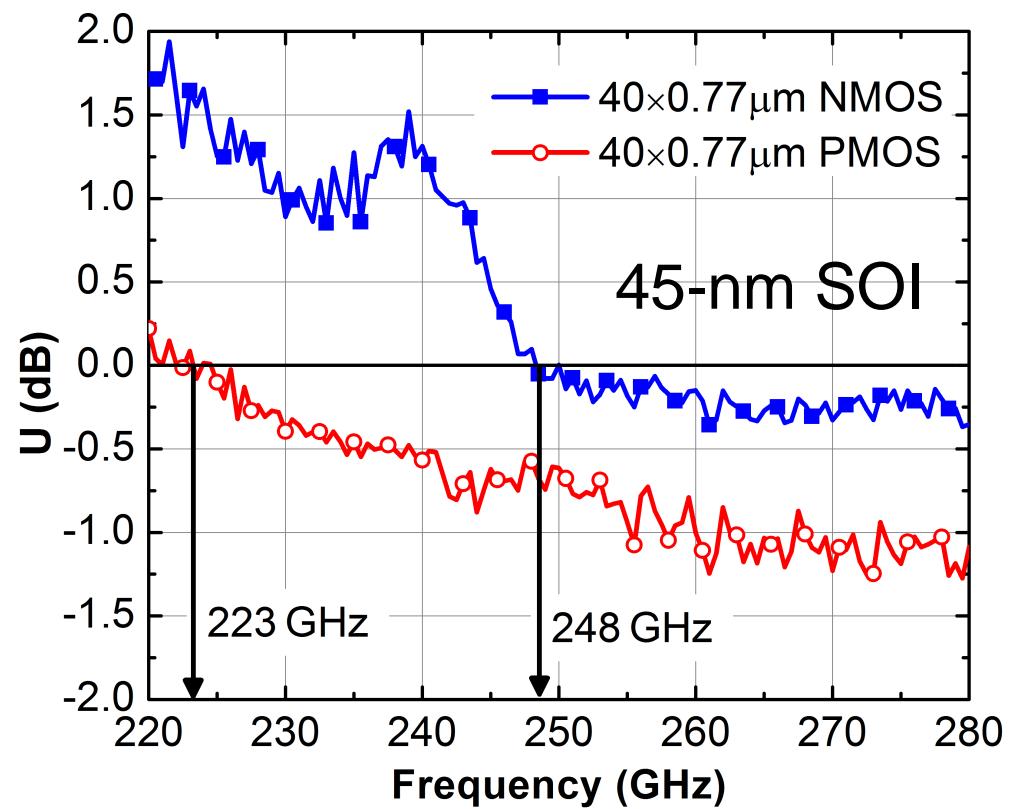
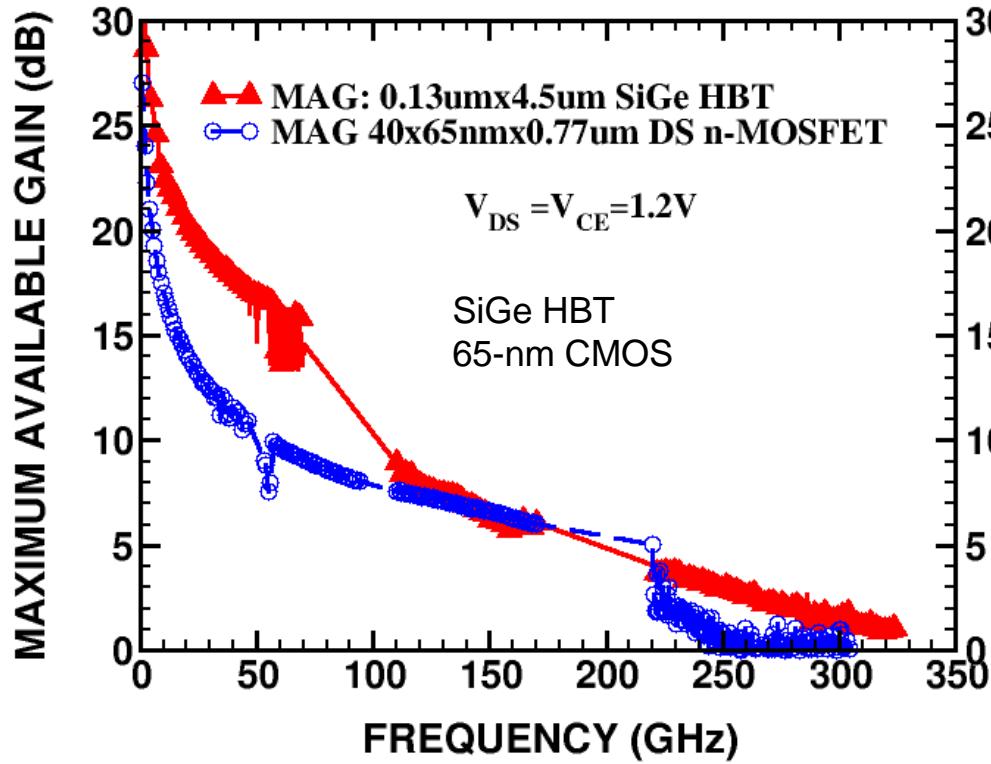
Conclusions

- Why?
 - ◆ Because we can!
 - ◆ “Cloud” unsustainable without 10x speed and 100x efficiency improvement
 - ◆ Need 1Tb/s for near field and intra data center comms
- How?
 - ◆ 50-100 Gb/s inductively peaked CMOS logic
 - ◆ Mm-wave Power-DAC Transmitter
 - ◆ H-Band SoCs with on-die antennas
 - ◆ Low-cost QFN package

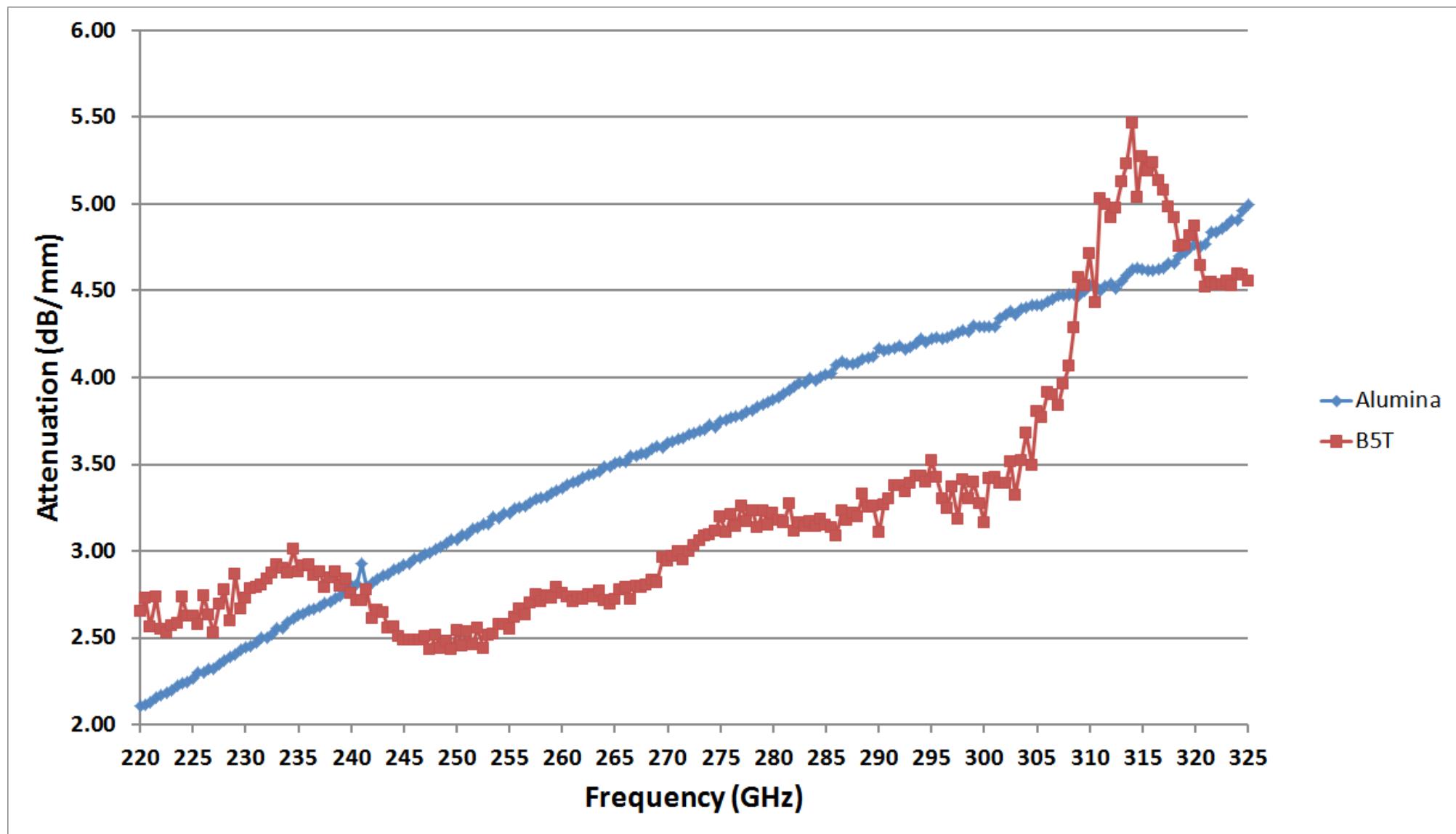
Antenna Efficiency & Bandwidth



Si Transistor Performance at H-Band



SiGe vs. Alumina μ strip-lines: H-Band

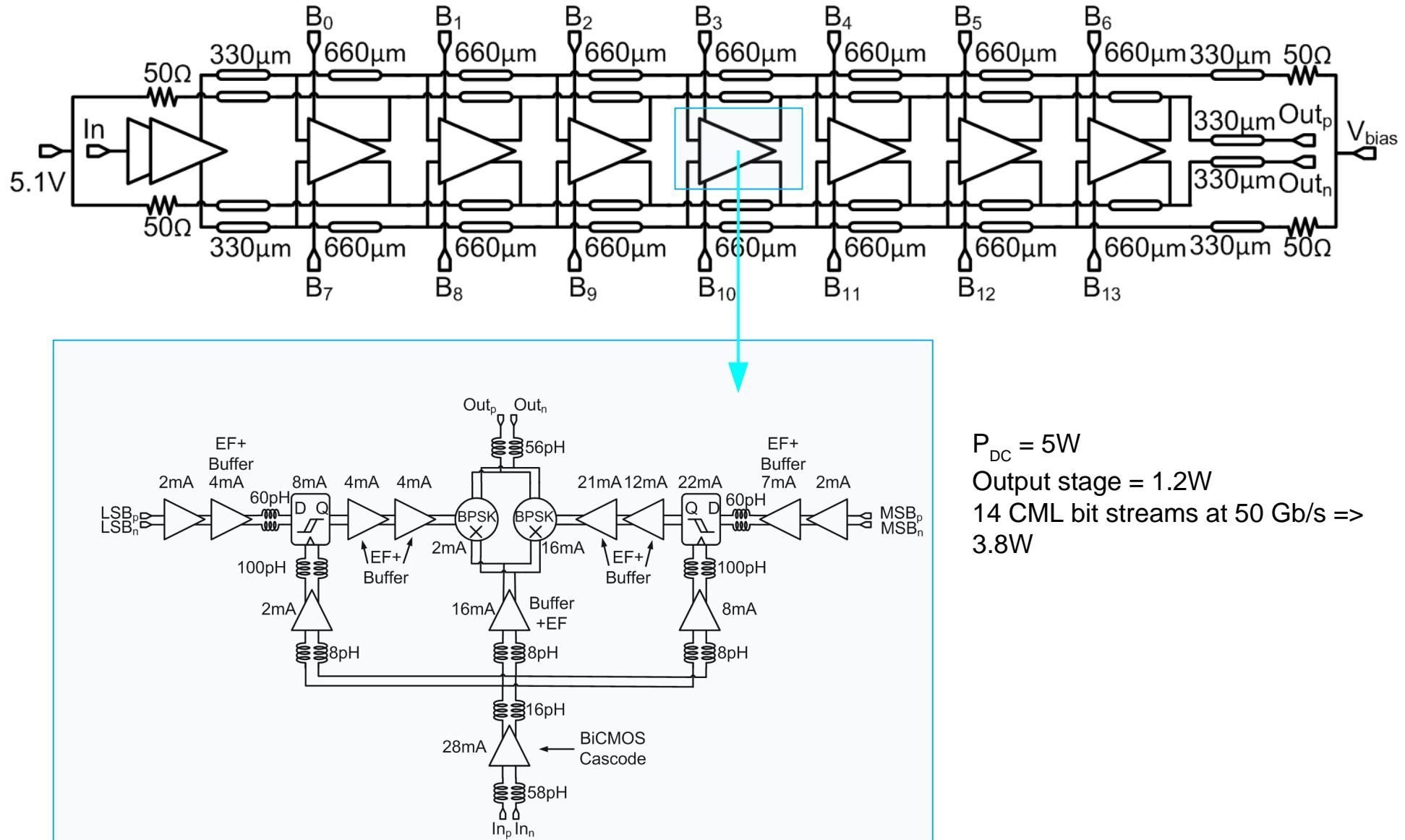


50-GS/s 6-bit Fully Segmented RZ-DAC 3Vpp swing per side

A. Balteanu et al. IMS 2012

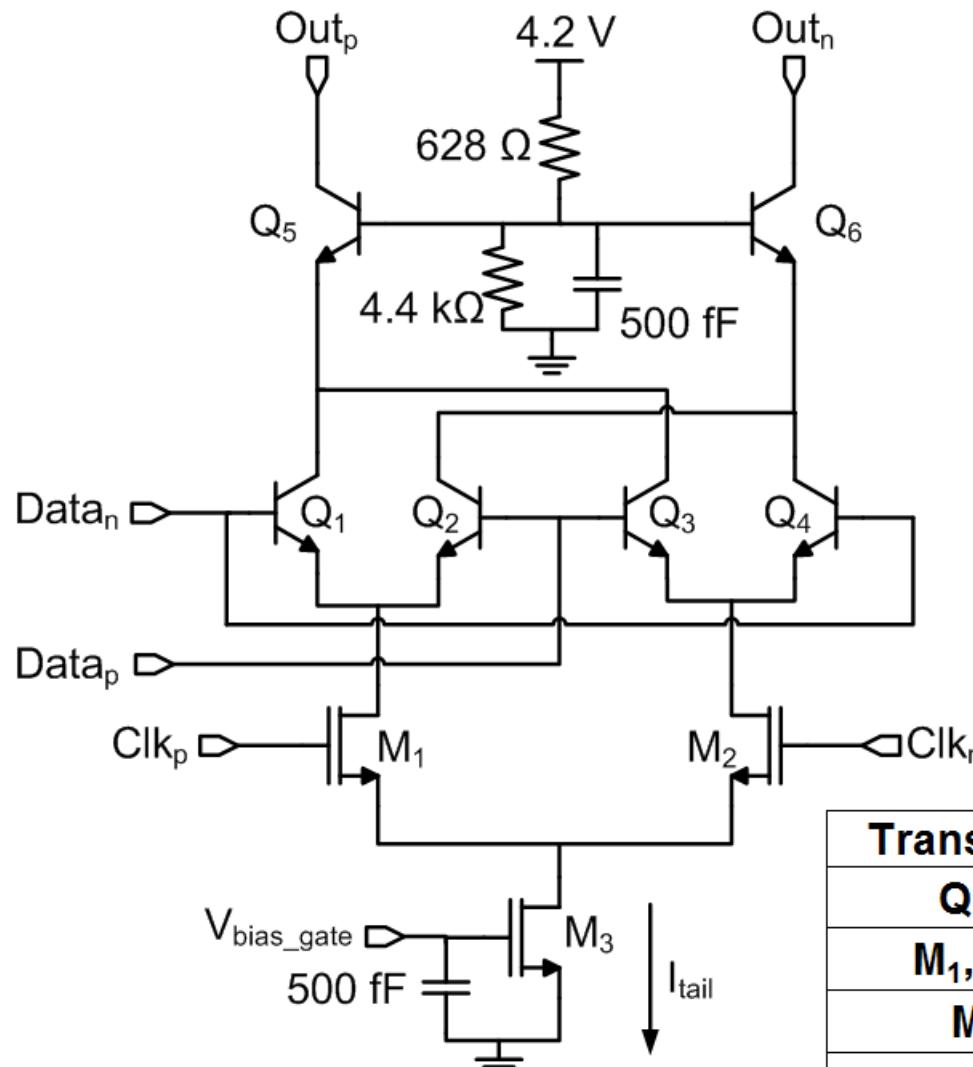


Block Diagram



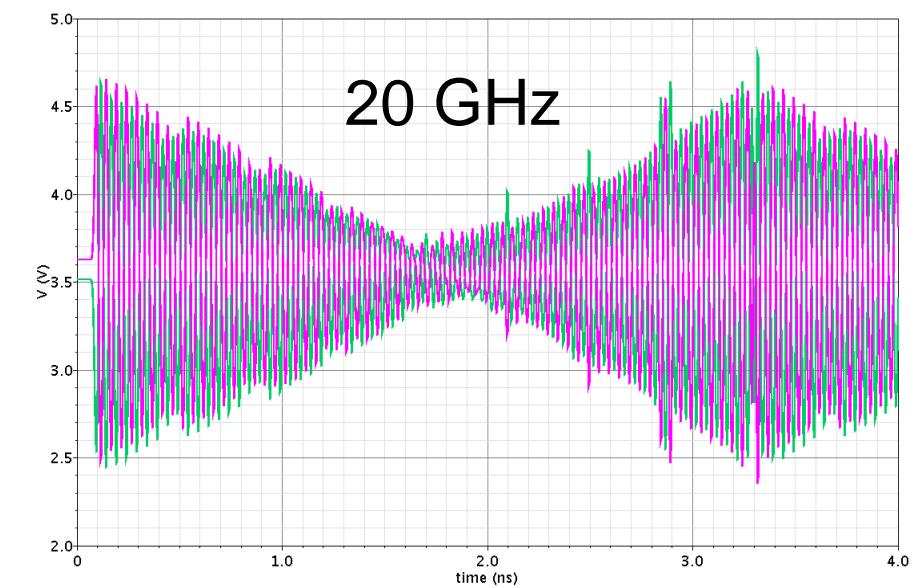
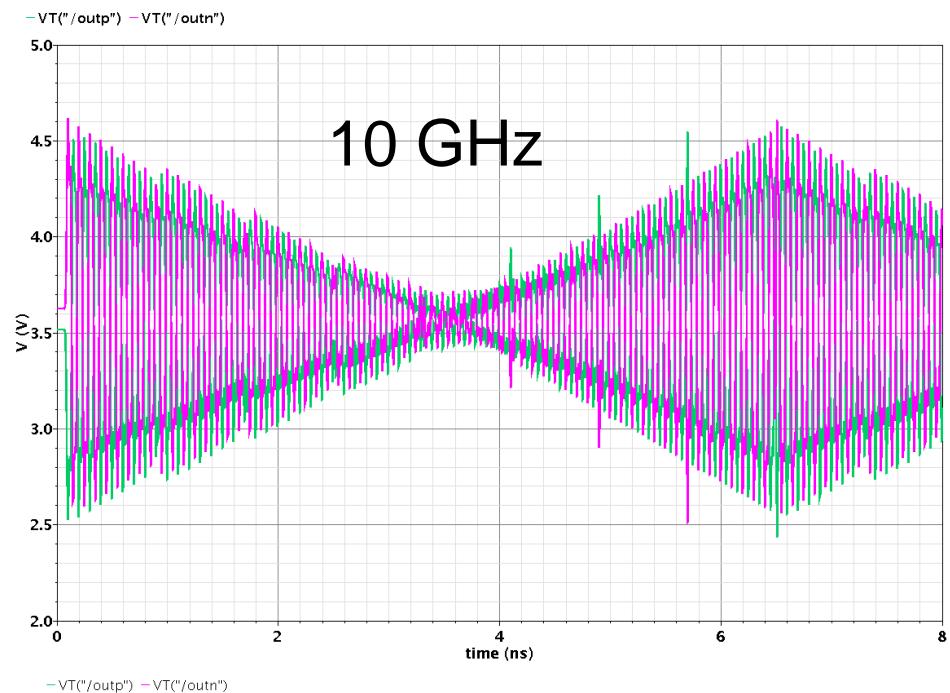
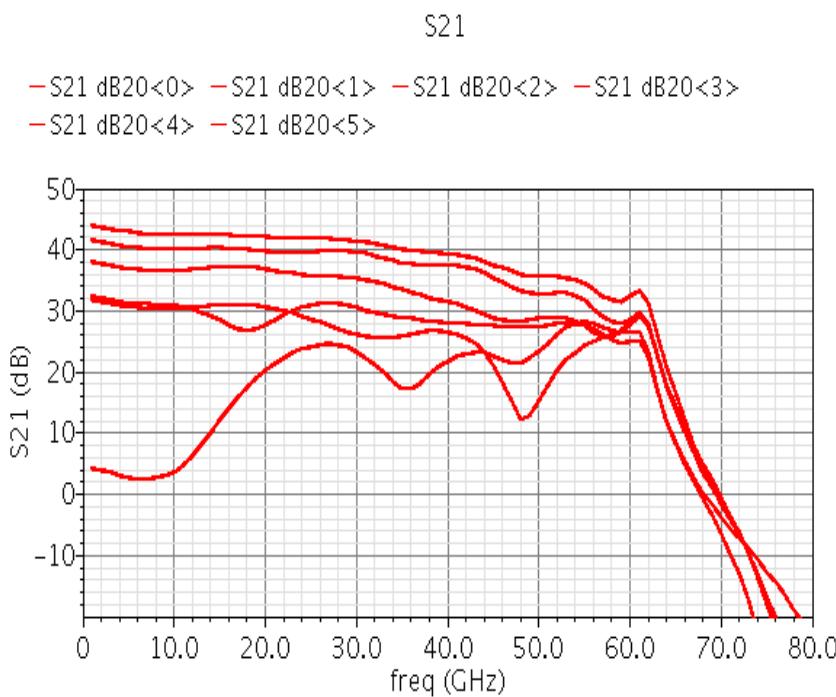
- Distributed Segmentation: 7 MSBs and 7 LSBs in 8:1 size ratio
- Each bit retimed at up to 50 GHz

BPSK Cell Schematics

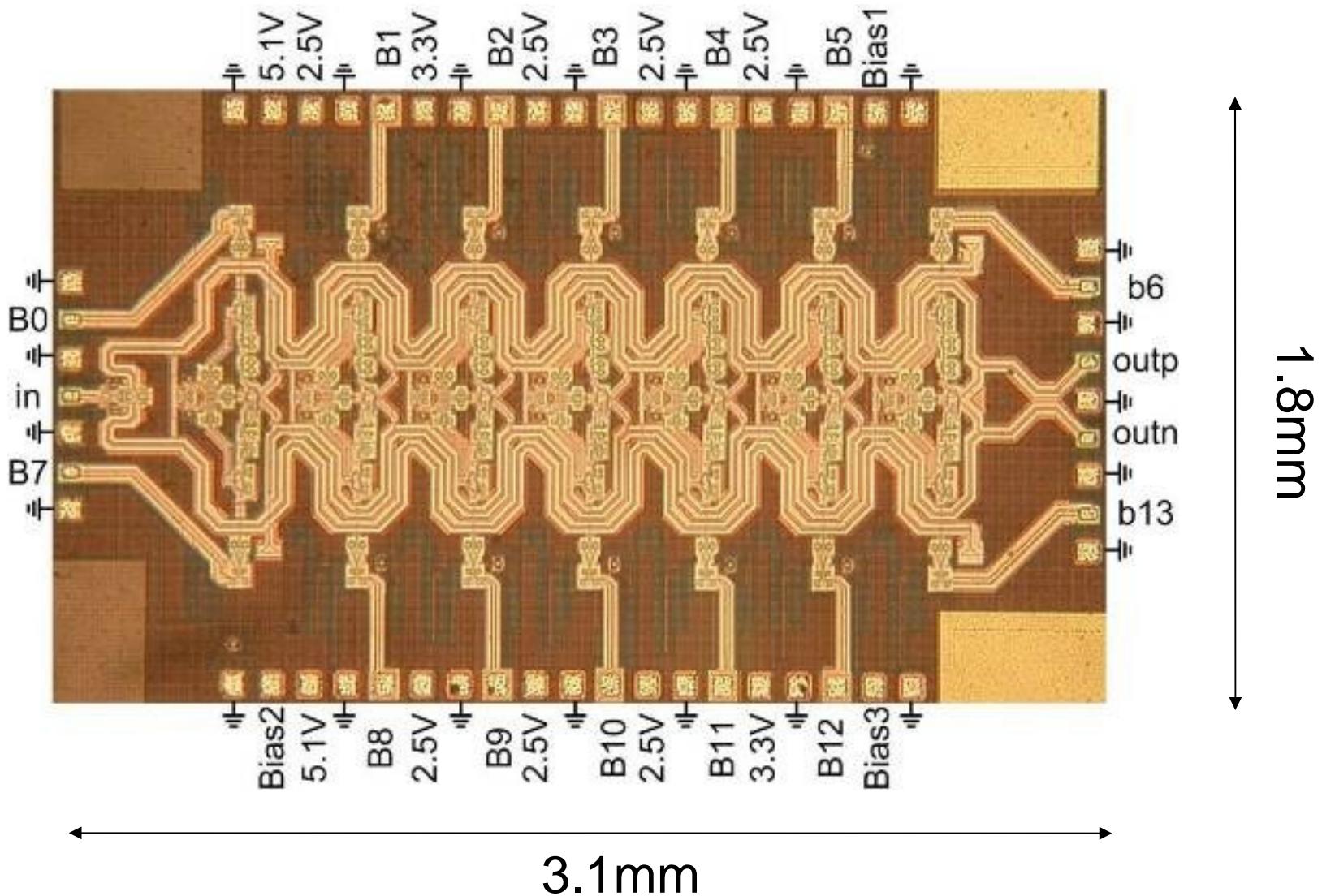


Transistor	LSB	MSB
Q₁₋₆	1 μm	4×2 μm
M₁, M₂	3×2 μm	24×2 μm
M₃	5×4 μm	40×4 μm
I_{tail}	2 mA	16 mA

Distributed Power DAC Simulations (V2)

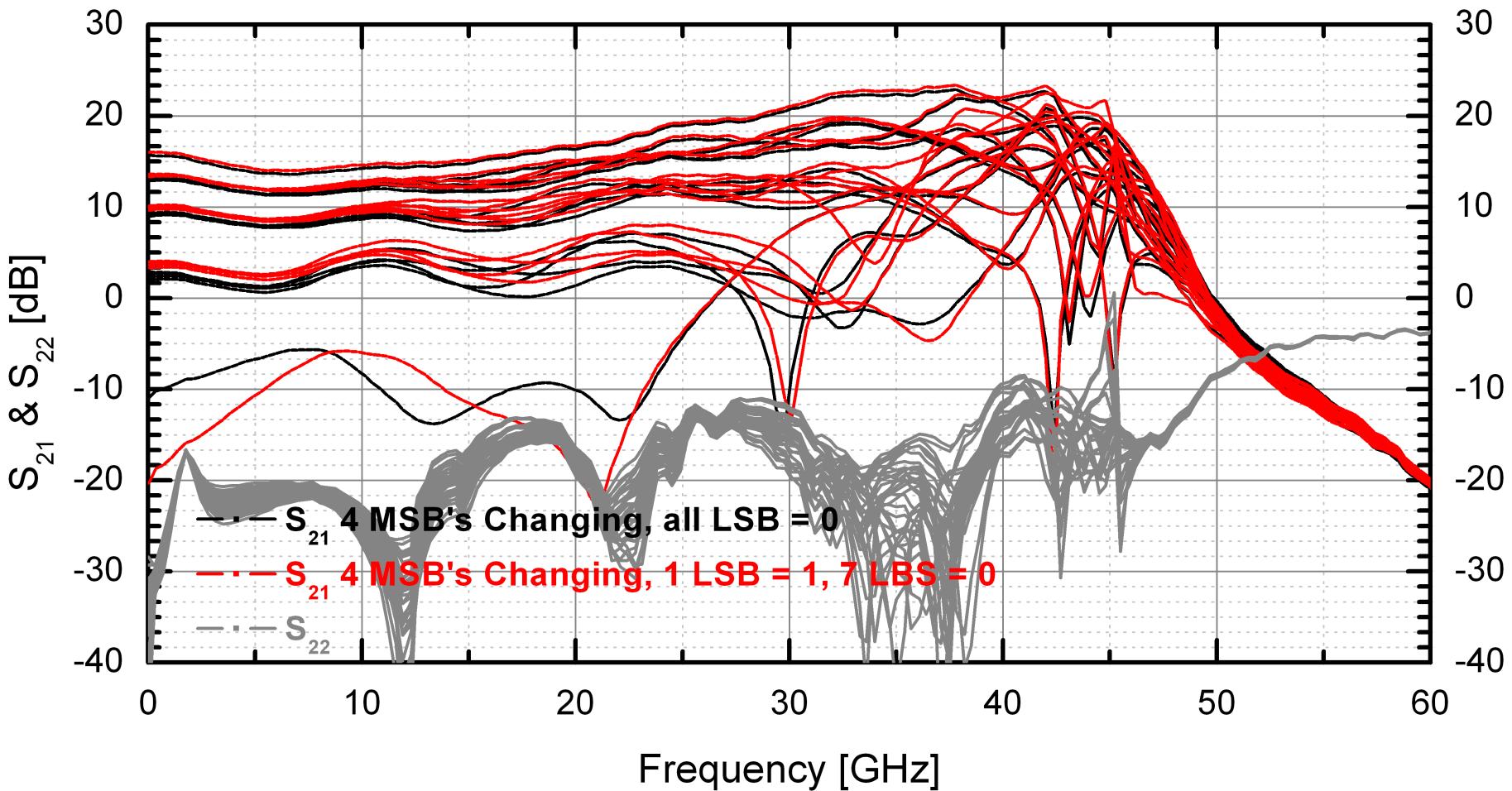


Die Photo (V1)

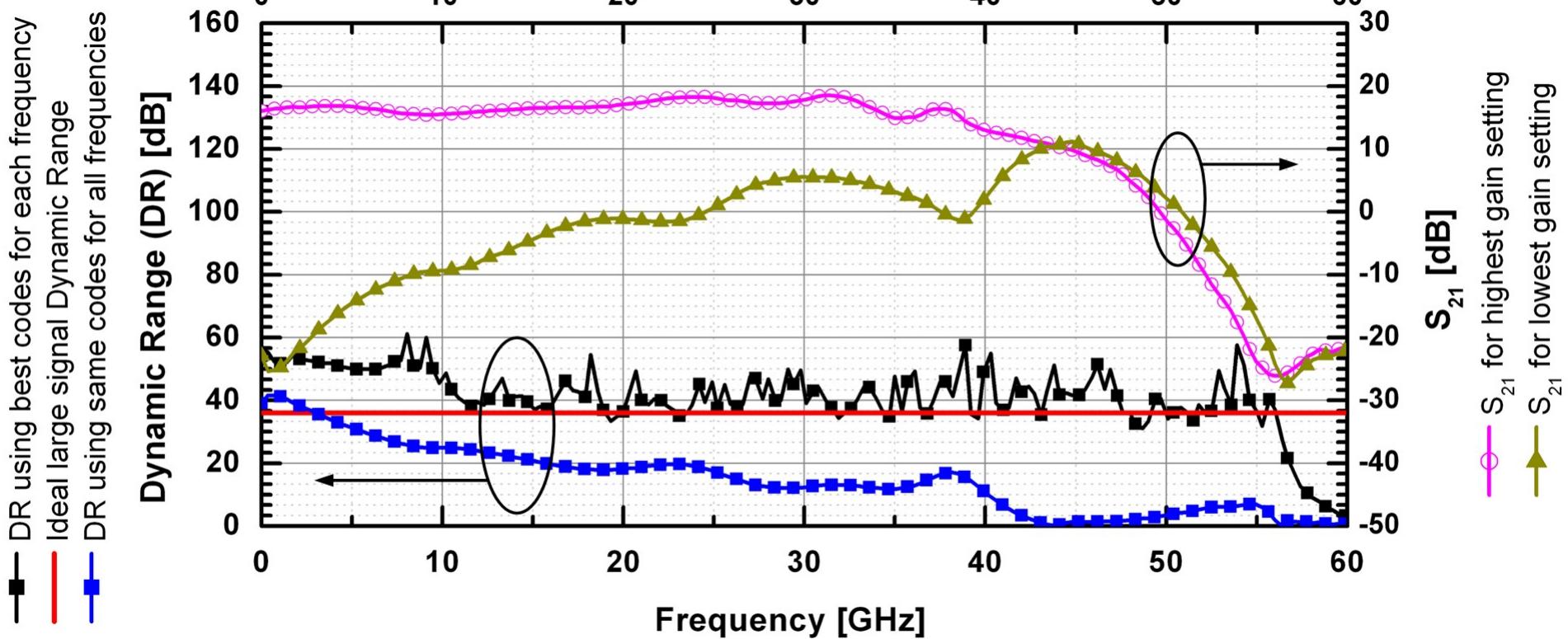


ST's 130-nm SiGe BiCMOS Production Process
 $f_T/f_{MAX} = 230/280$ GHz

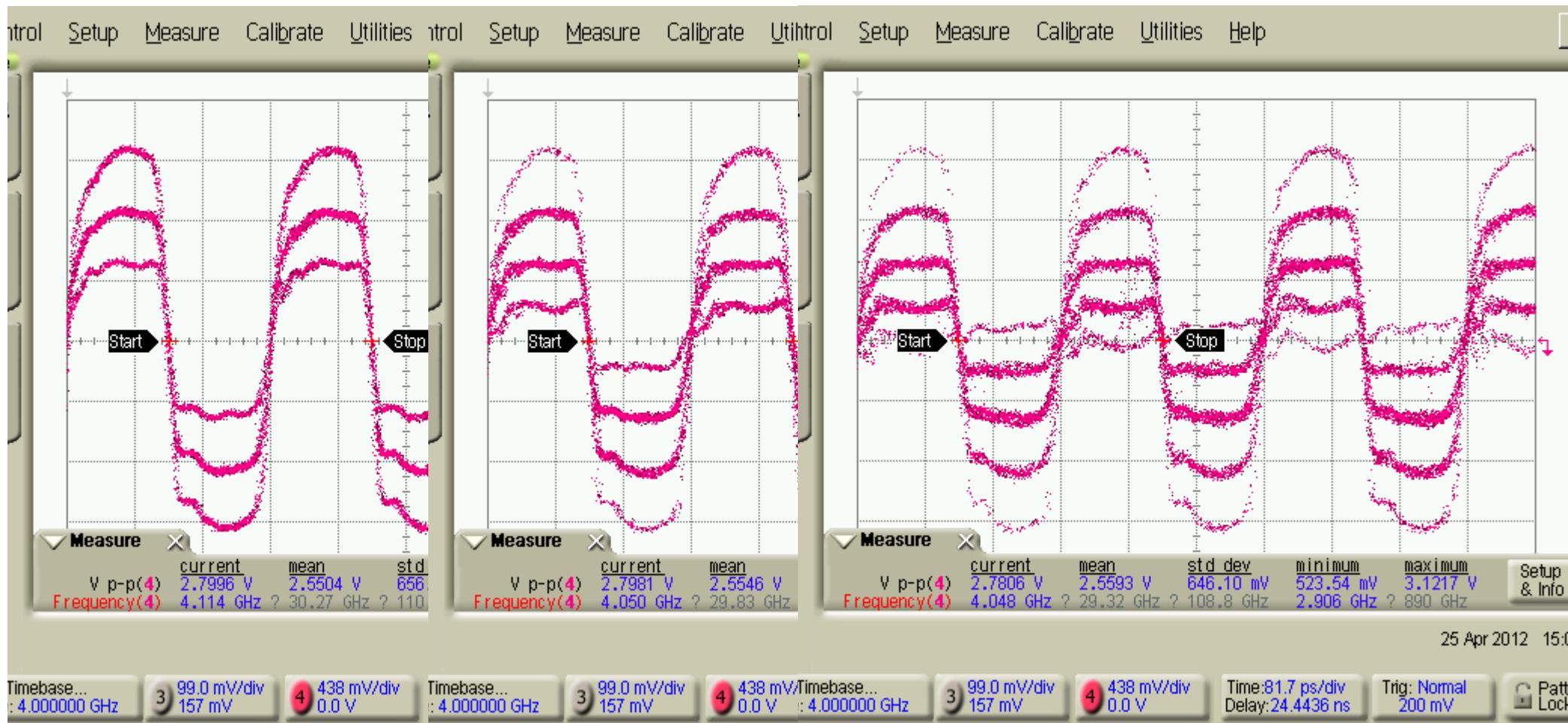
Measured S-parameters (V1)



Dynamic Range from S-parameters (V1)



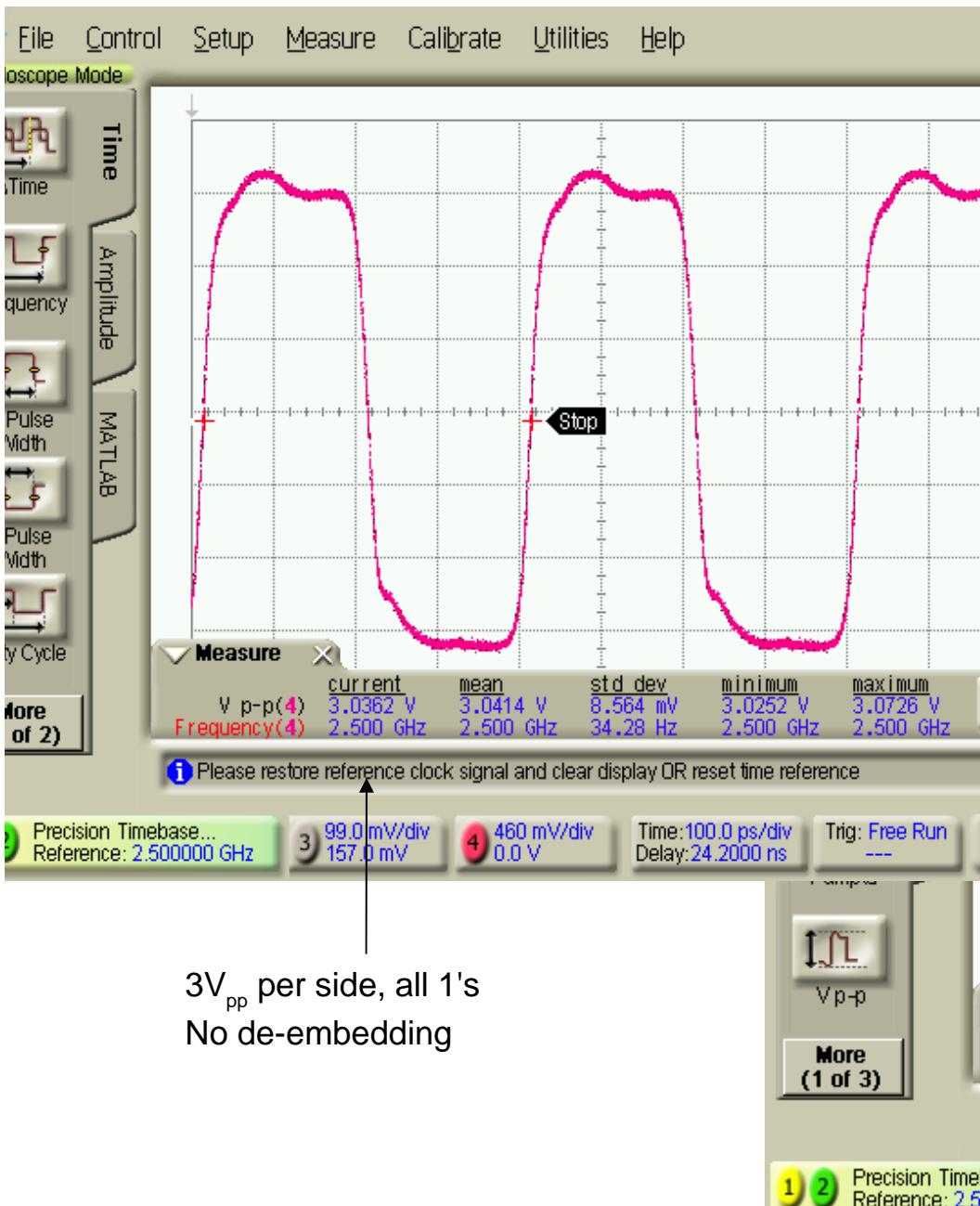
4 GHz large signal: one MSB at a time (V2)



2.8Vpp per side, no de-embedding

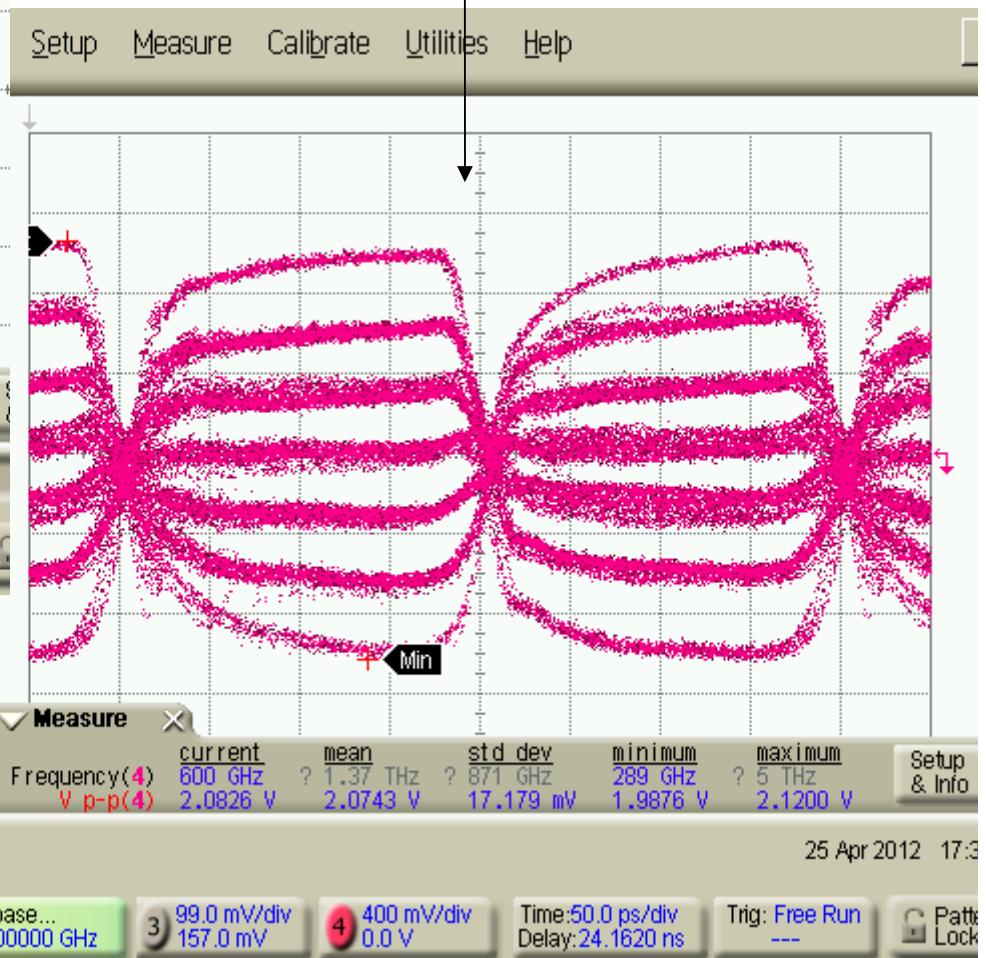


2.5 GHz large signal swing (V2)

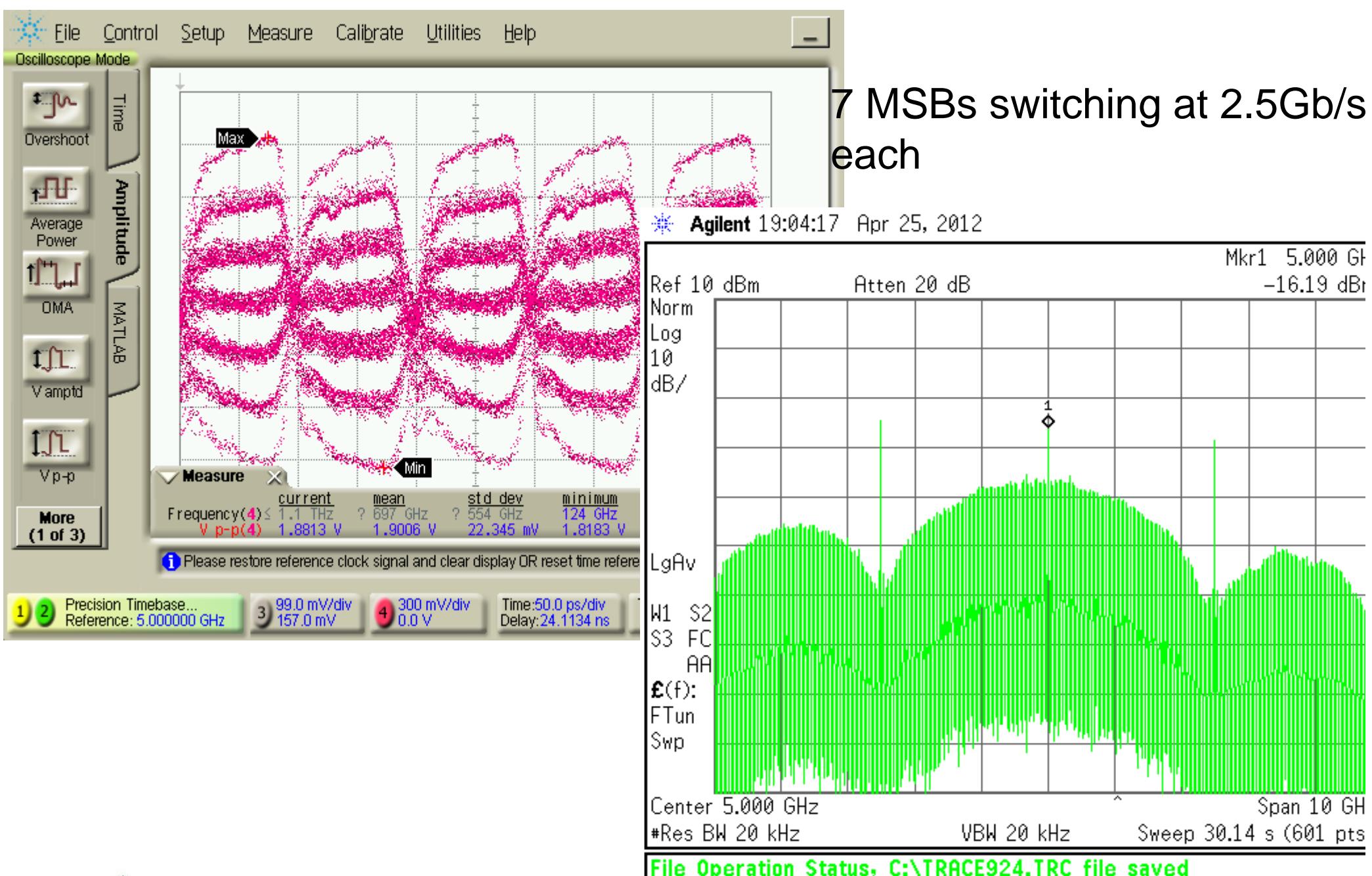


3V_{pp} per side, all 1's
No de-embedding

7 MSBs switching at 2.5Gb/s each



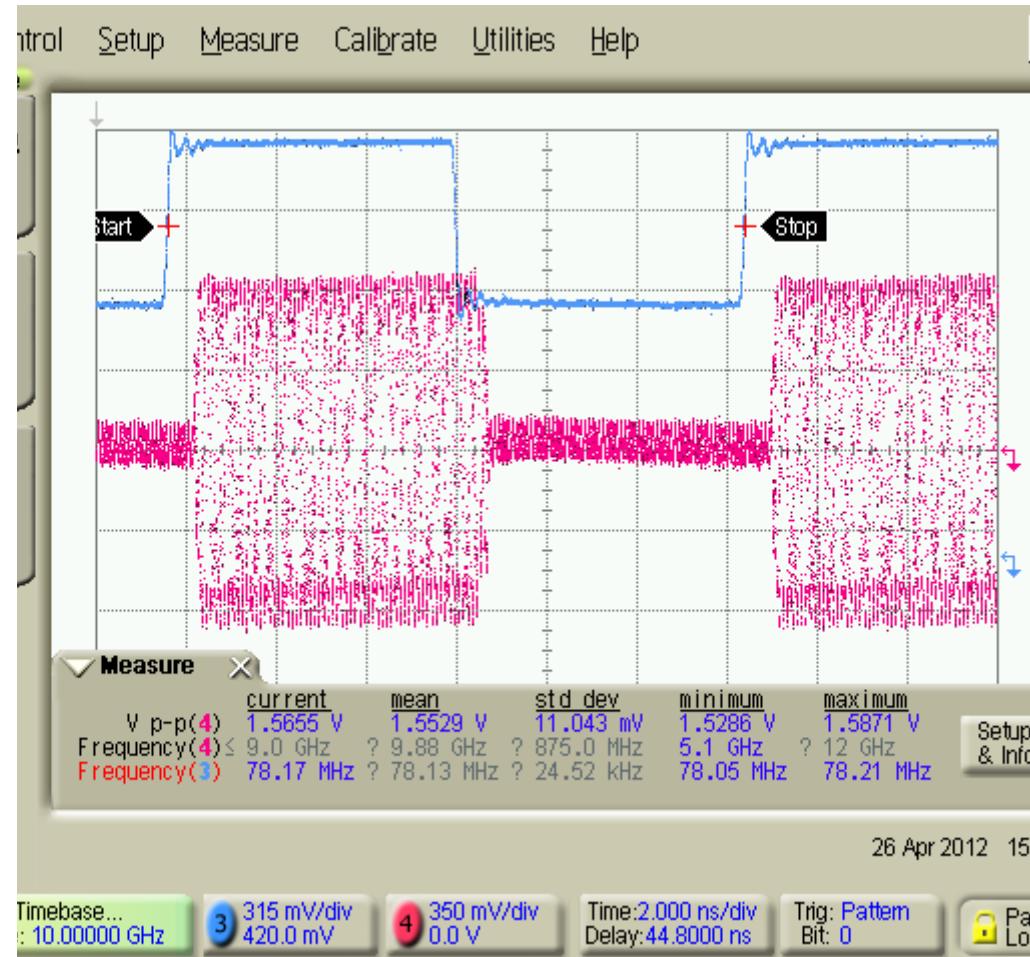
5 GHz large signal swing, spectra (V2)



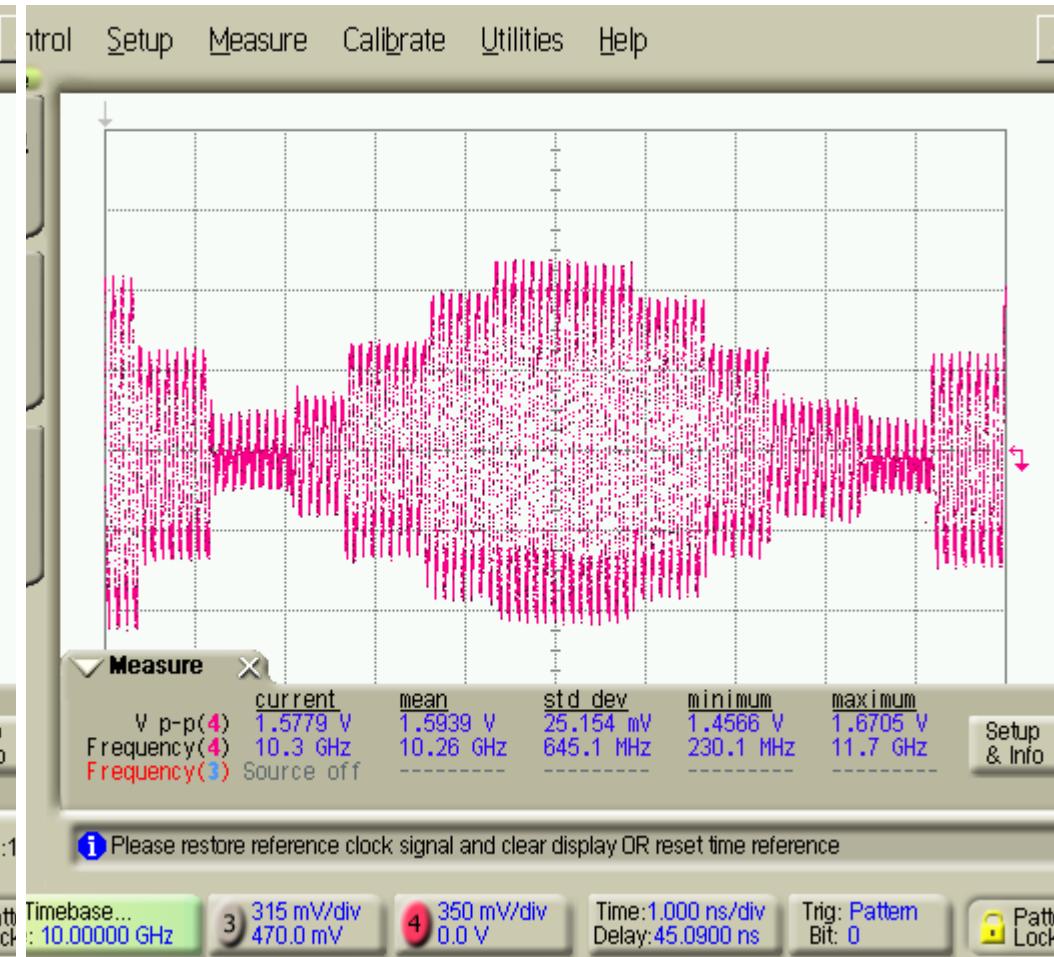
10 GHz large signal swing, spectra (V2)



10 GHz large signal patterns (V2)



On-Off

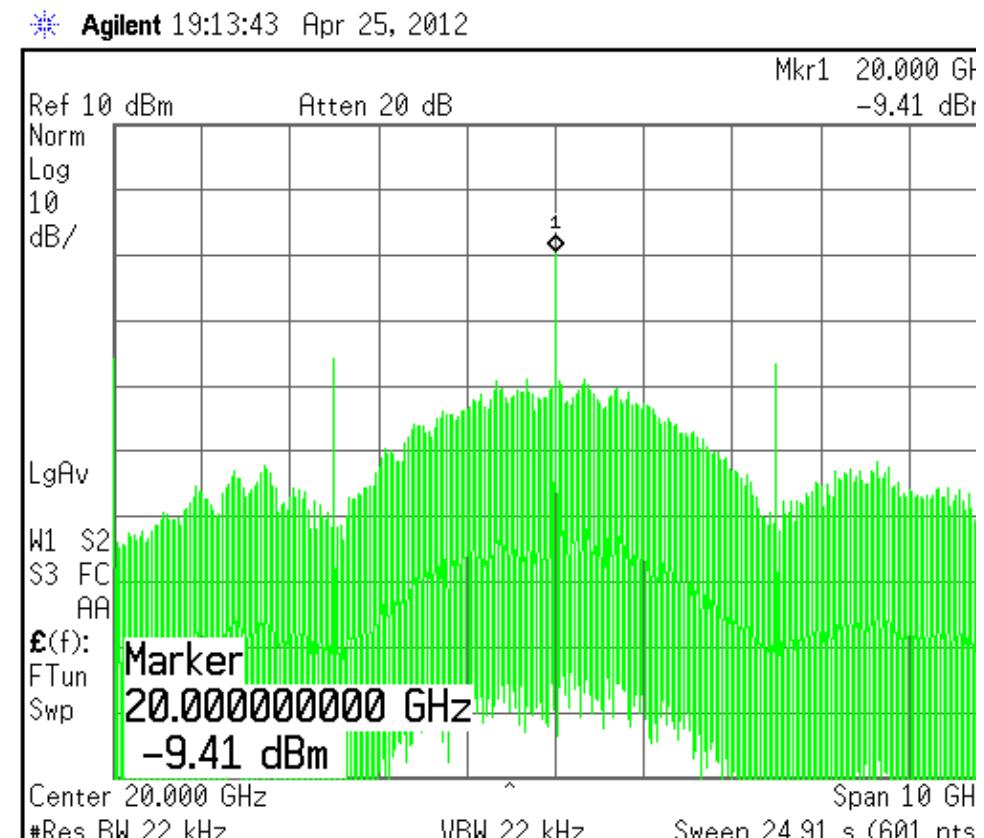
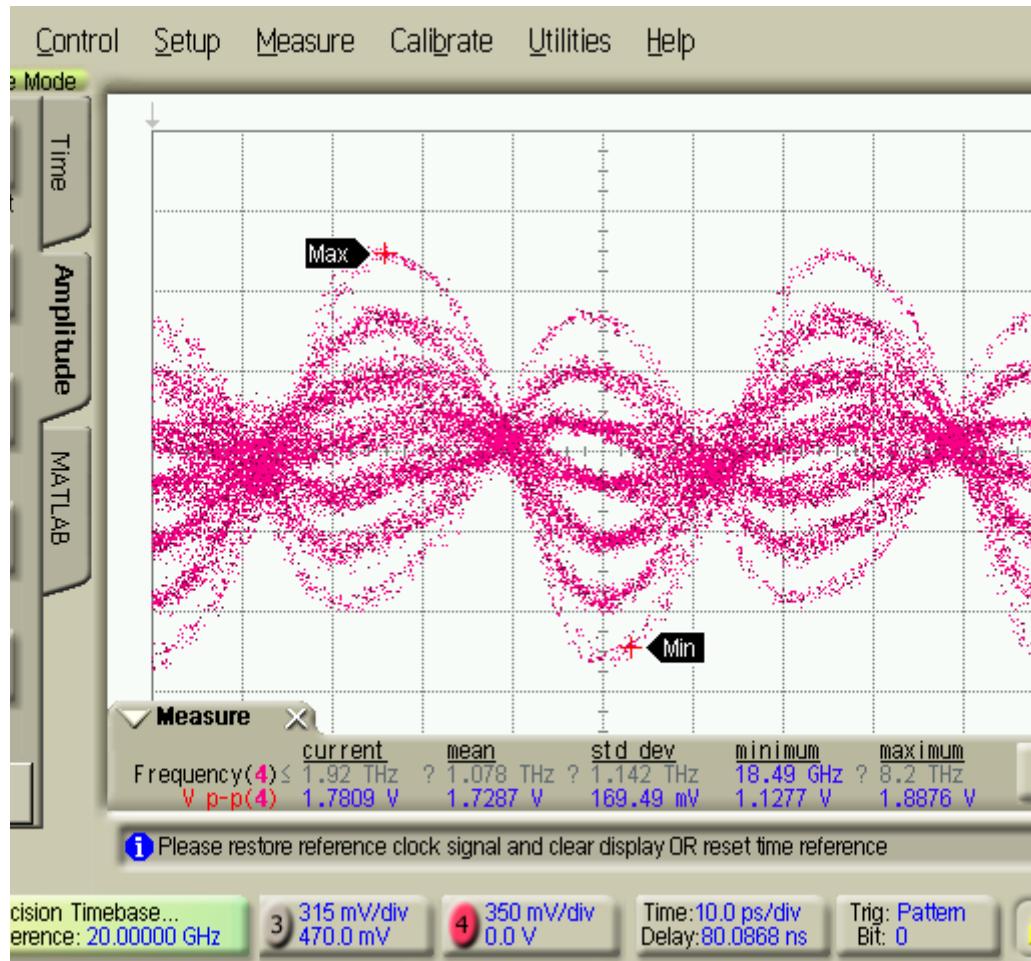


Sine



20 GHz large signal swing, spectra (V2)

7 MSBs + 5 LSBs switching at 2.5 Gb/s each



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